

ZSSC3286

IO-Link Ready Dual Channel Resistive Sensor Signal Conditioner IC

The ZSSC3286 is a dual path sensor signal conditioning IC (SSC) for highly accurate amplification, digitization, and sensor-specific correction of sensor signals.

The ZSSC3286 supports IO-Link connectivity with an integrated IO-Link stack running the IO-Link Smart Sensor Profile for digital measuring and switching sensors.

The device is suitable for bridge and half-bridge sensors, as well as external voltage source elements.

Digital compensation of the sensor offset, sensitivity, temperature drift, and nonlinearity is accomplished via a 32-bit ARM based math core running a correction algorithm with calibration coefficients stored in a non-volatile, reprogrammable memory.

The programmable, integrated sensor front-end allows optimally applying various sensors for a broad range of applications.

The ZSSC3286 supports system calibration and firmware update via the IO-Link or I2C interface.

Applications

- Industrial sensors with IO-Link interface
- Smart and digital sensors for energy-efficient solutions
- Single/Dual/Differential sensing
- Factory automation
- Process automation
- Calibrated, continuously operating sensors for:
 - Pressure
 - Flow
 - Load
 - Level
 - Temperature

Features

- IO-Link stack embedded
- Smart Sensor Profile in COM3 mode
- Firmware update via IO-Link
- Calibration and configuration via IO-Link
- Clock recovery system, no external crystal needed
- IODD generator included
- Accommodates nearly all resistive bridge sensors in various configurations:
 - Resistive bridge or half-bridge
 - Resistive divider string
 - Voltage source
- On-chip temperature sensor
- External temperature sensing supported
- Programmable 16-bit digital-to-analog-converter and output (supporting “True-0Volt”-output):
 - Absolute voltage output (supporting 0V to 1V, 0V to 5V, or 0V to 10V applications)
 - 4mA to 20mA current-loop output supported
- Wide operational temperature and supply range
- On-chip voltage regulators for sensor supply, and IC operation
- Programmable sensor-signal-conditioning math core
- Reprogrammable, non-volatile memory (NVM)
- On-chip diagnostics:
 - Sensor connection
 - AFE self-test
 - Memory integrity

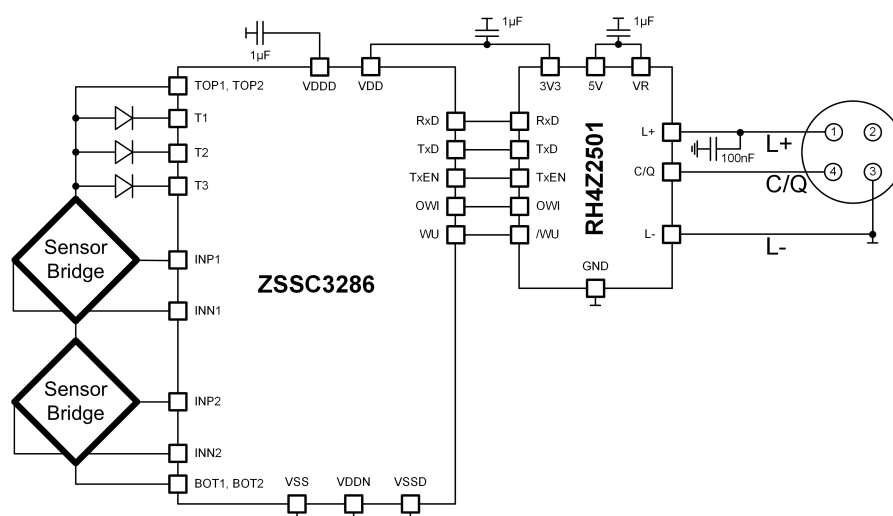


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1 Overview

1.1 Block Diagram

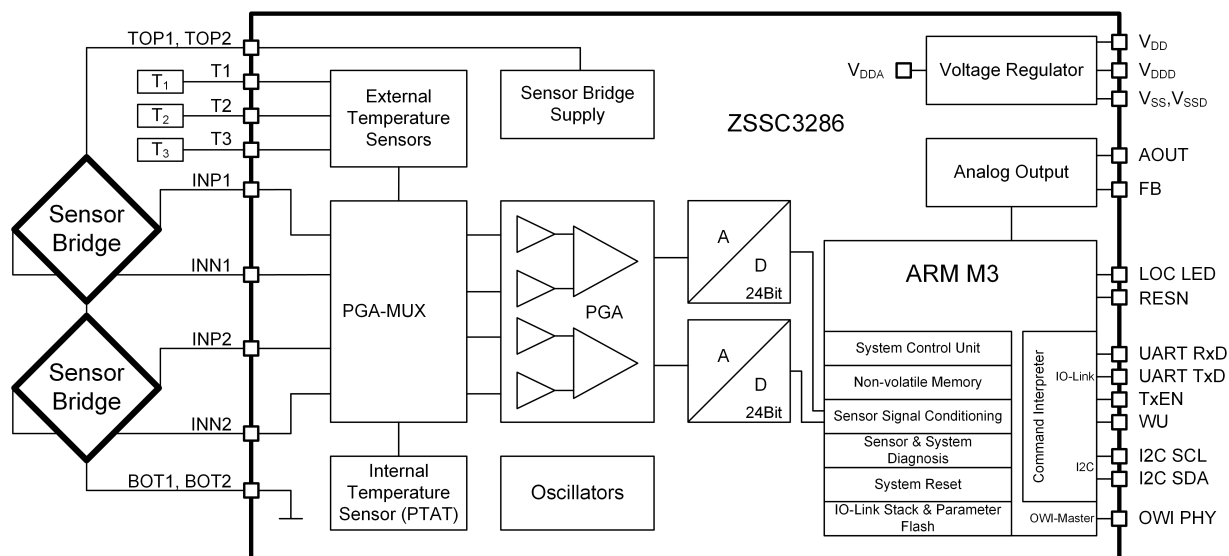


Figure 2: Block Diagram

1.2 Ordering Information

Orderable Part Number	Description and Package	MSL Rating	Carrier Type	Temperature Range
ZSSC3286CI1B	DICE on 304μm wafer no inking		Wafer Box	-40°C to 125°C
ZSSC3286CI5B	DICE on 304μm wafer with inking		Wafer Box	-40°C to 125°C
ZSSC3286CI1C	DICE on 304μm wafer no inking		Wafer Sawed on Frame	-40°C to 125°C
ZSSC3286CI1D-ES	DICE on 304μm wafer no inking		Waffle Pack (Engineering Samples)	-40°C to 125°C
ZSSC3286CI3R	5 x 5 mm2 NDG40S1 (40-VFQFPN)	MSL1	13 inch Reel	-40°C to 125°C
ZSSC3286CI8R	WLCSP	MSL1	13 inch Reel	-40°C to 125°C
ZSSC3286KIT	Modular ZSSC3286 SSC Evaluation Kit including three interconnecting boards, five ZSSC3286 QFN40 samples, one RH4Z2501 PMOD, one two channel IO-Link master and cable. Software is available for download on www.renesas.com/ZSSC3286 .			

1.3 Pin Configuration

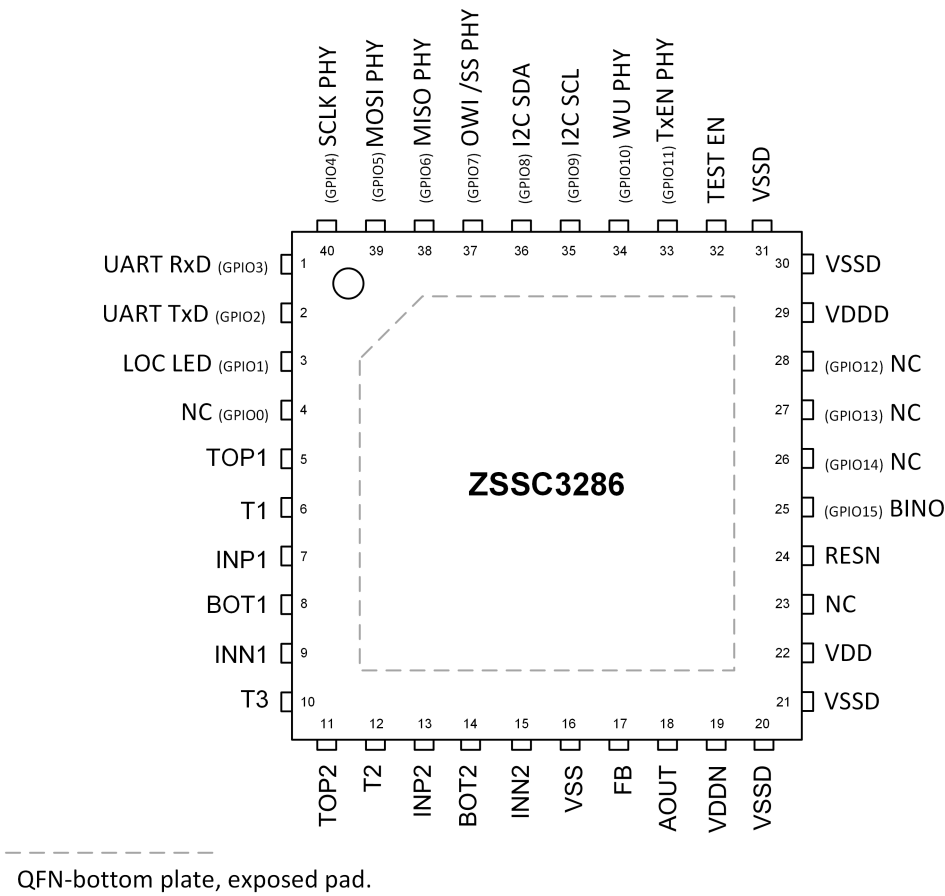


Figure 3: Pin Layout QFN40

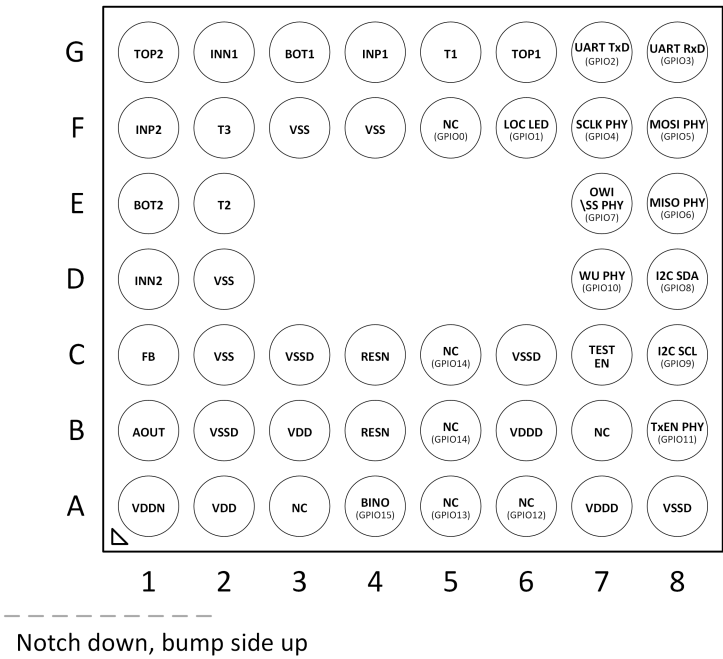


Figure 4: Pin Layout WLCSP

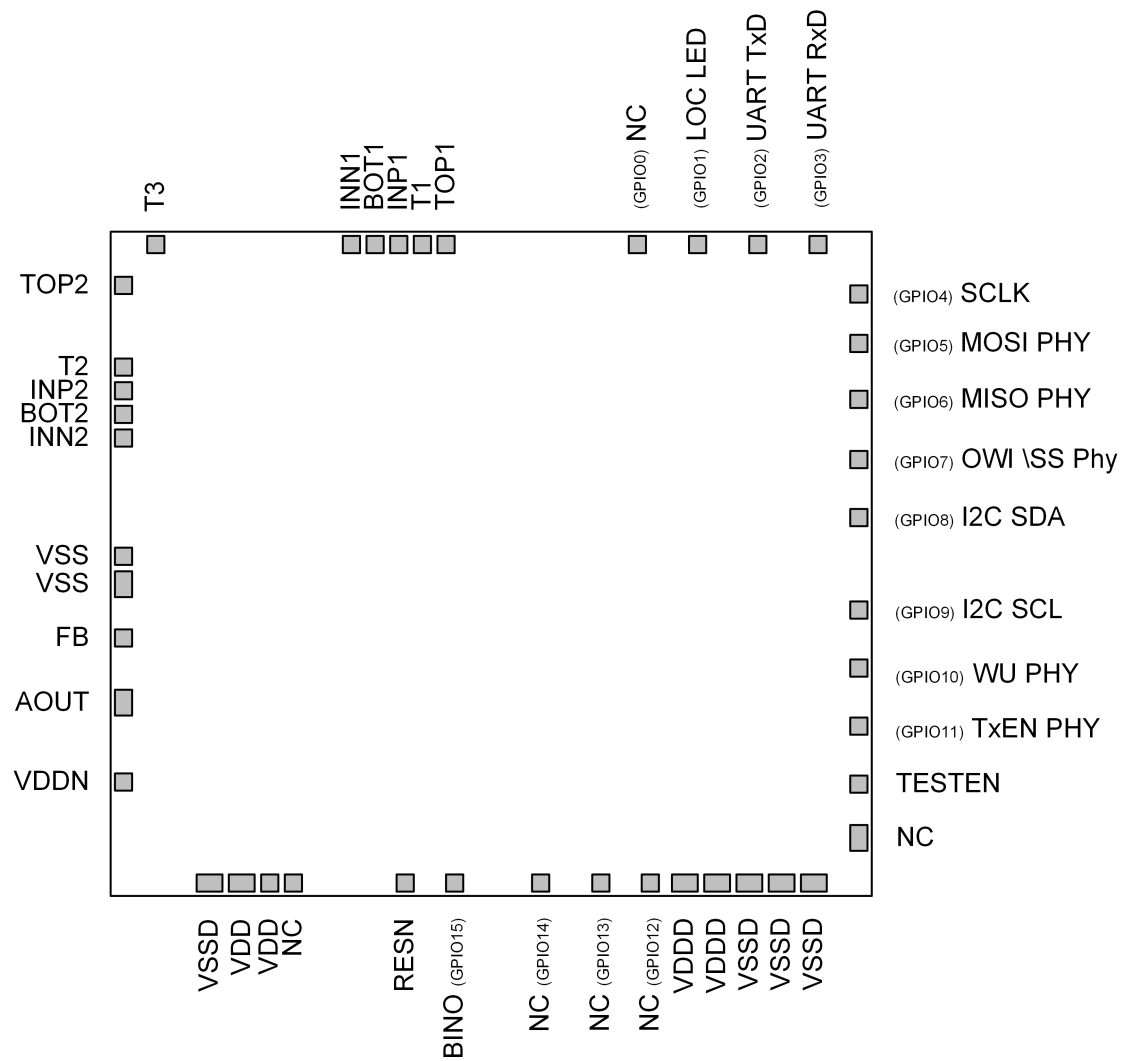


Figure 5: Pad Layout Bare Die

1.4 Pin Descriptions

QFN40 Pin Number	WLCSP Pin Number	Name	Type	Description
2	G7	UART TxD	Digital Output	GPIO2: UART transmit function for IO-Link PHY communication
1	G8	UART RxD	Digital Input	GPIO3: UART receive function for IO-Link PHY communication
3	F6	LOC LED	Digital Output	GPIO1: Timer functionality for Locator LED
4	F5	NC	Digital Input/Output	GPIO0: Not connected. Leave pin floating.
5	G6	TOP1	Analog Input/Output	Positive sensor (bridge 1) supply or sensor-signal input
6	G5	T1	Analog Input/Output	External temperature sensor
7	G4	INP1	Analog Input/Output	Positive sensor (bridge 1) signal
8	G3	BOT1	Analog Input/Output	Sensor (bridge 1) ground or sensor-signal input
9	G2	INN1	Analog Input/Output	Negative sensor (bridge 1) signal
10	F2	T3	Analog Input/Output	External temperature sensor 3
11	G1	TOP2	Analog Input/Output	Positive sensor (bridge 2) supply or sensor-signal input
12	E2	T2	Analog Input/Output	External temperature sensor 2
13	F1	INP2	Analog Input/Output	Positive sensor (bridge 2) signal
14	E1	BOT2	Analog Input/Output	Sensor (bridge 2) ground or sensor-signal input
15	D1	INN2	Analog Input/Output	Negative sensor (bridge 2) signal
16	C2, D2, F3, F4	VSS	Ground	Power supply ground
17	C1	FB	Analog Output	Feedback pin for AOUT. No connection if not used.
18	B1	AOUT	Analog Output	Analog smart-sensor output signal
19	A1	VDDN	Analog Output	Negative voltage output, charge pump buffer capacitor
20	A8, B2, C3, C6	VSSD	Ground	Digital power supply ground
21	A8, B2, C3, C6	VSSD	Ground	Digital power supply ground
22	A2, B3	VDD	Supply	Power supply
23	A3, B7	NC	Analog Output	Not connected. Leave pin floating.
24	B4	RESN	Digital Input	Digital IC reset (low active); internal pull-up
25	A4	BINO	Digital Output	GPIO15: Binary Output (BINO) for Sensor Switching Signal
26	B5, C5	NC	Digital Input/Output	GPIO14: Not connected. Leave pin floating.
27	A5	NC	Digital Input/Output	GPIO13: Not connected. Leave pin floating.
28	A6	NC	Digital Input/Output	GPIO12: Not connected. Leave pin floating.
29	A7, B6	VDDD	Analog I/O	Buffer cap connection for internal VDDD
30	A8, B2, C3, C6	VSSD	Ground	Digital power supply ground
31	A8, B2, C3, C6	VSSD	Ground	Digital power supply ground
32	C7	TEST EN	–	Renesas internal use only. Connect to VSSD
33	B8	TxE PHY	Digital Output	GPIO11: UART transmit enable function for IO-Link PHY communication
34	D7	WU PHY	Digital Output	GPIO10: Wake-Up for IO-Link PHY communication
35	C8	I2C SCL	Digital Input	GPIO9: I2C SCL
36	D8	I2C SDA	Digital Input/Output	GPIO8: I2C SDA
37	E7	OWI /SS PHY	Digital Input/Output	GPIO7: OWI master interface or Slave Select for IO-Link PHY communication
38	E8	MISO PHY	Digital Input	GPIO6: SPI master function - MISO for IO-Link PHY communication
39	F8	MOSI PHY	Digital Output	GPIO5: SPI master function - MOSI for IO-Link PHY communication
40	F7	SCLK PHY	Digital Output	GPIO4: SPI master function - Clock for IO-Link PHY communication
n.a.	B7	NC	Analog Output	Not connected. Leave pin floating.
	n.a.	exposed pad	-	QFN-bottom plate, Die-bottom/substrate. Recommendation is to connect to VSS, PAD to be used for heat dissipation and additional EMC robustness.

2 Specifications

2.1 Absolute Maximum Ratings

Symbol	Parameter	Conditions	Minimum	Maximum	Units
T_J	Junction temperature			135	°C
T_S	Storage temperature		-45	150	°C
	ESD: Human Body Model tested per JS-001-2017	Pins: INPx, INNx, TOPx, BOTx, Tx, VDDD		2000	V
		Pins: GPIOx, VDD, VDDN, VSS, VSSD, AOUT, FB, RESN, NC		4000	V
	ESD: Charged Device Model tested per JS-002-2014 (OFN package)	All Pins		750	V
	ESD: Charged Device Model tested per JS-002-2014 (WLCSP package)	All Pins		500	V
	Latch-up	Tested per JESD78E; Class 2, Level A	-100	+100	mA
V_{DD_max}	Maximum allowed for voltage supply	Referenced to VSS	-0.3	6.5	V
V_{IF_max}	Voltage at digital I/O	Referenced to VSSD	-0.3	5.5	V

WARNING: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

2.2 Thermal Information

Symbol	Parameter	Conditions	Typical	Units
θ_{JA}	Theta JA	40Ld 5×5 QFN Package, 0 m/s air flow	25.8	K/W
		40Ld 5×5 QFN Package, 1 m/s air flow	22.4	K/W
		40Ld 5×5 QFN Package, 2 m/s air flow	20.8	K/W
θ_{JB}	Theta JB	40Ld 5×5 QFN Package	1.3	K/W
θ_{JC}	Theta JC	40Ld 5×5 QFN Package	24.4	K/W

2.3 Recommended Operating Conditions

Symbol	Parameter	Minimum	Typical	Maximum	Units
V_{DD}	Power supply voltage	1.8	–	5.5	V
	Flash write/erase	2.7			
	With optional "True-0V" at analog output	2.7			
T_J	Junction temperature	-40		125	°C
C_{VDD}	External capacitance between VDD and VSS	10 ±20%		22 ±20%	μF
C_{V3D}	External capacitance between VDDD and VSS	1 ±20%		1 ±20%	μF
C_{VDDN}	External capacitance between VDDN and VSS, with optional "True-0V" at analog output	1 ±20%		1 ±20%	μF
C_{TOP_EMC}	Recommended, external capacitance between TOP and VSS for electro-magnetic immunity (EMI)	0	6.8	8	nF
C_{AOUT_EMC}	Recommended, external capacitance between AOUT versus VDD and VSS for EMI suppression ¹	0	22	33	7nF
I_{Sensor}	Load current through external sensor element ²	0.005	0.5	2	mA
$V_{DioDrop}$	External temperature diode and RTD input range, drop over external element referenced to T1, T2, T3 pin	0.2		1.2	V
V_{Sens_in}	Absolute sensor signal input level, INN, INP pins	0.2		1.2	V
$I_{max_AOUT_V}$	Maximum current load at AOUT pin for voltage outputs	0	5		mA
S_{RVDD_POR}	Recommended VDD rise slew rate for Power-On-Reset (POR)	1.5			V/ms
I_{max_GPIO}	Maximum overall GPIO driver strength			120	mA

¹ For applications with OWI interface or analog voltage output.

² With ratiometric sensor supply configuration. For example, a ratiometric bridge or bridge as temperature sensor with internal or external temperature sensitive resistor

2.4 Electrical Specifications

All parameter values are valid only under operating conditions specified in subsection 2.3. All voltages are referenced to VSS.

Table 1: IC Supply

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
I_{IC}	Current consumption, active mode (depending on settings)	Excluding connected sensor elements		8	15	mA
VDDA	Internally generated analog supply		1.6	1.65	1.85	V

Table 2: Sensor Supply

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
TOP	Sensor bias voltage in ratiometric Supply Mode	Ratiometric sensor voltage supply		VDDA		V
I_{bias_TOP}	Sensor bias current used in Source Mode	Programmable in 10 steps: 0μA, 5μA, 10μA, 20μA, 40μA, 80μA, 100μA, 160μA, 200μA, 500μA	0		500	μA
I_{biasN_BOT}	Sensor current used in Sink Mode	Programmable in 2 steps: 20μA, 100μA	20		100	μA
I_{ERR}	Relative bias current (I_{bias_TOP} and I_{biasN_BOT}) error	Overall	-10		10	%
		Over temperature range	-1		1	
R_{TH}, R_{TL}	TOP/BOT bias resistor	Programmable in 12 steps: open, 1.33kΩ, 2kΩ, 4kΩ, 8kΩ, 10kΩ, 14kΩ, 18kΩ, 20kΩ, 24kΩ, 28kΩ, 40kΩ	1.3		40	kΩ
dR_{TH}, dR_{TL}	TOP/BOT bias resistor process variation		-30		30	%
TK of R_{TH}, R_{TL}	TOP/BOT bias resistor temperature variation	T = -55°C to 125°C			1.3	%

Table 3: Analog-to-Digital Converter (ADC)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
r_{ADC}	Resolution		10	16	24	Bit
V_{ADCmid} (AGND)	Differential ADC input Common Mode	With internal regulator supplying TOP pin, typical: $V_{TOP/2} = 875mV$ (=PGA output Common Mode level)		0.5		V_{TOP}
$\Delta_{ADC,c}$	Differential input offset shift	Sensor signal offset versus maximum sensor signal. Programmable in 8 steps.	0		7/8	V_{shift}/V_{fs}
ENOB ¹	Effective number of bits, $3\sigma_{Noise}$ based	Gain = 1.32, $r_{ADC} = 24$ bit, no oversampling		17		Bit
		Gain = 28, $r_{ADC} = 16$ bit, no oversampling		12		Bit
		Gain = 100, $r_{ADC} = 15$ bit, no oversampling		10		Bit
		Gain = 495, $r_{ADC} = 24$ bit, no oversampling		11		Bit

¹ $ENOB = \log_2 \left(\frac{2^{r_{ADC}}}{3\sigma_{Noise}} \right)$ with for example, r_{ADC} [Bit] = 24.

Table 4: Digital-to-Analog Converter (DAC) and Analog Output

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
VDD	VDD operating range	AOUT modes using 1V buffer	1.8		5.5	V
		AOUT modes using 5V buffer	2.7		5.5	
t _{AOUTsettle}	Time from digital value applied at DAC and voltage at VOUT	10% to 90% input step: V _{AOUT} at 90% of final value			100	μs
V _{OUT_START}	Voltage at AOUT during startup			0		V
V _{AOUT}	Output voltage at pin AOUT	Ratiometric Voltage Mode	0		VDD	V
		1V absolute Voltage Mode	0		1	
I _{OUTMAX}	Short current limit at pin AOUT	AOUT modes using 5V Buffer • short to VDD or VSS • programmable in 4 steps	3	5	9	mA
			8	12	20	
			13	19	25	
			18	25	32	
C _{load}	Load capacitance at AOUT	For example: cap for EMC: 33nF, ECU load: 10nF)	10 ¹		50	nF
r _{DAC}	Resolution			16		Bit

¹ In case of enabled Power-Ground Loss detection minimum 10nF on AOUT is required.

Table 5: Programmable-Gain Amplifier (PGA)

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
G _{amp}	Gain	120 steps	1.32		495	V/V
G _{err}	Gain error	Referenced to nominal gain Gain = 1.32...5	-2.5	0	2.5	%
		Gain = 6...125	-5		5	
		Gain = 126...495	-10		10	
G _{errTemp}	Gain error over-temperature	Temperature compensated sensors do not require calibration over temperature.	-0.2		0.2	%
V _{CMin}	Supported input Common Mode		0.2	0.5	0.7	V _{TOP}
V _{ioffsc}	Differential input offset shift	Programmable in 30 steps: Gain1 ≤ 223	-28.1	0	28.1	mV
		Gain1 = 275	-22.5	0	22.5	

Table 6: Sensor Signal Conditioning (SSC) Performance

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
OUR	Output Update Rate	3 measurements: signal+, signal-, diagnosis - r_{ADC} = 16bit (main) - r_{ADC} = 15bit (temp) - diagnosis ≤ 350μs - SSC-corrected digital output		1.15		kHz
		2 measurements: signal+, diagnosis - r_{ADC} = 15bit (main) - r_{ADC} = 15bit (temp) - diagnosis ≤ 350μs - SSC-corrected digital output		1.82		kHz
t _{AOUT_SR}	Step response	3 measurements: signal+, signal-, diagnosis - r_{ADC} = 16bit (main) - r_{ADC} = 15bit (temp) - diagnosis ≤ 350μs - at AOUT (90% final)		1.51		ms
		3 measurements: signal+, signal-, diagnosis - r_{ADC} = 15bit (main) - r_{ADC} = 15bit (temp) - diagnosis ≤ 350μs - at AOUT (90% final)		0.86		ms

Table 7: Analog Inputs

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{INP1} , V_{INN1} , V_{INP2} , V_{INN2}	Absolute sensor input	Voltages at INPx and INNx pin; resulting minimum/maximum differential voltages: $-800\text{mV} < V_{INDIFF} < 800\text{mV}$	0.2		1.2	V
V_{TEXT}	External temperature diode or RTD input range	at T1, T2, T3 pin (see Sensor Supply section of this table and ExtTempBrdgIBias for available configuration options)	0.3		1.2	V
R_{SENSOR}	External sensor (bridge) resistance	TOP = 1.65V	0.825		60	k Ω
		2-wire Current Loop Mode	3.3		60	k Ω
$ V_{DIFFIN} $	Differential input signal range	Referenced to sensor supply ($V_{DDA_{INT}}$)			800	mV

Table 8: Diagnostics

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
R_{OPEN}	Broken sensor: values $>R_{OPEN}$ set a failure flag	- INP1 vs. INN1 - INP2 vs. INN2	100	120	150	k Ω
R_{SHORT}	Shorted sensor: values $<R_{SHORT}$ set a failure flag	- INP1 vs. INN1 - INP2 vs. INN2 - INP1 vs. INP2 - INP2 vs. INN1	120		220	Ω
I_{LEAK}	Sensor leakage check	Sensor leakage current from INP/INN to VSS: values $>I_{LEAK}$ set a failure flag	0.8	1	2	μA
V_{COMMON}	Sensor Common Mode check (measurement $V_{INP} - V_{AGND}$, $V_{INN} - V_{AGND}$)	Detects sensor connection failure: - open TOP or BOT - short INP or INN to TOP or BOT	0.4		0.6	V_{TOP}
V_{RDAC}	RDAC differential output voltage	VDDAx = 1.65V: • S = 00		2		mV
		• S = 01		10		
		• S = 10		100		
		• S = 11		200		
R_{T_OPEN}	T1, T2, T3 connection check: open	Broken Tx sensor: values $>R_{T_OPEN}$ set a failure flag: 3 level can be configured - INN is drawn to VSS!	1.6	2	3	M Ω
			0.4	0.5	0.6	
			0.07	0.1	0.13	
t_{T_OPEN}	Diagnosis time; depends on C_{IS} and R_{T_OPEN}	Time spent between failure occurrence and output signalization.	0.1		10	ms
R_{T_SHORT}	T1, T2, T3 connection check: short to TOP, BOT, INP, INN	Shorted Tx sensor: values $<R_{T_SHORT}$ set a failure flag: configuration for Pt1000	320	500	650	Ω
VDD	Programmed (expected) VDD level	Programmable in 6 steps: 2.2V, 2.7V, 3V, 4V, 5V, 5.25V	2.2		5.25	V
VDDD _{BOD}	VDDD brown out detection	VDDD < VDDD _{BOD} system is in reset state	85		92	%VDDD
V_{LOSS}	Power/ground loss with respect to AOUT	$V_{AOUT} - VDD > V_{LOSS}$ $V_{AOUT} - VSS < V_{LOSS}$		0.2		V

Table 9: Power-Up

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
t_{STA1}	Startup time	VDD ramp up to interface communication			10	ms
t_{STA2}		VDD ramp up to analog operation; depends on the configuration used			10	ms
t_{WUP1}	Wake-up time	Sleep to Active State interface communication		2	10	μs

Table 10: Oscillator

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
f_{CLK_HF}	Internal HF-oscillator frequency	At T=27°C	15.8	16	16.2	MHz
		Across temperature range	15		17	
f_{CLK_LF}	Internal LF-oscillator frequency		25	32	41	kHz

Table 11: Internal Temperature Sensor

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
r_{Temp}	Internal temperature sensor resolution	Differential output voltage		220		$\mu V/K$

Table 12: Digital IO Pins

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
V_{IL}	Input low Voltage	voltage level where the input is recognized as low level			30	% VDD
V_{IH}	Input high Voltage	voltage level where the input is recognized as high level	70			% VDD
V_{Ihys}	Input hysteresis		10		35	% VDD
V_{OL}	Output low Voltage				8	% VDD
V_{OH}	Output high Voltage		92			% VDD
I_{OL}	Output drive low current	$V_{PAD} = V_{OL}$: VDD = 1.7V	1		2.4	mA
		VDD = 2.6V	2.7		6.6	
		VDD = 5V	9		20	
I_{OH}	Output drive high current	$V_{PAD} = V_{OH}$: VDD = 1.7V	1.2		2.3	mA
		VDD = 2.6V	3.2		6.4	
		VDD = 5V	10.9		20.2	
I_{pullup}	Weak pull-up current at pin RESN	$V_{PAD} = 0V$: VDD = 1.7V	5		13	μA
		VDD = 2.6V	17		50	
		VDD = 5V	84		250	
$I_{pulldown}$	Weak pull-down current at pin WAKEUP	$V_{PAD} = VDD$: VDD = 1.7V	5		11	μA
		VDD = 2.6V	17		35	
		VDD = 5V	80		160	

Table 13: Serial Interfaces

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$f_{C,UART}$	UART clock frequency (for IO-Link protocol)			230.4		kBit/s
$f_{C,I2C}$	I2C clock frequency				1	MHz
CD_{OWI}	OWI data rate			4		kBit/s

Table 14: Flash Memory

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
t_{PROG}	NVM program time	Programming time for complete configuration and calibration page		360		ms
n_{NVM}	NVM endurance	Number of reprogramming cycles	20000			Numeric
$t_{RET,NVM}$	Data retention		10			Years

3 Basic System Configuration

3.1 System Modes/System Start

The ZSSC3286 can operate in three different main operating modes:

Bootloader	It is started after successfully passing the initialization phase of the ZSSC3286 hardware. ZSSC3286 checks that firmware and CCP CRC are correct to allow starting the firmware in SIO Mode. The bootloader allows to update the CCP content.
Standard I/O Mode (SIO)	It is the startup operation mode after passing the bootloader. The SIO mode supports the Command Mode and Cyclic Mode operational states. ZSSC3286 waits for actions on I2C interface or the wakeup request (WURQ) to start transition to IO-Link COM Mode.
I/O-Link COM Mode	It is the default operation mode if IO-Link communication is established during operation in the field or during calibration process. The I/O Link COM mode supports the Command Mode and Cyclic Mode operational states.

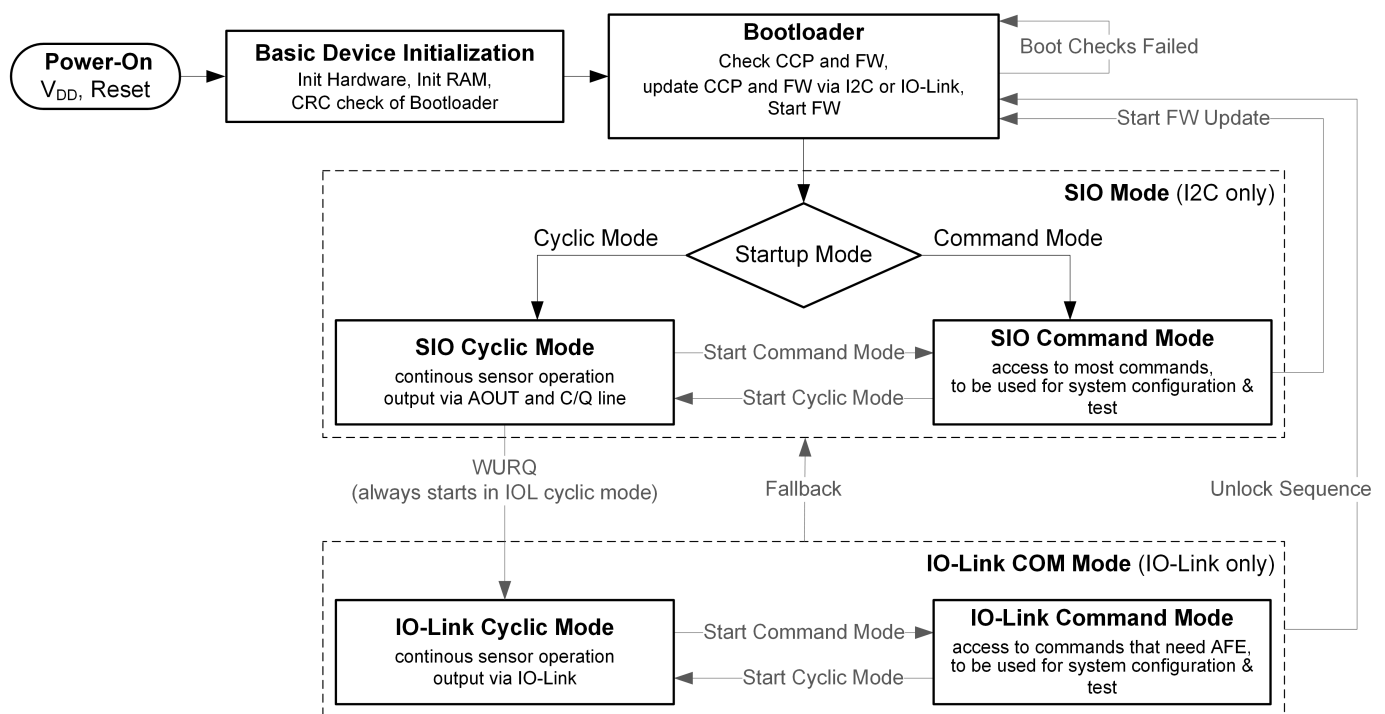


Figure 6: Main Operation Modes

SIO Mode and I/O-Link Mode will support the following operation states:

Cyclic Mode	This is the default mode for continuously operating sensors. In this mode autonomous, cyclically repeated sensor measurements are performed and related digital (via IO-Link in IO-Link COM Mode), and/or analog output (via AOUT in SIO Mode) and/or digital alarm output (C/Q line in SIO Mode) updates are provided. The cyclic sequences for sensor measurements and system diagnostic measurements are configurable and allow to define the output update rate of the conditioned sensor signals.
Command Mode	This is the most appropriate mode for evaluation, test, and calibration purposes. In this mode, all commands to support calibration process via serial interface commands are available. Command Mode can be used for applications requiring re-occurring digital interaction on functions that are not available in Cyclic Mode or certain system configuration changes.

After power-on (reset) the ZSSC3286 always enters the Basic Device Initialization phase. In this phase the firmware is still in boot-up and command interpreter is not yet functional. Therefore write access and command execution is not supported. If Basic Device Initialization is successful, ZSSC3286 enters Bootloader operation mode.

Finally the ZSSC3286 will enter SIO mode. In SIO mode the programmed operation state is started (System Startup Mode set by CCP register *0x2E – StartupParamCfg*). The System Startup Mode can be configured via GUI path: Configure\System Control\System Startup.

Changing the ZSSC3286 to another operation mode or operating state is possible via the start commands START_CM and START_CYC (see subsection 9.6 for details).

The ZSSC3286 supports three different types of digital interfaces: IO-Link, I2C, and OWI while OWI is only used to control the IO-Link physical layer transceiver.

3.2 System Clocks

3.2.1 Main Internal Oscillators and Specifications

ZSSC3286 is equipped with the following internal oscillators:

- Calibrated, first order temperature compensated 16MHz system clock oscillator
- Un-calibrated, first order temperature compensated 32kHz ultra low power oscillator

3.2.2 Main System Clock

The Main System Clock, which drives the ARM MCU, the memories (ROM, Flash, SRAM), and the peripherals is derived from the internal System Clock Oscillator. By default, the oscillator frequency (16MHz) is directly applied across the entire system without further down division. Hardware and software driven clock gating are applied to maintain a low power consumption.

3.2.3 Always-On Clock

The 32kHz always-on clock is used by the System Management Unit to control the Basic Device Initialization (power-up sequence) of the ZSSC3286 device, as well as by the internal low speed timer.

3.3 System Reset

The ZSSC3286 resets at following scenarios:

- Power-On-Reset
Brown out Voltage at VDD or VDDD is below the specified limits (see Table 8)
- External reset RESN pin of ZSSC3286 is set to LOW.
- Command (via I2C) Start Firmware Update command
- Command sequence
(via IO-Link) Unlock sequence

Table 15: VDDD Power-On-Reset Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{riseVDDD}$	Reset release voltage	VDDD level where reset is released	1.35		1.8	V
$V_{fallVDDD}$	Reset voltage	VDDD level where reset is generated	1.1		1.6	V
$V_{hysVDDD}$	Reset hysteresis voltage		50		500	mV

4 Analog Front End (AFE)

4.1 AFE Signal Path

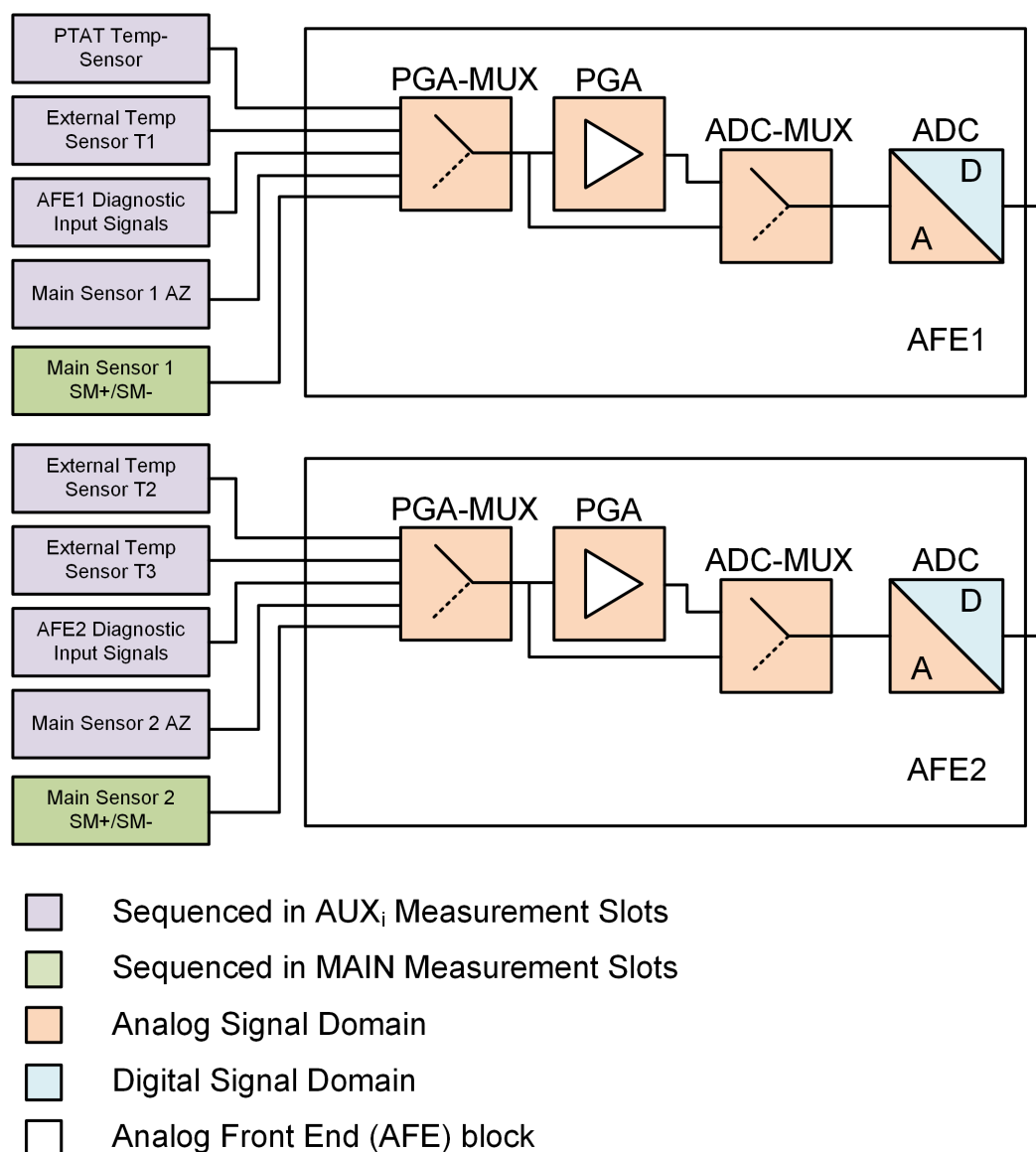


Figure 7: Block Diagram Analog Front End

4.2 Bridge Sensor Inputs

4.2.1 Resistive Bridge Sensors

Table 16: Resistive Bridge Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
R_{br}	Bridge resistor	Constant Voltage Mode	0.825		60	k Ω
		Constant Current Mode	0.1			
C_{br}	Bridge capacitance, depends on the required resolution: $\tau = R_{br} \times C_{br}$ defines the settle time.	Filter capacitances C_{br} between INN x /INP x and VSS		1		nF
V_{sig}	Signal span	mV/V is related to the bridge supply			500	mV/V
V_{off}	Signal offset	For example: $V_{sig} = 1\text{mV}$ allows $V_{off} = 20\text{mV}$			2000	% off V_{sig}
					20	1/ V_{sig}

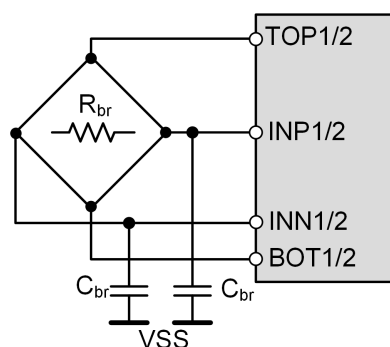


Figure 8: Bridge Sensor Type 1

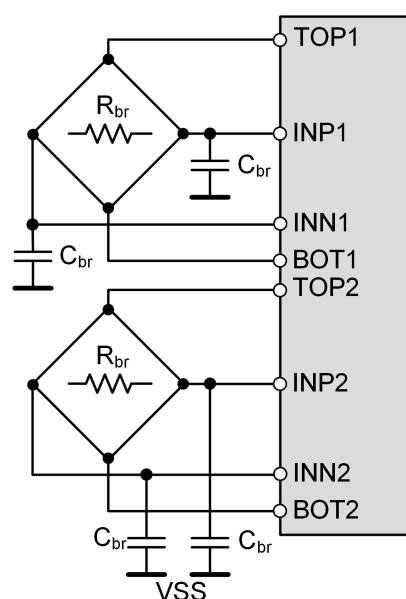
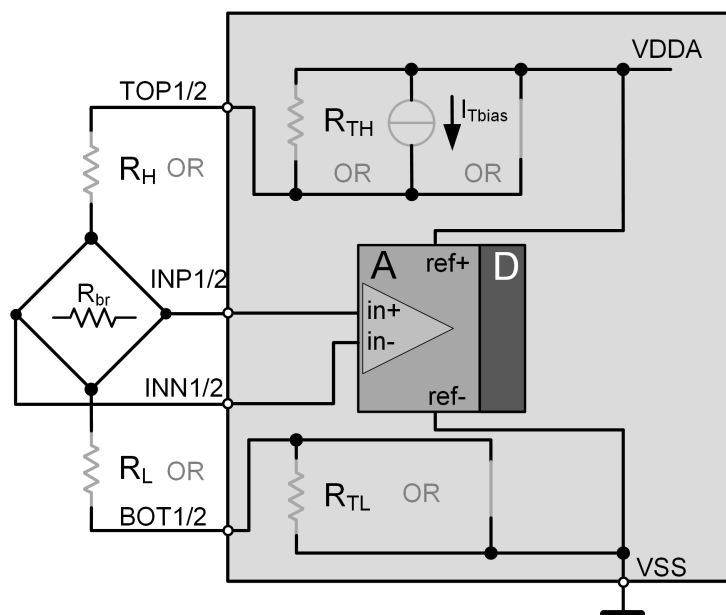


Figure 9: Bridge Sensor Type 2

In single bridge applications shown in Figure 8 the resistive bridge can be connected to either AFE1 or AFE2 depending on PCB layout requirements.

The resistive bridge can be sourced in either Constant Voltage mode (V-source) or in Constant Current mode (I-source), whereby last mode requires low bridge resistance.



Legend:

Gray components: can be activated “either-or” via the GUI.

Figure 10: Resistive Bridge Bias Configurations

In Constant Current mode the bridge output must be set within the common input range of the PGA. This can be done with a low side external resistor R_L or with the internal resistor R_{TL} . The current that is supplied to the bridge must be adjusted to bridge resistance and this additional R_L or internal R_{TL} to meet the common input range of PGA.

In Constant Voltage mode the bridge current can be reduced by inserting the internal high and low side resistors R_{TH} , R_{TL} or by adding external resistors R_H and R_L .

Table 17: Resistive Bridge Supply Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{TOP1/2}$	Output voltage at TOP1/2			VDDA		V
I_{load}	Load current	In Constant Voltage mode defined by bridge resistance			2	mA
I_{Rbr_bias}	Current out of TOP1/2	In Constant Current mode adjustable via <i>BmBrdgIBias</i>	5		500	μ A
C_{TOP_BOT}	Load capacitance				2.2	nF
R_{TH}, R_{TL}	Bias resistor		1.3		40	k Ω

4.3 Auxiliary Temperature Sensor Inputs

4.3.1 Internal PTAT Temperature Sensor

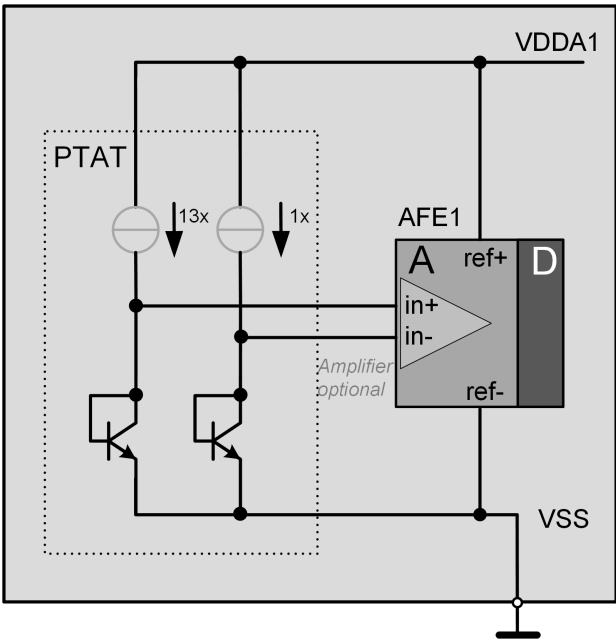


Figure 11: PTAT Sensor Configuration

Table 18: Internal PTAT Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
T _{meas}	Measurement range		-55		125	°C
E _T	Measurement error	Calibrated	-5		5	K
ADC _{res}	Resolution	Programmable ADC resolution	10		15	bit
T _{res}	Effective resolution	±1.5sigma	2			LSB/°C
S	Sensitivity	Differential output voltage	218		230	μV/K

4.3.2 External Temperature Sensors

Three different external sensor types can be used to measure the temperature of the main sensor or a media temperature in the auxiliary signal path of the AFEs:

- PTC
- Diode
- TC Bridge Sensor

The PTC and Diode Sensors can be supplied either in Sink Mode or in Source Mode as shown in Figure 12. The gray marked components can be activated “either-or” via the GUI. The AGND potential is at $VDDA/2$.

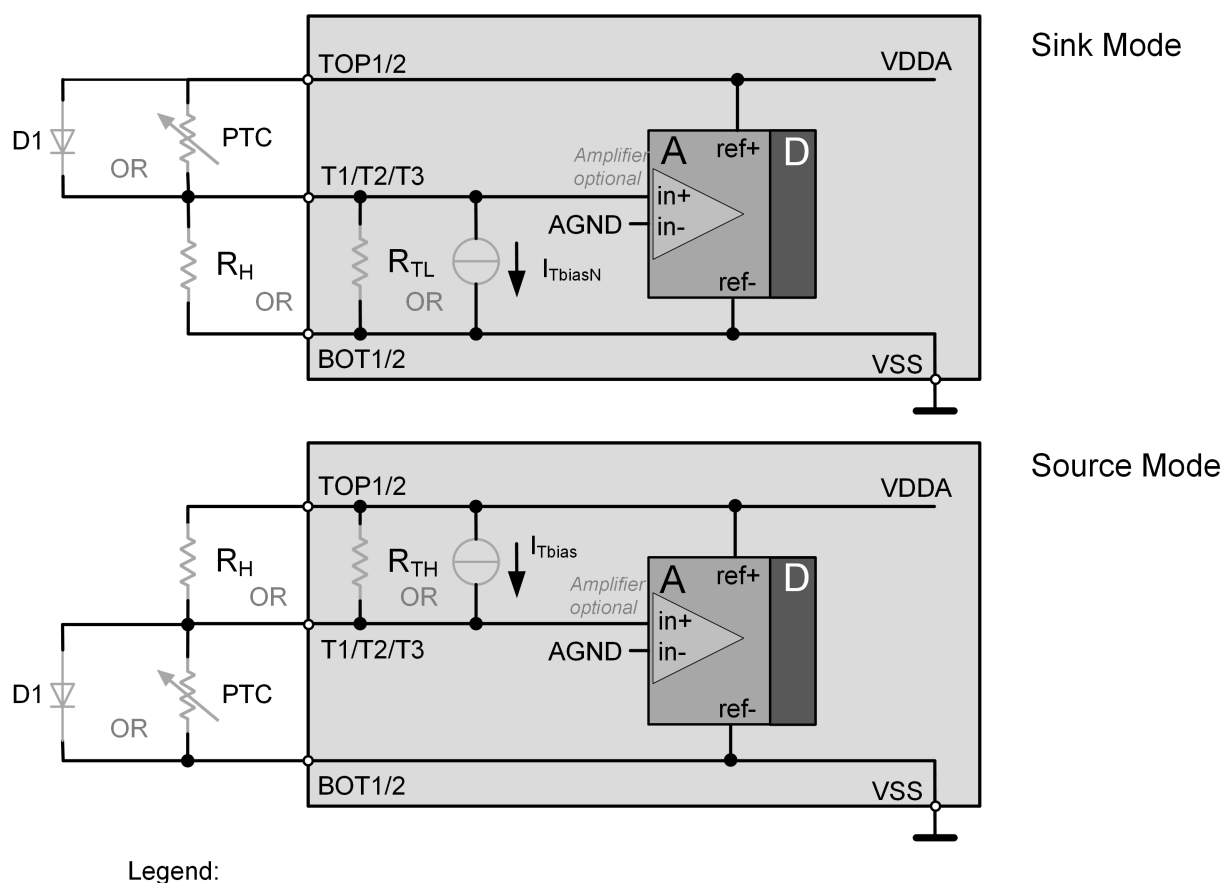
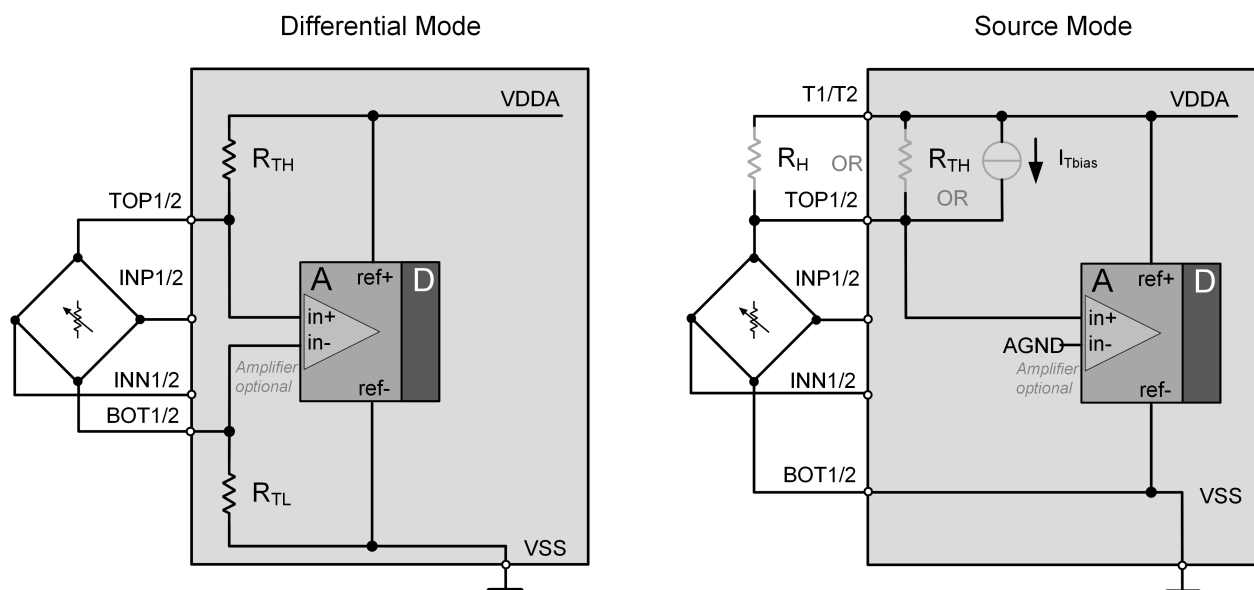


Figure 12: PTC, Diode Sensor Bias Configurations

TC Bridge Sensor configurations can be supplied in Differential Mode or Source Mode as shown in Figure 13.



Legend:

Gray components: can be activated “either-or” via the GUI. The AGND potential is at VDDA/2.

Figure 13: TC Bridge Sensor Bias Configurations

Table 19: External Temperature Sensor Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
R_{sensor}	Sensor resistance (PTC/TC Bridge Sensor)		50		1M	Ω
ADC_{res}	ADC resolution	Programmable ADC resolution	10		15	bit
ENOB	Effective resolution	$\pm 1.5\sigma$	14			bit

4.4 Programmable Gain Amplifier (PGA)

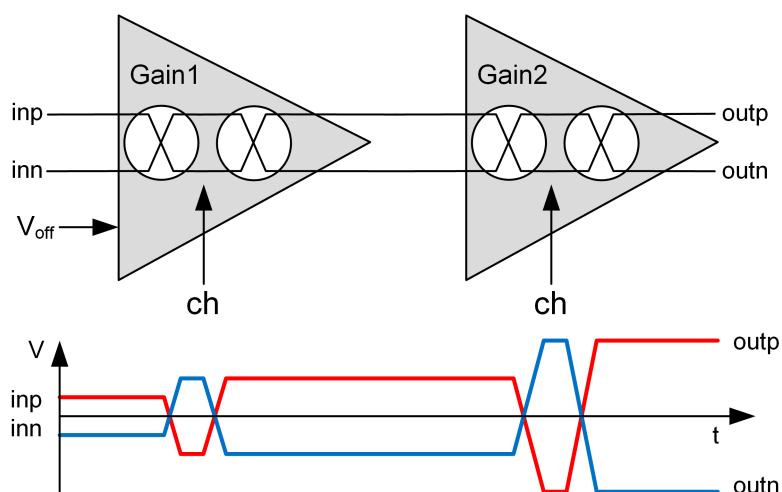


Figure 14: PGA Architecture

The first amplifier (Gain1) has a built in PGA offset compensation (auto-zero) that is refreshed at the beginning of every measurement. The second stage has no offset compensation. The second stage amplifier offset is present at the PGA output with offset $\times$ Gain2. Both PGA amplifier stages have built-in chopper functionality to suppress $1/f$ noise.

The gain settings that can be selectively programmed for both PGA stages are listed in Table 20.

Table 20: PGA Gain Steps

Gain1	Gain2
1.2	1.1
2	1.2
4	1.3
5.97	1.4
11.9	1.5
19.8	1.6
29.6	1.7
39.2	1.8
58.1	
76.6	
112	
143	
187	
223	
275	

If bridge sensors show noticeable DC offsets in their differential output voltage (usable differential voltage range is offset from zero) this limits the maximum PGA gain, which can be applied without putting the PGA into saturation. To compensate for such sensor offsets, the PGA can be programmed to shift the input signal by an offset voltage shown in Table 21 and Figure 15 before it gets gained up. The default shift is 0mV, the offset can be compensated by 15 steps in positive and negative direction as shown in Table 21. The PGA offset shift function is offered only for PGA Gain1 $\geq$ 11.9.

Table 21: PGA Input Offset Compensation Steps

$11.9 \leq \text{Gain1} \leq 223$ [mV]	Gain1 = 275 [mV]
0	0
± 1.9	± 1.5
± 3.8	± 3
± 5.6	± 4.5
± 7.5	± 6
± 9.4	± 7.5
± 11.3	± 9
± 13.1	± 10.5
± 15	± 12
± 16.9	± 13.5
± 18.8	± 15
± 20.6	± 16.5
± 22.5	± 18
± 24.4	± 19.5
± 26.3	± 21
± 28.1	± 22.5

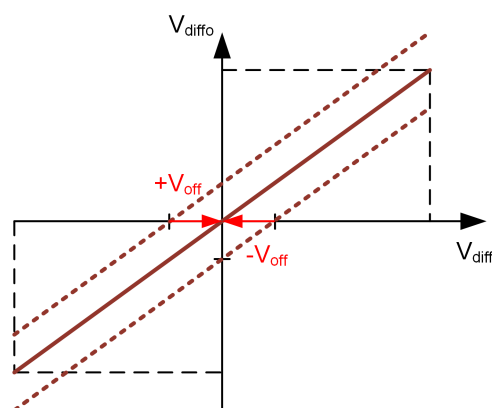


Figure 15: PGA Input Offset Compensation

PGA gain and the Input Offset Compensation value can be programmed separately for the two main bridge sensors and for the three external auxiliary temperature sensors that can be connected to the ZSSC3286. The PGA Input Offset Compensation feature is limited to SM+/SM- and SM+ sequencer configurations which are described in subsection 4.6.

Table 22: PGA Parameters

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
Gain	Total PGA gain	Programmable in 15/8 steps: • stage1: 15 steps, 1.2 to 275 • stage2: 8 steps, 1.1 to 1.8	1.32		495	V/V
V _{cmi}	Input Common Mode voltage			VDDA/2		V
BW _{PGA}	Bandwidth			5		kHz
t _{az_PGA}	Auto-zero time		10			μs
f _{ch_PGA}	Chopper frequency			100		kHz

4.5 Analog-to-Digital Converter (ADC)

An incremental delta-sigma analog-to-digital converter (ADC) is used to digitize the PGA signal. To allow optimizing the trade-off between conversion time and resolution, the resolution can be programmed from 10-bit to 24-bit. The ADC processes differential input signals around its input Common Mode level VDDA/2. Table 23 lists the ADC resolution, signal ranges, conversion times for a single analog-to-digital conversion and VDDA = 1.65V.

Table 23: ADC Configuration Parameters

ADC Resolution [Bits]	Full Scale Input Voltage V _{fs} [V]	LSB Size V _{LSB} [μV]	Conversion Time, Typical, T _{Conv} [μs]	Conversion Rate, Typical, F _{Conv} [kHz]
10	±1.418	2768.638	32.54	30.73
11	±1.425	1391.718	43.75	22.86
12	±1.431	698.499	59.59	16.78
13	±1.434	350.189	81.99	12.20
14	±1.437	175.428	113.68	8.80
15	±1.439	87.832	158.49	6.31
16	±1.440	43.958	221.86	4.51
17	±1.441	21.994	311.48	3.21
18	±1.442	11.002	438.22	2.28
19	±1.443	5.503	617.46	1.62
20	±1.443	2.752	870.94	1.15
21	±1.443	1.376	1229.41	0.81
22	±1.443	0.688	1736.38	0.58
23	±1.443	0.344	2453.33	0.41
24	±1.444	0.172	3467.25	0.29

The ADC can perform an additional offset shift (independent of the PGA shifting) to adapt input signals with offsets to the ADC input range. Enabling the offset shift causes the ADC to perform an additional amplification of the ADC's input signal by factor ×2. This must be considered for a correct PGA configuration setup.

The ADC offset shift feature is limited to SM+/SM- and SM+ sequencer configurations which are described in subsection 4.6.

The shift values in Table 24 are related to the input voltages at INP, INN:

- Full scale differential input voltage: $V_{INdiff_fs} = \frac{V_{fs}}{Gain}$
- Differential input shift voltage: V_{INdiff_shift}
- Maximum, minimum differential input voltage: V_{INdiff_max} , V_{INdiff_min}

Table 24: ADC Input Offset Shift Steps

PGA Polarity	ADC Shift Enable	ADC Gain	ADC Shift	$V_{INDIFF_shift} / V_{INDIFF_fs}$	$V_{INDIFF_min} / V_{INDIFF_fs}$	$V_{INDIFF_max} / V_{INDIFF_fs}$
Positive	0	x1	0	No shift	-1	+1
Negative			0	No shift	+1	-1
Positive	1	×2	1	7/8	-1/16	+15/16
			2	6/8	-2/16	+14/16
			3	5/8	-3/16	+13/16
			4	4/8	-4/16	+12/16
			5	3/8	-5/16	+11/16
			6	2/8	-6/16	+10/16
			7	1/8	-7/16	+9/16
			0	No shift	-1/2	+1/2
Negative			0	No shift	+1/2	-1/2
			1	1/8	-9/16	+7/16
			2	2/8	-10/16	+6/16
			3	3/8	-11/16	+5/16
			4	4/8	-12/16	+4/16
			5	5/8	-13/16	+3/16
			6	6/8	-14/16	+2/16
			7	7/8	-15/16	+1/16

4.6 AFE Sequencer

The measurement flow, especially the frequency of main bridge measurements vs. auxiliary measurements can be configured by the user. Once started by the ARM MCU, the measurement flow runs autonomously controlled by the AFE. The AFE Sequencer state machine ensures predictable measurement timing in the continuous cyclic operation of ZSSC3286.

The AFE sequencer carries out AFE measurements based on a measurement slot mechanism. There can be up to eight measurement slots assigned per AFE, which form a single measurement cycle. A measurement cycle can be executed only once (for example, initiated by a dedicated command request) or continuously cycled in Cyclic Mode operation of ZSSC3286.

Each of the measurement slots inside AFE1 or AFE2 can be individually configured for the following measurement types:

- Sensor Measurement (SM+): bridge inputs INP/INN directly converted (non-inverted)
- Sensor Measurement (SM-): bridge inputs INP/INN flipped (inverted)
- Auxiliary Measurement (aux_i): cycles through the auxiliary measurement vector

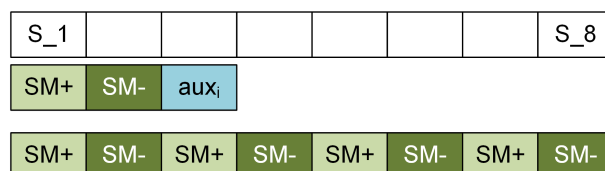


Figure 16: Measurement Slot Configuration with Two Example Configurations

The actual number of measurement slots per measurement cycle can be defined by the user between 1 and 8. The hardware allows to configure any combination, but not all combinations lead to reasonable measurement schemes. The GUI supports the user in selecting proper measurement schemes. Figure 16 shows two example configurations. The measurement schemes are explained in further detail in subsubsection 4.6.3, 4.6.4, and 4.6.5. 4.6.4, and 4.6.5.

Auxiliary measurements usually have lower response time requirements than measurements on the main sensor bridge. The auxiliary measurements are therefore cycled orthogonal to the main loop of the sequencer. Activated

auxiliary measurements become listed in the so called auxiliary measurement vector. The vector index 'i' gets increased after each executed aux_i slot and starts over after the entire set of active measurements was completed. The configuration options of auxiliary measurements are further detailed in subsubsection 4.6.2.

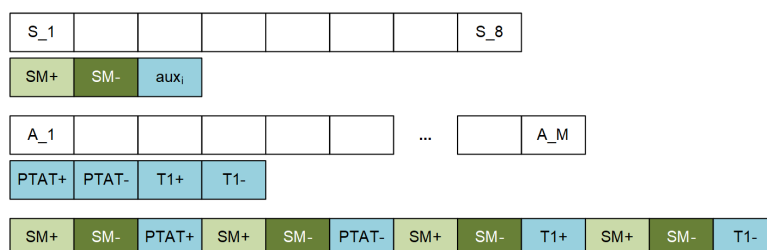


Figure 17: Auxiliary Measurement Configuration, and Corresponding Measurement Flow

Figure 17 illustrates the sequencer operation with an example configuration using 4 auxiliary measurements. During the 3rd measurement (configured as aux_i), the first enabled auxiliary measurement is executed ("PTAT", internal temperature sensor). After the measurement sequence ($\text{SM+}/\text{SM-}/\text{aux}_i$) is executed again in the next measurement slot, the next enabled auxiliary measurement is executed ("T1", external temperature sensor). Similarly, "Bridge1 open" and "Bridge1 short" diagnostics measurements are carried out in following measurement slots. During the 5th execution of the measurement sequence, the PTAT auxiliary measurement is carried out again.

4.6.1 Bridge Sensor Measurement Configuration

The main bridge sensor signals can be measured in three ways:

- $\text{SM+}/\text{SM-}$ (or $\text{SM-}/\text{SM+}$) measurement
- $\text{SM+}/\text{AZ}$ measurement (SM+ and auto-zero measurement)
- SM+ without AUX_AZ measurement

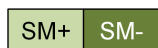


Figure 18: $\text{SM+}/\text{SM-}$ (or $\text{SM-}/\text{SM+}$) Measurement



Figure 19: $\text{SM+}/\text{AZ}$ Measurement

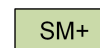


Figure 20: SM+ without AZ Measurement

Configurations in Figure 18 and Figure 19 provide digital offset compensation of the entire signal path in the analog front end. The configuration in Figure 20 only provides analog offset compensation in the first stage of the PGA. The offsets of the second PGA stage and the ADC offset are not compensated.

In the $\text{SM+}/\text{SM-}$ configuration, the bridge inputs INP/INN are first converted straight forward in the SM+ measurement slot and second with an internally flipped INP/INN input signal in SM- slot. For the $\text{SM+}/\text{AZ}$ configuration, the second measurement (AZ) is performed without applied input signal. INP/INN become disconnected from the sensor and internally shorted for AZ measurements.

Since signal integration time in $\text{SM+}/\text{SM-}$ configuration is twice as long as in the $\text{SM+}/\text{AZ}$ configuration (same ADC resolution settings assumed), the $\text{SM+}/\text{SM-}$ configuration achieves approx. 0.5 bit better noise performance than the $\text{SM+}/\text{AZ}$ configuration. The longer input signal integration time of the $\text{SM+}/\text{SM-}$ configuration leads to an increased output update rate and step response as described in subsubsection 4.6.3 and subsubsection 4.6.4.

The auto-zero measurement (AZ) belongs to the group of auxiliary measurements and is cycled less often if either of the following options appears:

- further auxiliary measurements are enabled in the auxiliary measurement vector described in subsubsection 4.6.2
- accelerated bridge measurements are enabled as described in subsubsection 4.6.5

Since the offset in the internal signal path varies rather slowly, the auto-zero compensation remains very accurate even for a long auxiliary measurement vector.

Because SM- needs to be configured and most sensor applications also require other auxiliary measurements, the assignment of the AZ measurement to the group of auxiliary measurements helps to reduce the worst case step response on the main bridge sensor.

The lowest step response is achieved with the “SM+ only” configuration shown in Figure 20 if no other auxiliary measurements are needed for the desired sensor application.

A further influence on the overall measurement time (output update rate and worst case response) has the input settling time of each measurement task. This settling is required depending on the output resistance of the external sensors, respective capacitive loads on the signal lines and the ADC resolution selected by the user. The input settling time is always inserted before an ADC conversion starts and can be configured in the GUI for main bridge measurements via Configure\AFE\Bridge\SetTime [μs] and for auxiliary temperature measurements via Configure\AFE\Temperature\SetTime [μs].

Considering achievable measurement latencies and noise performance, configuration shown in Figure 18 is better when higher ADC resolutions are required or for sensor configurations with fast input settling, while configuration shown in Figure 19 and Figure 20 are preferable when lower ADC resolutions become selected or for sensor configurations requiring long input settling times (bridge settling time has a considerable impact on the timing budget).

4.6.2 Auxiliary Measurement Configuration

The supported auxiliary measurements are:

- Auto-zero for internal signal path
- Temperature on sensor input T1
- Temperature on sensor input T2
- Temperature on sensor input T3
- Internal PTAT
- AFE diagnostic checks
 - Sensor connection checks for all external sensors (Short to TOPx pin or BOTx pin and Open)
 - Bridge signal range check

They can be activated in the GUI via tabs Configure\AFE\Sequencer, Configure\AFE\Temperature Selection and Diagnostic\Sensor\AFE.

4.6.3 Timings with SM+/SM- Configuration

As described in subsubsection 4.6.1, sensor configurations with fast input settling or applications requiring higher ADC resolutions are better served with the SM+/SM- scheme for the main bridge measurement. For the step response consideration the following application example is used:

- Sensor Measurement (non-inverted)
- Sensor Measurement (inverted)
- Auxiliary Measurement (for example, for sensor temperature)

Note: SM+ and SM- can be exchanged yielding to the same result



Figure 21: SM+/SM- Configuration

For SM+/SM- configuration the measurement cycle and output update rate is shown in Figure 22 for an example of three enabled auxiliary measurement tasks. After finishing the last main measurement task, firmware starts with data processing as described in section 5 and section 6. The resulting signal conditioning output signal is written into output registers.

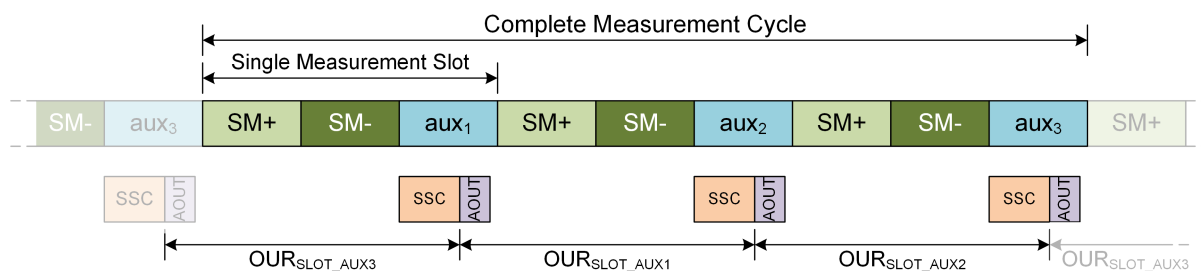


Figure 22: SM+/SM- Measurement Cycle and Output Update Rate

For SM+/SM- configuration the worst-case step response is shown in Figure 23 and consists of:

- 4 sensor ADC-conversion times (duration depending on selected ADC resolution)
- 1 auxiliary conversion time (fixed duration, based on longest auxiliary conversion timing)
- 1 SSC calculation

Additionally, there is a delay that depends on the selected interface:

- 1 settling time at AOUT for all analog output options
- 2 cycle times for IO-Link communication

In a worst-case scenario, intermediate results can occur due to the asynchronous nature of input changes and data readout relative to the internal measurement cycle.

Worst-case scenario for IO-Link communication depends on IO-Link master since it defines the cycle time. ZSSC3286 defines minimum cycle time of 600µs.

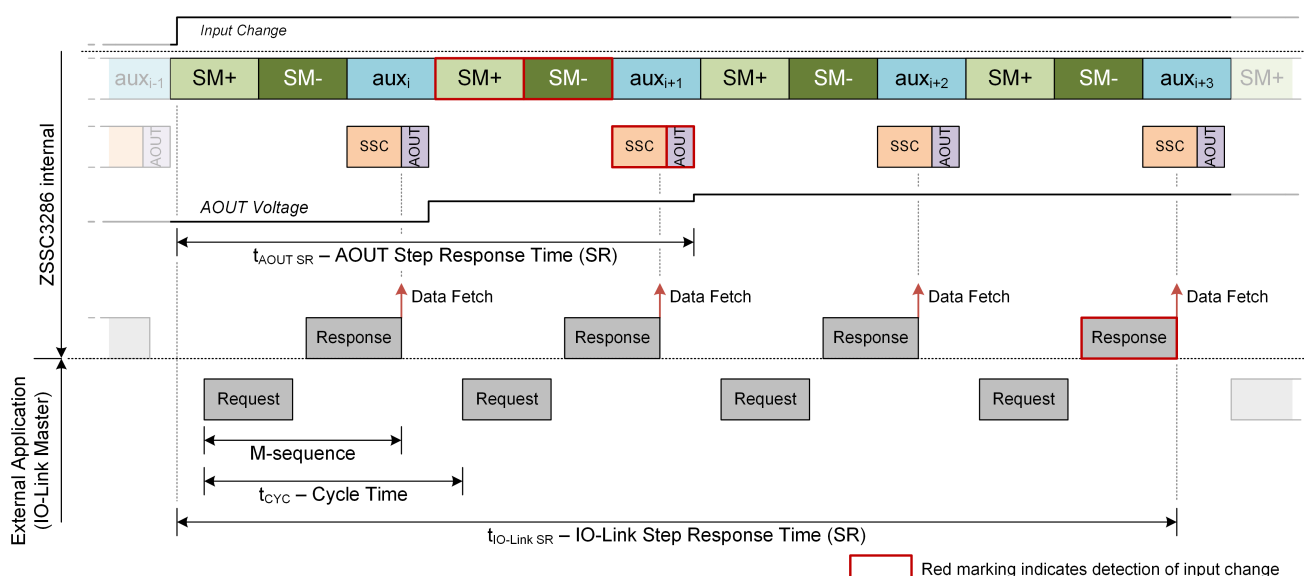


Figure 23: SM+/SM- Step Response

4.6.4 Deterministic Input Step Response with SM+/AZ Configuration

Since the SM+/SM- configuration samples the input signal twice as long as the SM+/AZ configuration and it suffers a noticeable timing overhead for sensor configurations with slow sensor input signal settling, a second SM+/AZ measurement scheme with deterministic step response times is available. For the step response consideration, the following application example is used:

- Sensor measurement (non-inverted)
- Auxiliary measurement (for example, for sensor path auto-zero and/or sensor temperature) within the auxiliary measurement vector



Figure 24: SM+/AZ Configuration

For SM+/AZ configuration the measurement cycle and output update rate is shown in Figure 25 for an example of five enabled auxiliary measurement tasks. After finishing the SM+ main measurement task, firmware starts with data processing as described in section 5 and section 6. The resulting signal conditioning is written into the output registers. Assuming equal ADC resolution settings for the SM+/SM- configuration as described in subsubsection 4.6.3 and the SM+/AZ configuration described in this section, the worst case step response is shorter by two sensor AD-conversion times in case of the SM+/AZ setup. The auxiliary measurement duration in the SM+/AZ setup may become slightly longer than for the SM+/SM- configuration, since it is determined by the AZ measurement time if the selected resolution of the main bridge is larger than the resolutions of all other active auxiliary measurements. This is because the resolution of the AZ measurement is set by the resolution of the SM+ measurement and the longest measurement of the auxiliary measurement vector determines the duration of the aux_i slot(s)

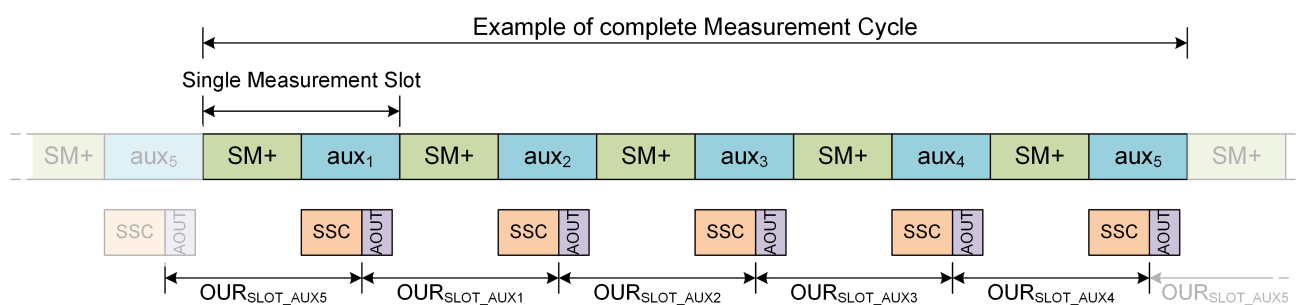


Figure 25: SM+/AZ Measurement Cycle and Output Update Rate

As shown in Figure 26, the worst-case latency consists of:

- 2 sensor AD-conversion times (duration depending on selected ADC resolution)
- 1 auxiliary conversion time (fixed duration, based on longest auxiliary conversion timing)
- 1 SSC calculation

Additionally, there is a delay that depends on the selected interface:

- 1 settling time at AOUT for all analog output options
- 2 cycle times for IO-Link communication

In a worst-case scenario, intermediate results can occur due to the asynchronous nature of input changes and data readout relative to the internal measurement cycle.

Worst-case scenario for IO-Link communication depends on IO-Link master since it defines the cycle time. ZSSC3286 defines minimum cycle time of 600µs.

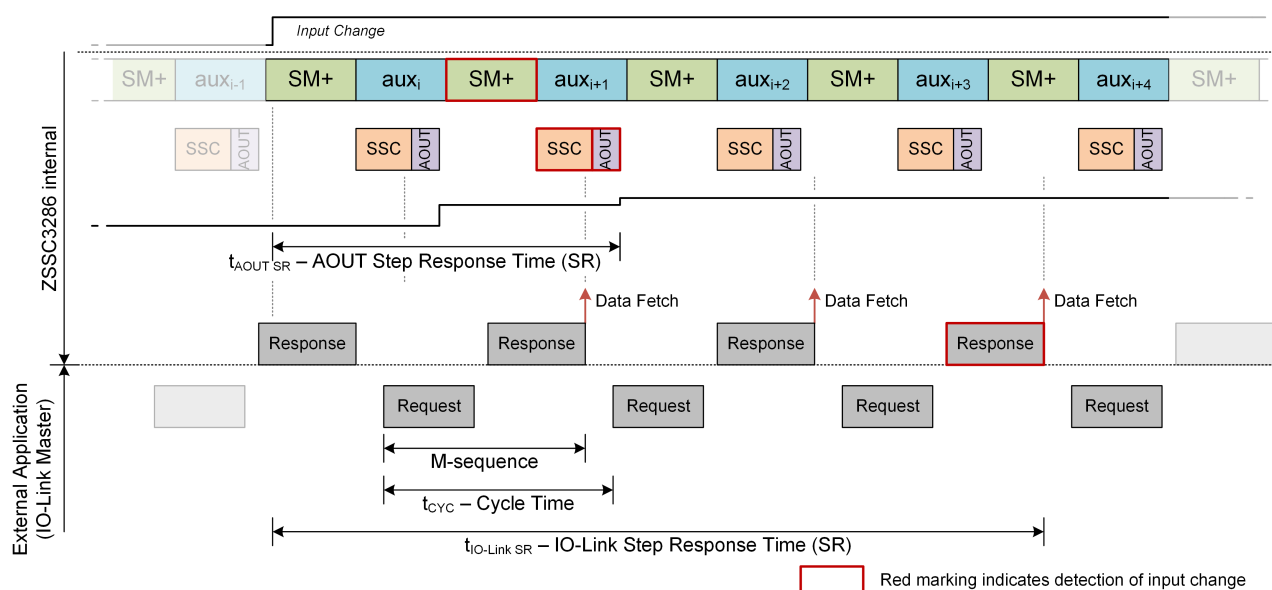


Figure 26: Measurement Flow and Latency for SM+/AZ Configuration

4.6.5 Accelerated Bridge Measurements with Sparsely Inserted Auxiliary Measurements

For applications which focus on highest conversion rates at the bridge sensor input but do not require a deterministic maximum input to output latency of the corrected sensor signal, auxiliary measurements can be sparsely inserted to occur only after a certain number of measurement sequences were executed by the AFE sequencer. This way, auxiliary measurements become executed even more seldom, giving the main sensor bridge measurements priority.

The AFE sequencer can be configured such that an aux_i measurement is only executed (inserted) after every P x measurement sequence. P can be selected as 2, 4, or 8. Figure 27 shows an example of a measurement flow with $P = 2$ while Figure 28 uses $P = 8$ where aux_i measurements are executed after eighth measurement sequences.

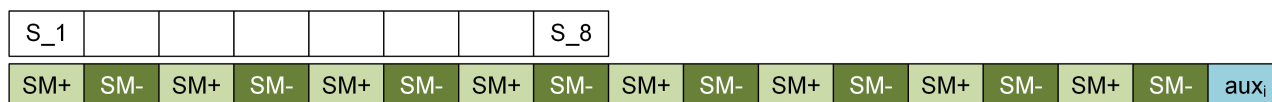


Figure 27: Auxiliary Measurement Executed after Every Second Measurement Cycle

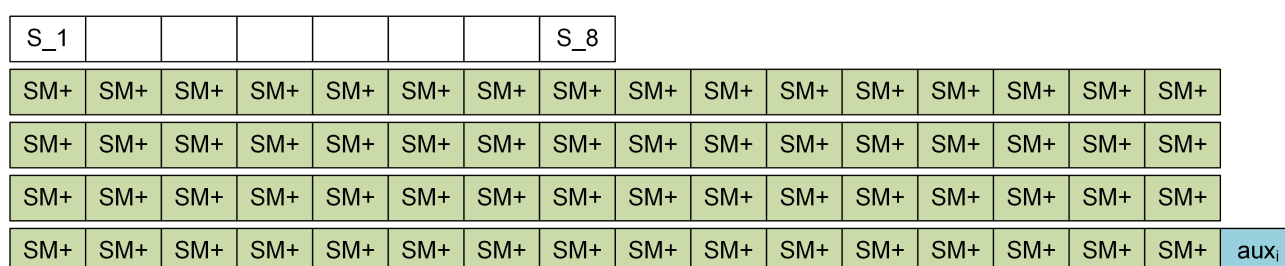


Figure 28: Sequencer Setup for Highest Update Rate on Bridge Sensor

For the use case of SM+/SM- measurement sequencer, the output update rate is shown in Figure 29. The complete measurement cycle is finished after finishing the last auxiliary measurement task. After finishing the SM+ main measurement task, firmware starts with data processing as described in section 5 and section 6. Since the auxiliary measurement tasks are inserted only after every 2nd, 4th, or 8th measurement sequence, the output update rate also varies in the same period. The same description is also valid if SM+/AZ only measurement sequencer is used.

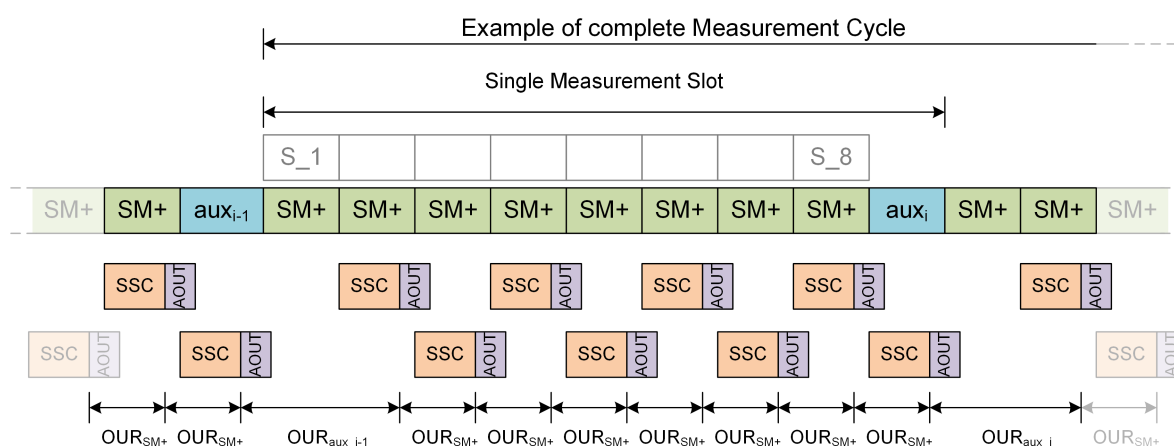


Figure 29: SM+ Accelerated Measurement Cycle and Output Update Rate

The worst case step response mainly depends on the selected AFE sequencer mode:

- SM+/SM- configuration: refer to Figure 23 and description for step response in subsection 4.6.3
- SM+/AZ configuration: refer to Figure 26 and description for step response in subsection 4.6.4

5 Sensor Signal Conditioning

5.1 Signal Conditioning Data Path

Figure 30 illustrates the sensor signal conditioning flow that is applied for AFE output data to compensate for offset, gain, non-linearity, and temperature effects and to calculate the conditioned data for further output processing. See subsection 5.2 to subsection 5.6 for more information on the basis mathematical subfunctions.

The signal path from conditioned data to individual output signals is described in section 6.

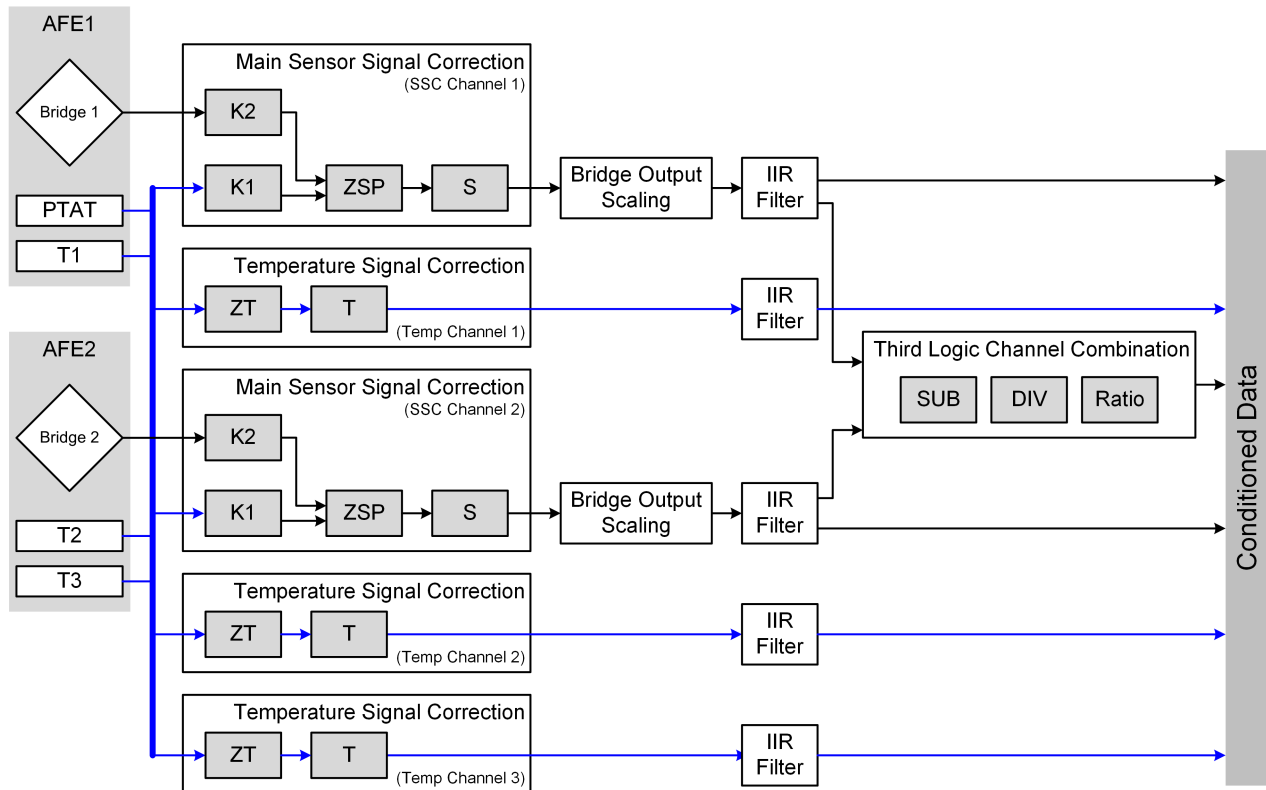


Figure 30: Sensor Signal Flow Chart from Input to Conditioned Data

5.2 Main Sensor Signal Correction

ZSSC3286 supports basic second-order compensation of sensor nonlinearities. The following basic SSC math options are available:

- Sensor signal correction
 - SOT Curve-0: Parabolic compensation curve
 - SOT Curve-1: S-shaped compensation curve
- Temperature signal correction

The parabolic compensation is recommended for most sensor types. The applied SSC math option can be selected in the GUI through the field Calibration\Curve.

The available SSC capabilities for SOT Curve-0 and SOT Curve-1 are described in Table 25, Table 26, and Table 27. The used equation terms are as follows:

S	Corrected sensor reading output via I2C, OWI, or SPI	Valid Input Range 0x0 to 0xFFFFF
S_Raw	Raw sensor reading from ADC (after AZ correction, depends on Afe1SmConfig)	-(0x7FFFFF) to 0x7FFFFF
Gain_S	Sensor gain term	-(0x7FFFFF) to 0x7FFFFF
Offset_S	Sensor offset term	-(0x7FFFFF) to 0x7FFFFF
Tcg	Temperature coefficient gain term	-(0x7FFFFF) to 0x7FFFFF
Tco	Temperature coefficient offset term	-(0x7FFFFF) to 0x7FFFFF
T_Raw	Raw temperature reading (after AZ correction)	-(0x7FFFFF) to 0x7FFFFF
SOT_tcg	Second-order term for Tcg non-linearity	-(0x7FFFFF) to 0x7FFFFF
SOT_tco	Second-order term for Tco non-linearity	-(0x7FFFFF) to 0x7FFFFF
SOT_sens	Second-order term for sensor non-linearity	-(0x7FFFFF) to 0x7FFFFF
SENS_shift	Post-calibration, post-assembly offset shift	-(0x7FFFFF) to 0x7FFFFF
 ... 	Absolute value	
[...]^{ul}/_{ll}	Bound/saturation number range from <i>ll</i> to <i>ul</i> , overflow and/or underflow is reported as saturation in the Status Byte	

All raw data and compensation coefficients supplied to the formulas are required in 24-bit data format shown in Table 25 and Table 26.

Table 25: Data Format of Raw ADC Readings

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	-2^0	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

Table 26: Data Format of 24-bit SSC Coefficients

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	0 = positive 1 = negative	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

The compensated result data is supplied in 24-bit data format as shown in Table 27.

Table 27: Data Format of Corrected SSC Result

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	2^0	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

5.2.1 Pre-calculation

Simplified:

$$K_1 = 2^{23} + \frac{T_Raw}{2^{23}} \times \left(\frac{4 \times SOT_tcg}{2^{23}} \times T_Raw + 4 \times Tcg \right) \quad (1)$$

$$K_2 = 4 \times Offset_S + S_Raw + \frac{T_Raw}{2^{23}} \times \left(\frac{4 \times SOT_tco}{2^{23}} \times T_Raw + 4 \times Tco \right) \quad (2)$$

Complete:

$$K_1 = \left[2^{23} + \left[\frac{T_Raw}{2^{23}} \times \left[\left[\frac{SOT_tcg}{2^{21}} \times T_Raw \right]_{-2^{25}}^{2^{25}-1} + 4 \times Tcg \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \quad (3)$$

$$K_2 = \left[4 \times Offset_S + \left[S_Raw + \left[\frac{T_Raw}{2^{23}} \times \left[\left[\frac{SOT_tco}{2^{21}} \times T_Raw \right]_{-2^{25}}^{2^{25}-1} + 4 \times Tco \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \quad (4)$$

5.2.2 SOT Curve-0 (Parabolic Compensation)

Simplified:

$$Z_{SP} = \frac{4 \times Gain_S}{2^{23}} \times \frac{K_1}{2^{23}} \times K_2 + 2^{23} \quad (5)$$

$$S = \frac{Z_{SP}}{2^{23}} \times \left(\frac{4 \times SOT_sens}{2^{23}} \times Z_{SP} + 2^{23} \right) + SENS_shift \quad (6)$$

Note: Z_{SP} and S are delimited to positive number range.

Complete:

$$Z_{SP} = \left[\left[\frac{Gain_S}{2^{21}} \times \left[\frac{K_1}{2^{23}} \times K_2 \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} \quad (7)$$

$$S = \left[\left[\frac{Z_{SP}}{2^{23}} \times \left[\left[\frac{SOT_sens}{2^{21}} \times Z_{SP} \right]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} + SENS_shift \right]_{-2^{25}}^{2^{24}-1} \quad (8)$$

5.2.3 SOT Curve-1 (S-shaped Compensation)

Simplified:

$$Z_{SS} = \frac{4 \times Gain_S}{2^{23}} \times \frac{K_1}{2^{23}} \times K_2 \quad (9)$$

Note: K_1 and K_2 according to Equation 3 and Equation 4.

$$S = \frac{Z_{SS}}{2^{23}} \times \left(\frac{4 \times SOT_sens}{2^{23}} \times |Z_{SS}| + 2^{23} \right) + 2^{23} + SENS_shift \quad (10)$$

Note: S is delimited to positive number range.

Complete:

$$Z_{SS} = \left[\frac{Gain_S}{2^{21}} \times \left[\frac{K_1}{2^{23}} \times K_2 \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \quad (11)$$

$$S = \left[\left[\left[\frac{Z_{SS}}{2^{23}} \times \left[\left[\frac{SOT_sens}{2^{21}} \times |Z_{SS}| \right]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} + SENS_shift \right]_{-2^{25}}^{2^{24}-1} \quad (12)$$

5.3 Temperature Signal Correction

Temperature is measured either internally by the ZSSC3286, through an additional external element, or by means of a combination of ZSSC3286 internal and external temperature sensing capabilities. Temperature correction contains both linear gain and offset terms as well as a second-order term to correct for any nonlinearities. For temperature, second-order compensation is always parabolic.

The correction equation terms are as follows:

		Valid Input Range
T	Corrected temperature sensor reading output via digital interface	0x0 to 0xFFFFF
T_Raw	Raw temperature reading after AZ correction	-(0x7FFFFF) to 0x7FFFFF
$Gain_T$	Gain coefficient for temperature	-(0x7FFFFF) to 0x7FFFFF
$Offset_T$	Offset coefficient for temperature	-(0x7FFFFF) to 0x7FFFFF
SOT_T	Second-order term for temperature source nonlinearity	-(0x7FFFFF) to 0x7FFFFF
T_shift	Shift for post-calibration/post-assembly offset compensation	-(0x7FFFFF) to 0x7FFFFF

The correction formula is best represented as a two-step process as follows:

Simplified:

$$Z_T = \frac{4 \times Gain_T}{2^{23}} \times (T_Raw + 4 \times Offset_T) + 2^{23} \quad (13)$$

$$T = \frac{Z_T}{2^{23}} \times \left(\frac{4 \times SOT_T}{2^{23}} \times Z_T + 2^{23} \right) \quad (14)$$

Note: Z_T and T are delimited to positive number range.

Complete:

$$Z_T = \left[\left[\frac{Gain_T}{2^{21}} \times [T_Raw + 4 \times Offset_T]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} \quad (15)$$

$$T = \left[\left[\frac{Z_T}{2^{23}} \times \left[\left[\frac{SOT_T}{2^{21}} \times Z_T \right]_{-2^{25}}^{2^{25}-1} + 2^{23} \right]_{-2^{25}}^{2^{25}-1} \right]_{-2^{25}}^{2^{25}-1} + T_shift \right]_{-2^{25}}^{2^{25}-1} \quad (16)$$

All raw data and compensation coefficients supplied to the formulas are required in 24-bit data format shown in Table 28 and Table 29.

Table 28: Data Format of Raw Temperature ADC Readings

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	2^0	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

Table 29: Data Format of 24-bit SSC Coefficients for Temperature Compensation

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	0 = positive 1 = negative	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

The compensated result data is supplied in 24-bit data format as shown in Table 30.

Table 30: Data Format of Corrected Temperature SSC Results

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	2^0	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

5.4 Bridge Output Scaling

ZSSC3286 offers a linear rescaling function to amplify or compress a partial region of the sensor input range to the desired signal output range. Figure 31 illustrates the rescaling on an example where the 25% to 75% calibrated signal input range is mapped to the output range of 0% to 100%. The feature is intended for customers who need to separate product derivatives after a common sensor calibration step.

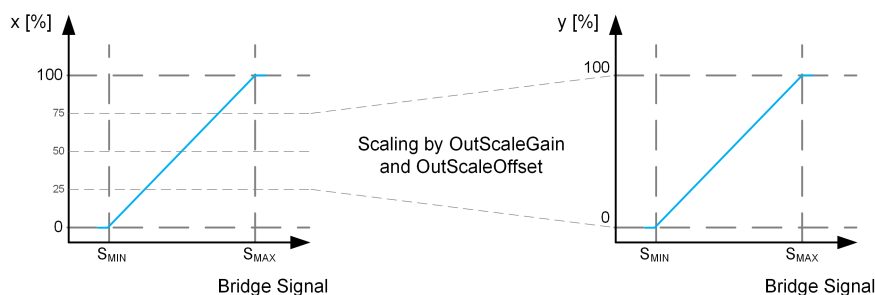


Figure 31: Example: Bridge Output Scaling Function for Scaling 25% - 75%, to final 0% - 100%

The rescaling feature applies the following formula to the SSC conditioned outputs of the main bridge sensor:

$$y = \left[\frac{8 \times OutScaleGain}{2^{23}} \times (x + 8 \times OutScaleOffset) \right]_{0}^{2^{24}-1} \quad (17)$$

The Coefficients *OutScaleGain* and *OutScaleOffset* are stored in the CCP (Configuration and Calibration Page) of ZSSC3286 in signed magnitude format. According to Table 31 *OutScaleGain* is limited to a maximum gain of 4 and the *OutScaleOffset* can vary from -1.5 to 0 related to the SSC result number range 0 to ~2.

Table 31: Examples for Bridge Output Scaling

Input Relative – x [%]		OutScaleGain		OutScaleOffset		Output Relative – y [%]	
		real	CCP Content (Decimal)	real	CCP Content (Decimal)		
0	50.0	2.000	2097152	0.0	0	0	100
0	33.3	3.003	3148876	0.0	0	0	100
0	25.0	4.000	4194304	0.0	0	0	100
25	50.0	4.000	4194304	-0.5	-524288	0	100
25	75.0	2.000	2097152	-0.5	-524288	0	100
50	100.0	2.000	2097152	-1.0	-1048576	0	100
75	100.0	4.000	4194304	-1.5	-1572864	0	100

Table 32 lists the mapping of CCP register content to output scaling coefficients.

Table 32: Data Format of Output Scaling Coefficients in CCP

Bit Number	23	22	21	20	19	...	1	0
Meaning, Weighting	0 = positive 1 = negative	2 ²	2 ¹	2 ⁰	2 ⁻¹	...	2 ⁻¹⁹	2 ⁻²⁰

The GUI supports the calculation of *OutScaleGain* and *OutScaleOffset* based on provided relative input and output range specifications (Can be configured on the GUI tab Configure\Output Scaling).

5.5 IIR Filter

The conditioned outputs of the two main sensor bridge channels CH1 and CH2 and the conditioned outputs of the temperature channels TCh1 to TCh3 can be low pass filtered for noise reduction. Each channel is equipped with an independent configurable IIR Filter. The mathematical filter description is as follows:

$$y_0 = x_0 \quad (18)$$

$$y_i = x_{i-1} + \frac{(x_i - y_{i-1}) \times Diff}{Avg} \quad (19)$$

where:

$$Diff = FiltDiff + 1 \quad (20)$$

$$Avg = 2^{FiltAvg} \quad (21)$$

FiltDiff and *FiltAvg* represent the filter coefficients which are stored as unsigned 3-bit values per filter channel in *lirFiltCoeffReg* inside the CCP of ZSSC3286. They are determined by the GUI (Configure\Filter) depending on the filter Tau selections made by the user. For a stable system, the $Diff \leq Avg$ must be ensured.

The filter Tau can be calculated by:

$$\frac{Diff}{Avg} = \alpha \approx \frac{1}{\tau_{dig}} = \frac{\Delta T}{\tau_{ana}} \quad (22)$$

$$\tau_{dig} = -\frac{1}{\ln(1 - \alpha)} \quad (23)$$

τ_{dig} is given in number of digital samples.

5.6 Third Logic Channel Combination

The potentially pre-scaled and filtered two main sensor bridge channels Ch1 and Ch2 of ZSSC3286 can be mathematically combined to calculate the output of a third logic channel Ch3. Channel Ch3 is only available in the synchronized AFE mode which is enabled via the GUI menu Configure\AFE\Sequencer\AFE Selection and Configurability\selection: "AFE1+AFE2, config equally".

The calculation result on Ch3 is available through serial interface read out only. The digital output format is signed 32-bit (two's complement), see Table 33. Outputting the Ch3 result at AOUT is possible for subtraction and ratio only. Division is readable via digital interfaces only.

The Third Logic Channel (TLC) can be configured via the GUI menu Configure\TLC menu.

Following mathematical operations are available:

- Subtraction: (Ch1 – Ch2) or (Ch2 – Ch1)
- Division: (Ch1 / Ch2) or (Ch2 / Ch1)
- Ratio: If Ch1 == Ch2 then Ch3 = 1
Else if Ch1 < Ch2 then Ch3 = Ch1 / Ch2
Else Ch3 = 2 – (Ch2 / Ch1)

Note: Division calculation can lead to math saturation, which is not suppressed by firmware.

Calibration of the sensor channels Ch1 and Ch2 must still be done independently applying the single channel calibration routines.

Table 33: Data Format of Logic Output Channel Ch3 at Serial Interface

Bit Number	31	30	29	...	24	23	22	21	...	2	1	0
Meaning, Weighting	-2^8	2^7	2^6	...	2^1	2^0	2^{-1}	2^{-2}	...	2^{-21}	2^{-22}	2^{-23}

6 Post Processing Options for Conditioned Sensor Signals

6.1 Signal Post Processing Flow Chart

Figure 32 illustrates the signal flow from conditioned data to individual output signals. All basis mathematical functions are described within the subsection 6.2, subsection 6.3, subsection 6.4, and subsection 6.5.

The signal path from AFE output data to conditioned data is described in subsection 5.2.

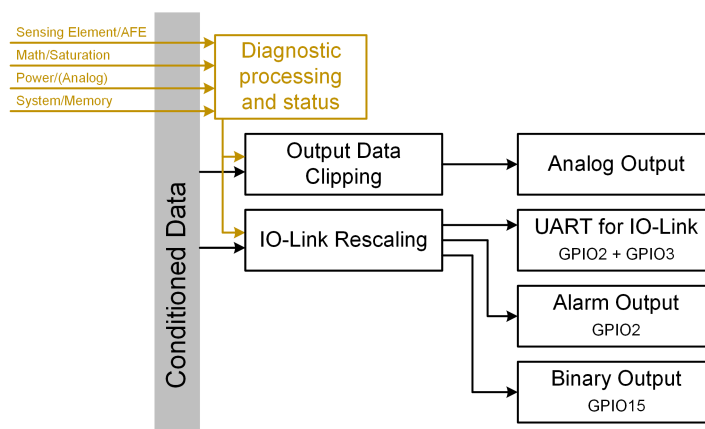


Figure 32: Sensor Signal Flow Chart from Input to Output

6.2 Output Data Clipping

The signaling of a diagnosis failure state can also be activated on the analog output AOUT via GUI tab Diagnostic\General. If the signalization of Diagnostic State at AOUT is enabled, discovered diagnostic failure states can be either mapped to the Upper or the Lower Diagnostic Range (UDR and LDR) of the output span (GUI tab Diagnostic\Sensor/AFE).

The boundaries of the upper and lower diagnostic ranges are configurable via the GUI tab Configure\Output Pre-process. They are typically set to 5% and 95% of the full scale output level but can be modified to the application needs.

To prevent false interpretation of very large or very low output signals, the conditioned data is clipped according to Figure 33 to fit into the remaining output range between UDR and LDR before it is forwarded to the AOUT output.

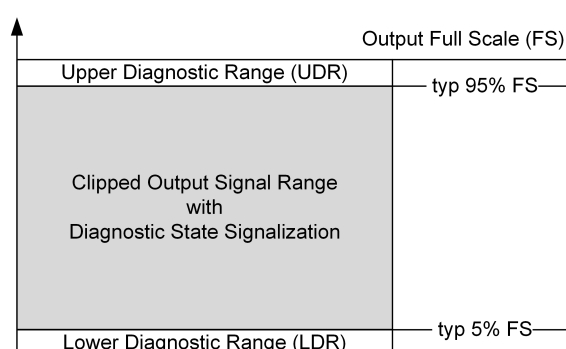


Figure 33: AOUT Output Ranges with Active Diagnostic State Signalization

- Notes:**
- There is no rescaling of the conditioned data performed at this stage. If rescaling of the conditioned data to the clipped output signal range is required, use the Bridge Output Scaling feature (see subsection 5.4) or use different target values during the SSC calibration process.
 - UDR has higher priority than LDR. Each sensor and AFE diagnostic feature described in subsection 7.1 individually assigns either a UDR or LDR. This assignment necessitates an internal prioritization process when multiple malfunctions are detected.

6.3 IO-Link Rescaling

The purpose of rescaling is to implement a simple algorithm for scaling and offsetting the 24-bit SSC corrected data so that it can be provided in SI Units as the IO-Link Smart Sensor Profil (SSP) process data requests. As described in subsection 9.2 the ZSSC3286 features SSP 4.1.1.

Therefore all 24-bit SSC corrected data is shifted to 32-bit domain and then compensated by the following compensation mathematics and Equation 24:

SSC	Corrected 24-bit sensor signal selected for IO-Link Output
$SSC_{IO-Link}$	Rescaled for IO-Link Output
$Gain_{Rescale}$	Gain term for IO-Link rescaling
$Offset_{Rescale}$	Offset term for IO-Link rescaling
$Offset_Scalar$	Offset shift for $Offset_{Rescale}$ parameter

Valid Input Range
0x0 to 0xFFFFFFFF
-(0x7FFFFFFF) to 0x7FFFFFFF
-(0x7FFFFFFF) to 0x7FFFFFFF
-(0x7FFFFFFF) to 0x7FFFFFFF
0x0 to 0xFF

The IO-Link rescaling is supported by the GUI within the tab IO-Link\SSP Scaling.

All data and compensation coefficients supplied to the formulas are required in the 32-bit data format described in Table 34, Table 35, Table 36, Table 37, and Equation 24.

Table 34: Data Format of Corrected SSC Result

Bit Number	23	22	21	20	...	2	1	0
Meaning, Weighting	2^0	2^{-1}	2^{-2}	2^{-3}	...	2^{-21}	2^{-22}	2^{-23}

Table 35: Data Format of IO-Link rescaled Output for SSP 4.1.1

Bit Number	15	14	13	12	...	2	1	0
Meaning, Weighting	$-(2^0)$	2^{-1}	2^{-2}	2^{-3}	...	2^{-13}	2^{-14}	2^{-15}

Table 36: Data Format of 32-bit $Gain_{Rescale}$ and $Offset_{Rescale}$ Coefficients

Bit Number	31	30	29	28	27	...	1	0
Meaning, Weighting	0 = positive 1 = negative	2^2	2^1	2^0	2^{-1}	...	2^{-27}	2^{-28}

Table 37: Data Format of 8-bit $Offset_Scalar$ Coefficient

Bit Number	7	6	5	4	3	2	1	0
Meaning, Weighting	2^7	2^6	2^5	2^4	2^3	2^2	2^1	2^0

$$SSC_{IO-Link} = (SSC \times 2^8 \times Gain_{Rescale}) + (Offset_{Rescale} \times Offset_{Scalar}) \quad (24)$$

6.4 Alarm Function

In SIO mode, the pin UART TxD (GPIO2) can be assigned a binary ALARM signal. This ALARM signal is output on C/Q line of IO-Link via the PHY as TxEN is always active in SIO mode.

Any Sensor Switching Channel from the IO-Link SSP can be mapped to the ALARM function. The ALARM switching behavior thus is completely dependent on IO-Link Sensor Switching Channel configuration. The ALARM signal can be inverted before being output on pin UART TxD (GPIO2).

In Cyclic Mode, the ALARM signal will be constantly updated when new measurement results are available. In Command Mode, the last switching level is kept and output stays constantly. On Fallback from IO-Link COM Mode, the ALARM signal automatically will be output if the ALARM function is enabled in CCP. On WURQ, pin UART TxD automatically switches to IO-Link COM operation.

The activation and configuration of ALARM Function is done in CCP register 0x04 – IoMisc.

6.5 Binary Output

The BINO pin (GPIO 15) can be configured as a binary output signal. This functionality is active in both SIO and IO-Link Cyclic Modes.

The switching behavior of the binary output signal is determined by the IO-Link Sensor Switching Channel configuration parameters. Additionally, the binary output signal can be inverted prior to output through the BINO pin (GPIO15).

Any Sensor Switching Channel from the IO-Link SSP can be mapped to the binary output function. The binary output switching behavior thus is completely dependent on IO-Link Sensor Switching Channel configuration. The binary output signal can be inverted before being output to pin BINO (GPIO15).

In Cyclic Mode, the binary output signal is continuously updated whenever new measurement results become available. In Command Mode, the output maintains the last switching level and remains constant.

When the binary output function is deactivated, the BINO pin (GPIO 15) enters a high-impedance state.

Configuration and activation of the binary output function are managed through the CCP register 0x04 – IoIMisc.

7 Sensor and System Diagnosis

The ZSSC3286 sensor and system diagnosis function can detect several false conditions on externally connected sensors and monitor long term gain and offset drifts of the analog front end. This makes ZSSC3286 well suited for sensing applications that require increased system reliability as well as for predictive maintenance supervision done by the host system.

7.1 Sensor and AFE Diagnostic Features

The supported sensor and AFE diagnostic features are summarized in Table 38.

Table 38: Sensor and AFE Diagnosis Functions

Monitored Input or Component	Failure Category	Failure Condition ¹
Main sensor bridge 1	INP or INN open	INP to INN resistance >125kΩ
	INP or INN shorted	INP to INN resistance <170Ω
Main sensor bridge 2	INP or INN open	INP to INN resistance >125kΩ
	INP or INN shorted	INP to INN resistance <170Ω
Temperature sensor T1	Short to Top (TOP)	T1 to TOP resistance <500Ω
	Short to Bottom (BOT)	T1 to BOT resistance <500Ω
	Open	T1 resistance >2MΩ, 500kΩ, 100kΩ
Temperature sensor T2	Short to Top (TOP)	T2 to TOP resistance <500Ω
	Short to Bottom (BOT)	T2 to BOT resistance <500Ω
	Open	T2 resistance >2MΩ, 500kΩ, 100kΩ
Temperature sensor T3	Short to Top (TOP)	T3 to TOP resistance <500Ω
	Short to Bottom (BOT)	T3 to BOT resistance <500Ω
	Open	T3 resistance >2MΩ, 500kΩ, 100kΩ

¹ Typical values. Further specifications are provided in Table 8.

For all active sensor inputs and AFEs, the checks can be enabled selectively on the GUI tab Diagnostic\Sensor/AFE.

To run single tests for sensor and AFE diagnosis features, 0xB4 command can be used which triggers a single measurement returning a pass or fail criteria as shown in Table 39. Complete update of all enabled sensor checks can be performed by the command 0xB2.

Table 39: 0xB4 - Self Diagnostic Measurement Command

Command Code	Description	Return
0xB4 followed by 0x0XYY	Self-Diagnostic Measure for AFE1 and AFE2 0x0X - AFE1: 0x00 - AFE2: 0x01 0xYY - see below	2 Bytes
0xYY	Measurement	Return
0x05	External temperature sensor, T1, check short to top	0b0000_0000_0000_000X
0x06	External temperature sensor, T1, check short to bottom	0b0000_0000_0000_000X
0x07	External temperature sensor, T1, check open	0b0000_0000_0000_000X
0x0A	External temperature sensor, T2, check short to top	0b0000_0000_0000_000X
0x0B	External temperature sensor, T2, check short to bottom	0b0000_0000_0000_000X
0x0C	External temperature sensor, T2, check open	0b0000_0000_0000_000X
0x0F	External temperature sensor, T3 (pin GUARD), check short to top	0b0000_0000_0000_000X
0x10	External temperature sensor, T3 (pin GUARD), check short to bottom	0b0000_0000_0000_000X
0x11	External temperature sensor, T3 (pin GUARD), check open	0b0000_0000_0000_000X
0x1B	Main bridge sensor connection check open	0b0000_0000_0000_000X
0x1C	Main bridge sensor connection check short	0b0000_0000_0000_000X

7.2 Sensor and System Diagnosis Status

All individual sensor and AFE diagnosis features are able to set an individual bit inside a Fault Memory.

Fault Memory is a nonvolatile memory that tracks all diagnosis bits until they are actively cleared. Clearing is possible only via ClearFaultMem (0xB9) command or a system reset. Thus before checking system diagnosis it is recommend to clear the fault memory. The fault memory can be read via RdFaultMem (0xB8) command. Reading the Fault Memory returns three words as shown in Table 40, Table 41, and Table 42. Updating the complete Fault Memory is possible via command 0xB2.

Any diagnosis listed in Table 40 and Table 41 additionally sets the Sensor Fault bit within the Status Byte. Similarly, any diagnosis listed in Table 42 sets the Saturation bit inside the Status Byte. The Status Byte is further explained in subsection 9.5.

Table 40: Fault Memory - Word 0 - Bits 31:0

Bits	Description	Bits	Description
31 : 25	Reserved	11	AFE2 sensor signal range check: INP2
24	AFE2 temperature sensor shorted connection check → T3 – BOT shorted: $R < R_{T_SHORT}$	10	AFE2 sensor leakage check: INN2 to VSS
23	AFE2 temperature sensor shorted connection check → T3 – TOP shorted: $R < R_{T_SHORT}$	9	AFE2 sensor leakage check: INP2 to VSS
22	AFE2 temperature sensor broken connection check → T3 open: $R > R_{T_OPEN}$	8	AFE2 sensor shorted connection check → INP2 – INN2 shorted: $R < R_{short}$
21	AFE2 temperature sensor shorted connection check → T2 – BOT shorted: $R < R_{T_SHORT}$	7	AFE2 sensor broken connection check → INP2 or INN2 open: $R > R_{broken}$
20	AFE2 temperature sensor shorted connection check → T2 – TOP shorted: $R < R_{T_SHORT}$	6	AFE1 sensor signal range check: INN1
19	AFE2 temperature sensor broken connection check → T2 open: $R > R_{T_OPEN}$	5	AFE1 sensor signal range check: INP1
18	AFE1 temperature sensor shorted connection check → T1 – BOT shorted: $R < R_{T_SHORT}$	4	AFE1 sensor leakage check: INN1 to VSS
17	AFE1 temperature sensor shorted connection check → T1 – TOP shorted: $R < R_{T_SHORT}$	3	AFE1 sensor leakage check: INP1 to VSS
16	AFE1 temperature sensor broken connection check → T1 open: $R > R_{T_OPEN}$	2	AFE1 sensor shorted connection check → INP1 – INN1 shorted: $R < R_{short}$
15 : 13	Reserved	1	AFE1 sensor broken connection check → INP1 or INN1 open: $R > R_{open}$
12	AFE2 sensor signal range check: INN2	0	Reserved

Table 41: Fault Memory - Word 1 - Bits 31:0

Bits	Description
31 : 4	Reserved
3	AFE2 Offset Drift
2	AFE2 Gain Drift
1	AFE1 Offset Drift
0	AFE1 Gain Drift

Table 42: Fault Memory - Word 2 - Bits 31:0

Bits	Description
31 : 6	Reserved
5	SSC calculation unit OR raw output data saturation channel 3, temperature sensor data
4	SSC calculation unit channel 3, bridge sensor data
3	SSC calculation unit OR raw output data saturation channel 2, temperature sensor data
2	SSC calculation unit OR raw output data saturation channel 2, bridge sensor data
1	SSC calculation unit OR raw output data saturation channel 1, temperature sensor data
0	SSC calculation unit OR raw output data saturation channel 1, bridge sensor data

8 Analog Output

The conditioned and post processed output data of one of the following channels can be made available as analog output signal at the Analog Output AOOUT

- Bridge Sensor Channel 1
- Bridge Sensor Channel 2
- Third Logic Channel
- Temperature Channel 1
- Temperature Channel 2
- Temperature Channel 3

Depending on the configuration of the Analog Output Driver, two different output modes, (absolute voltage output and current mode output) are supported.

Note: When implementing the analog output functionality of the ZSSC3286, the RESN pin and the "Restart the Device" command (0x8D) cannot be used for reset operations. In configurations utilizing the analog output, device reset must be performed exclusively through power cycling.

8.1 Analog Output Driver

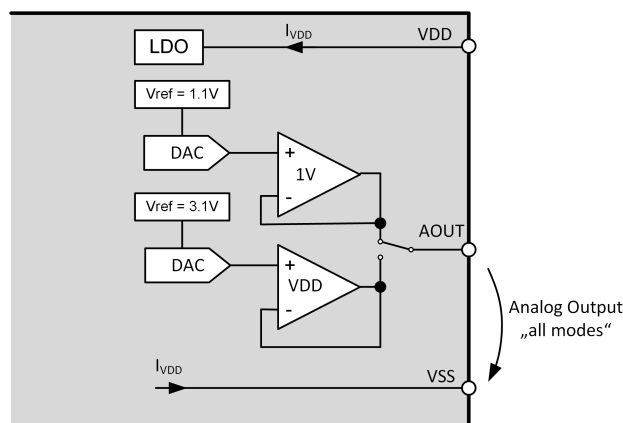


Figure 34: Block Schematic AOUT Driver

The Analog Output Driver features two distinct output buffers: one dedicated to a full-scale voltage of 1V, and another capable of handling full-scale voltages up to VDD. The following functional assignments apply:

- 1V buffer:
 - 1V absolute Voltage Mode
 - 3-wire Current Loop Mode
 - 5V absolute Voltage Mode (with external amplifier)
 - 10V absolute Voltage Mode (with external amplifier)
- VDD buffer:
 - 3V absolute Voltage Mode

Depending on the functional assignment and on the System Mode, the Analog Output Driver is set to the states shown in Table 43.

Table 43: Analog Output Driver States

System Mode	SIO Mode	IO-Link COM Mode
Disabled Mode	floating	floating
Absolute Voltage Mode	voltage following SSC value	0V
3-Wire Current Loop Mode	voltage for current following SSC value	voltage for minimum current (typ. 4mA)

8.2 Negative Voltage Generation for AOUT

To support True-0V signals on the Analog Output (AOUT), ZSSC3286 provides an option to externally supply a negative voltage rail for the AOUT buffer at VDDN. VDDN supply specifications are shown in Table 44. The external circuitry must ensure to not generate a VDDN voltage of less than -0.5V to prevent latchup conditions for the internal circuitry.

The negative VDDN voltage can also be generated by an internal charge pump circuit. Its maximum current can be adjusted.

The activation of the internal charge pump at VDDN considerably increases the power consumption of ZSSC3286 and needs to be carefully considered in applications where current consumption of the sensor device (sensing element + ZSSC3286) is a critical parameter. The VDDN charge pump can only be used for $VDD \geq 2.7V$.

If no True-0V signals are required at AOUT, the user must disable the VDDN charge pump in the GUI and directly connect VDDN with VSS on PCB level.

The charge pump function is only available for Voltage Output mode. The charge pump circuit requires an external buffer capacitor C_{VDDN} and a Schottky Diode to work properly.

Table 44: Parameter Negative Voltage for AOUT

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
VDD _{CP}	VDD operating range of internal charge pump		2.7		5.5	V
VDDN	Negative voltage supply for analog output (AOUT)	Internally generated, requires activation of VDDN charge pump		V _{ExtSchottky}		V
		Externally supplied	0	-0.3V	-0.5V	V
I _{VDDN}	Available charge pump load current	Programmable in 4 steps.			0.5	mA
					1	
					3	
					5	
I _{VDD}	Additional charge pump current consumption at VDD	0.5mA load current	0.5	4.5	5	mA
		1.0mA load current	1	9	10	
		3.0mA load current	3	15.5	17	
		5.0mA load current	5	25	30	
C _{VDDN}	Buffer capacitance at pin VDDN			1		μF
V _{FW-Schottky}	Forward voltage of external Schottky diode			0.3	0.5	V

8.3 Analog Output Configuration

8.3.1 1V Absolute Output Voltage Mode

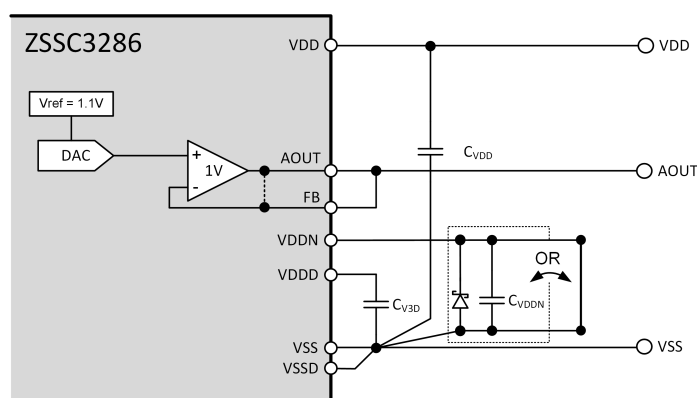


Figure 35: 1V Absolute Output Voltage Configuration at AOUT

The SSC output can be mapped to 0V to 1V voltage range with the application circuit shown in Figure 35 and activation of the 1V absolute Voltage Mode.

The applied reference voltage for the AOUT DAC is generated from an internal factory calibrated bandgap source.

8.3.2 0V to 5V or 10V Absolute Voltage Mode – External Amplification

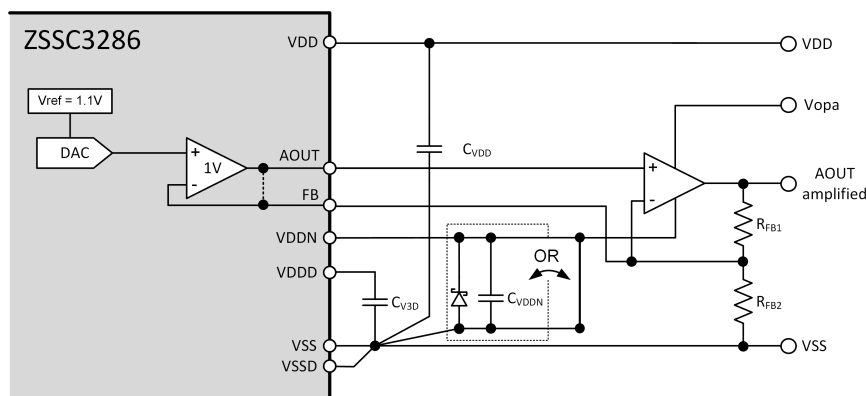


Figure 36: 5V or 10V Absolute Output Voltage Configuration at AOUT

Using an external operational amplifier, the 1V absolute voltage output can be scaled to higher voltages, for example 5V or 10V output. The application circuit is shown in Figure 36. The Feedback Pin FB should be connected to the inverting input of the external operational amplifier for better voltage accuracy. The external operational amplifier should be offset compensated. The external voltage amplification factor calculates as follows:

$$A = \frac{R_{FB1} + R_{FB2}}{R_{FB2}} \quad (25)$$

8.3.3 0V to 3V Absolute Voltage Mode

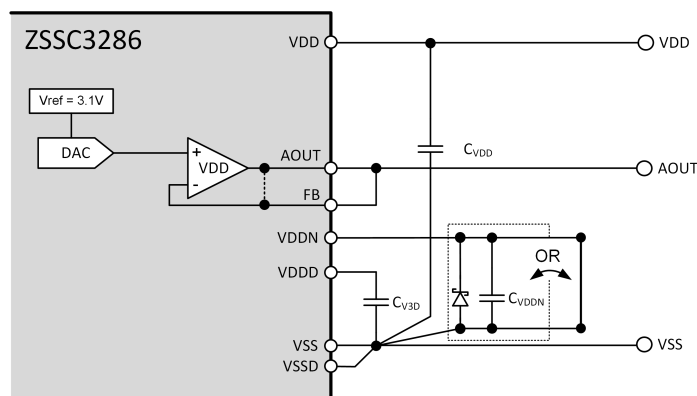


Figure 37: 3V Absolute Output Voltage Configuration at AOUT

The SSC output can be configured to map to a 0V to 3V voltage range by using the application circuit shown in Figure 37 and activation the 3V Absolute Voltage Mode. The reference voltage for the AOUT DAC is derived from an internally factory-calibrated bandgap source.

8.3.4 3-Wire Current Loop Mode

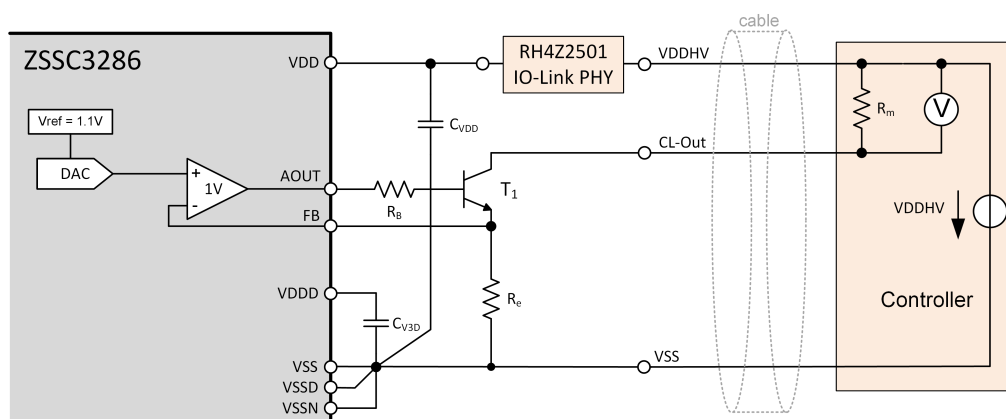


Figure 38: 3-wire NPN Current Loop Configuration at AOUT

Table 45: External Components in 3-Wire Current Loop Mode

Symbol	Parameter	Minimum	Typical	Maximum	Units
R_e	Emitter resistor		43		Ω
R_b	Base resistor		4700		Ω
T_1	Bipolar Transistor	for example BCX56-16			n.a.

The SSC output can be mapped to an input current at CL-Out in the application circuit shown in Figure 38 and by activation of the 3-Wire Current Loop Mode.

The signal current at CL-Out is typically required to range from 4mA to 20mA. The available min/max signal current range at CL-Out depends on the actual value of the external emitter resistor R_e .

To compensate for tolerances of R_e , the GUI offers a post calibration option to calibrate the current loop current to the required absolute accuracy (currently only available via I2C).

9 Digital Interfaces

9.1 Serial Interfaces

The ZSSC3286 features three digital interface protocols, shown in Table 46.

Table 46: Digital Interface Protocols

Protocol	Mode	Function
IO-Link (via UART)	Device	Sensor data read out, SSC configuration and calibration, FW Update
I2C	Slave	Sensor data read out, SSC configuration and calibration, FW Update
OWI	Master	Only for configuring the RH4Z2501 IO-Link PHY

Digital slave / device interfaces do not initiate data communication with the master system themselves but react on arbitrary received read/write requests from the master. I2C and IO-Link (COM mode) cannot be active at the same time.

After power up, the ZSSC3286 starts in SIO mode. In SIO mode, I2C communication is available. When a WURQ is received, the ZSSC3286 switches to IO-Link COM mode (refer to Figure 6).

9.2 UART (IO-Link)

The ZSSC3286 implements a UART interface for realization of IO-Link (SDCI) communication when connected to an IO-Link PHY (for example RH4Z2501, Reference 3, complying to the following standards:

- IO-Link Interface and System Specification V1.1.4 (Reference 1)
- IO-Link Common Profile Specification V1.2 (Reference 2)
- IO-Link Profile Smart Sensors 2nd Edition Specification V1.2
- IO-Link Profile BLOB Transfer & Firmware Update Specification V1.2
- IODD IO Device Description Specification V1.1.4

For connection to the PHY, the following pins are used:

- UART Rx/D
- UART Tx/D
- WU PHY
- TxEN PHY
- OWI /SS PHY

The ZSSC3286 only supports COM3 SDCI communication mode with transmission rate of 230.4kbit/s at a cycle time of 600μs. It features the Smart Sensor Profile (SSP) 4.1.1 (Profile-ID 0x0010, Process Data Structure PDI32.MSDC32_1). The ZSSC3286 supports the ISDUs listed in Table 47 to Table 68.

9.2.1 Direct Parameter Page 1

Table 47: Communication Control

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x0	0x1	MasterCommand	W	UIntegerT8 / (n.a.)		x	x
	0x2	MasterCycleTime	RW	UIntegerT8 / (0x0)	Defined by IO-Link master	x	x
	0x3	MinCycleTime	R	UIntegerT8 / (0x6)	600µs minimum cycle time for SSP 4.1.1		x
	0x3	MinCycleTime	R	UIntegerT8 / (0x16)	2200µs minimum cycle time	x	
	0x4	M-sequenceCapability	R	UIntegerT8 / (0x2B)	• ISDU support bit set • OPERATE with 2 bytes of on-request data • PRE-OPERATE with 8 bytes of on-request data		x
	0x4	M-sequenceCapability	R	UIntegerT8 / (0x2D)	• ISDU support bit set • OPERATE with 8 bytes of on-request data • PRE-OPERATE with 8 bytes of on-request data	x	
	0x5	RevisionID	RW	UIntegerT8 / (0x11)	IO-Link protocol V1.1	x	x
	0x6	ProcessDataIn	R	UIntegerT8 / (0x83)	SSP 4.1.1: • SIO-bit not set (0) • 4 bytes of Process Data SIO-bit depends on ALARM feature setting.		x
	0x6	ProcessDataIn	R	UIntegerT8 / (0x0)	No Process Data in bootloader.	x	
	0x7	ProcessDataOut	R	UIntegerT8 / (0x0)	n.a. for sensors, only for actuators	x	x

Table 48: Identification

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x0	0x8	VendorID 1 (Octet 1, MSB)	R	UIntegerT8 / (0x1)	Renesas vendor ID: 396 Note: Modifiable via CCP	x	x
	0x9	VendorID 2 (Octet 0, LSB)		UIntegerT8 / (0x8C)			
	0xA	DeviceID 1 (Octet 2, MSB)	RW	UIntegerT8 / (0x0)	Value 0x0 is not permitted. Values for Active Firmware and Bootloader shall be different. Write attempt to this parameter has no effect (compatibility mode not supported). Note: Modifiable via CCP		x
	0xB	DeviceID 2 (Octet 1)		UIntegerT8 / (0x0)			
	0xC	DeviceID 3 (Octet 0, LSB)		UIntegerT8 / (0x1)			
	0xA	DeviceID 1 (Octet 2, MSB)	RW	UIntegerT8 / (0x0)	Value 0x0 is not permitted. Values for Active Firmware and Bootloader shall be different. Write attempt to this parameter has no effect (compatibility mode not supported). Note: Modifiable via CCP	x	
	0xB	DeviceID 2 (Octet 1)		UIntegerT8 / (0x0)			
	0xC	DeviceID 3 (Octet 0, LSB)		UIntegerT8 / (0x2)			
	0xD	FunctionID 1 (MSB)	R	UIntegerT8 / (0x0)	value 0x0 by specification	x	x
	0xE	FunctionID 2 (LSB)					

9.2.2 System

Table 49: System

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x2	0x0	SystemCommand	W	UIntegerT8 / (n.a)	See supported commands in Table 50, Table 51, Table 52, Table 53 and Table 54	x	x

The following SystemCommands listed in Table 50, Table 51, Table 52, Table 53, and Table 54 are supported:

Table 50: System Commands - Block Parametrization

System Command	Name	Further info	IO-Link Operation Mode	
			Bootloader	COM Mode
0x1	ParamUploadStart			x
0x2	ParamUploadEnd			x
0x3	ParamDownloadStart			x
0x4	ParamDownloadEnd			x
0x5	ParamDownloadStore	Command used to finalize parametrization or to start Data Storage		x
0x6	ParamBreak			x

Table 51: System Commands - Device Reset

System Command	Name	Further info	IO-Link Operation Mode	
			Bootloader	COM Mode
0x80	DeviceReset		x	x
0x81	ApplicationReset	• reset of application-specific parameters • identification parameters stay unchanged • uninterrupted communication with Master		x
0x83	BackToBox	• reset of application-specific parameters and identification parameters • Device must be power cycled to reestablish communication with Master		x

Note: Commands in Table 52 are only available if Locator function is enabled in CCP.

Table 52: System Commands - Locator

System Command	Name	Further info	IO-Link Operation Mode	
			Bootloader	COM Mode
0x7E	LocatorStart	Locator sequence restarts in case this command is issued before completion of the previous locator sequence.		x
0x7F	LocatorStop	no effect if locator sequence is not in progress		x

Table 53: System Commands - Firmware Update

System Command	Name	Further info	IO-Link Operation Mode	
			Bootloader	COM Mode
0x50	BM_UNLOCK_S	Start unlocking sequence		x
0x51	BM_UNLOCK_F	Unlocking command 1		x
0x52	BM_UNLOCK_T	Unlocking command 2		x
0x53	BM_ACTIVATE	Activates new firmware	x	

Table 54: System Commands - Teach

System Command	Name	Further info	IO-Link Operation Mode	
			Bootloader	COM Mode
0x40	TeachApply			x
0x41	TeachSP1			x
0x42	TeachSP2			x
0x43	TeachSP1TP1			x
0x44	TeachSP1TP2			x
0x45	TeachSP2TP1			x
0x46	TeachSP12TP2			x
0x47	TeachSP1Start			x
0x48	TeachSP1Stop			x
0x49	TeachSP2Start			x
0x4A	TeachSP2Stop			x
0x4F	TeachCancel			x

Table 55: DataStorageIndex

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x3	0x1	DS_Command	RW	UIntegerT8 / (n.a.)			x
	0x2	State_Property	R	UIntegerT32 / (n.a.)			x
	0x3	Data_Storage_Size	R	UIntegerT32 / (n.a.)	sum of the size of all parameters plus 4 bytes per parameter		x
	0x4	Parameter_Checksum	R	UIntegerT32 / (n.a.)			x
	0x5	Index_List	R	UIntegerT8[N] / (n.a.)	$N = (\text{parameter count} \times 3) + 2$ index list contains three bytes for each ISDU parameter that is handled by the data storage mechanism: • upper 8bit of ISDU index • lower 8bit of ISDU index • subindex (usually 0x0) The index list ends with a termination marker of two zero bytes. It does not cover all parameters that are part of the parameter flash structure. The index list is fixed for any specific DeviceID.		x

Note: Table 56 column “ISDU Sub-Index” commands are not directly accessible. All parameter values within the ISDU Index are returned when sending command containing the ISDU Index with Sub-Index 0x0.

Table 56: ProfileCharacteristic

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0xD	0x1	SSP: Measuring and Switching Sensor, 1 channel	R	UIntegerT16 / (0x10)	SSP 4.1.1		x
	0x1	BLOB transfer	R	UIntegerT16 / (0x30)	BLOB transfer is used for CCP update.	x	
	0x2	Firmware Update Profile	R	UIntegerT16 / (0x31)		x	x
	0x3	Identification and Diagnosis Profile	R	UIntegerT16 / (0x4000)			x
	0x4	Two Value Teach Function Class	R	UIntegerT16 / (0x8011)			x
	0x5	Dynamic Teach Function Class	R	UIntegerT16 / (0x8012)			x
	0x6	Object Detection Function Class or Quantity Detection Function Class	R	UIntegerT16 / (0x8013) or UIntegerT16 / (0x8014)	Switching Scheme configured via CCP Note: Modifiable via CCP (default: quantity detection)		x
	0x7	Locator Function Class	R	UIntegerT16 / (0x8101)	Provides visual recognition of the Device Note: Subindex available only if Locator Function is enabled in CCP.		x

Table 57: PDInputDescriptor

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0xE	0x0	SystemCommand	W	UIntegerT8 / (n.a)	SSP 4.1.1: Describes the PDI32.MSDC32_1 layout (one field of size 32bit, starting at offset 0x0).	x	x

9.2.3 Identification

Table 58: Identification

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x10	0x0	VendorName	R	StringT48 / ("To be filled by Renesas customer")	Length of parameters may differ from specification in Reference 1 and Reference 2. Note: Modifiable via CCP.	x	x
0x11	0x0	VendorText	R	StringT48 / ("To be filled by Renesas customer")			x
0x12	0x0	ProductName	R	StringT32 / ("To be filled by Renesas customer")		x	x
0x13	0x0	ProductID	R	StringT32 / ("To be filled")			x
0x14	0x0	ProductText	R	StringT48 / ("To be filled by Renesas customer")			x
0x15	0x0	SerialNumber	R	StringT16 / ("To be filled")			x
0x16	0x0	HardwareRevision	R	StringT16 / ("To be filled")		x	x
0x17	0x0	FirmwareRevision	R	StringT32 / ([RCA version])	Contains ZSSC3286 TFW (RCA) release version. Length of parameter differs from specification in Reference 1 and Reference 2		x
0x17	0x0	FirmwareRevision	R	StringT32 / ([Bootloader version])	Contains ZSSC3286 Bootloader release version. Length of parameter differs from specification in Reference 1 and Reference 2	x	
0x18	0x0	ApplicationSpecificTag	RW	StringT32 / ("****")			x
0x19	0x0	FunctionTag	RW	StringT32 / ("****")			x
0x1A	0x0	LocationTag	RW	StringT32 / ("****")			x

9.2.4 Diagnosis

Table 59: Diagnosis

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x20	0x0	ErrorCount	R	UIntegerT16 / (0x0)			x
0x24	0x0	DeviceStatus	R	UIntegerT8 / (0x0)			x
0x25	0x0	DetailedDeviceStatus	R	OctetStringT3 / (0x0)			x

9.2.5 Process Data

Note: Table 60 column “ISDU Sub-Index” commands are not directly accessible. All parameter values within the ISDU Index are returned when sending command containing the ISDU Index with Sub-Index 0x0.

Table 60: Process Data

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x28	0x1	Measurement value	R	IntegerT16 / (0x0)			x
	0x2	Scale	R	IntegerT8 / (0x0)			x
	0x3	SSC1.1	R	BooleanT / (0x0)	SSC means Sensor Switching Channel in this occasion		x
	0x4	SSC1.2	R	BooleanT / (0x0)			x

9.2.6 BLOB Transfer and Firmware Update

Table 61: BLOB Transfer

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x31	0x0	BLOB_ID	R	IntegerT16 / (n.a.)	BLOB mechanism used for FW and CCP update volatile values used for BLOB transfer	x	
0x32	0x0	BLOB_CH	RW	variable / (n.a.)		x	

Table 62: Firmware Update

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x43BD	0x0	FW-Password	W	StringT16 / (empty string)	no password set by default Note: Modifiable via CCP		x
0x43BE	0x0	HW ID Key	R	StringT16 / ("TO BE FILLED")	Note: Modifiable via CCP	x	x
0x43BF	0x0	BootmodeStatus	R	UIntegerT8 / (0x0)			x
0x43BF	0x0	BootmodeStatus	R	UIntegerT8 / (0x1)		x	

9.2.7 ISDU - Smart Sensor Profile (SSP)

Note: Table 63 column "ISDU Sub-Index" for ISDU Index 0x3B commands are not directly accessible. All parameter values within the ISDU Index are returned when sending command containing the ISDU Index with Sub-Index 0x0.

Table 63: Teach

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x3A	0x0	TeachSelect	RW	UIntegerT8 / (0x1)			x
0x3B	0x1	State	R	UIntegerT4 / (0x0)	Teach Result		x
	0x2	Flag SP1 TP1	R	BooleanT / (0x0)			
	0x3	Flag SP1 TP2	R	BooleanT / (0x0)			
	0x4	Flag SP2 TP1	R	BooleanT / (0x0)			
	0x5	Flag SP2 TP2	R	BooleanT / (0x0)			

Table 64: SSP 4.1.1: SSC1.1 Param (Sensor Switching Channel)

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x3C	0x1	Setpoint 1	RW	IntegerT32 / (0x0)	switching channel deactivated by default		x
	0x2	Setpoint 2	RW	IntegerT32 / (0x0)			
0x3D	0x1	Logic	RW	UIntegerT8 / (0x0)	SSC1.1Config (Sensor Switching Channel)		x
	0x2	Mode	RW	UIntegerT8 / (0x0)			
	0x3	Hyst	RW	IntegerT32 / (0x0)			

Table 65: SSP 4.1.1: SSC1.2 Param (Sensor Switching Channel)

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x3E	0x1	Setpoint 1	RW	IntegerT32 / (0x0)	not used by default		x
	0x2	Setpoint 2	RW	IntegerT32 / (0x0)			
0x3F	0x1	Logic	RW	UIntegerT8 / (0x0)	SSC1.2Config		x
	0x2	Mode	RW	UIntegerT8 / (0x0)			
	0x3	Hyst	RW	IntegerT32 / (0x0)			

Note: Table 66 column “ISDU Sub-Index” commands are not directly accessible. All parameter values within the ISDU Index are returned when sending command containing the ISDU Index with Sub-Index 0x0.

Table 66: SSP 4.1.1: MDC1Descr

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x4080	0x1	LowerValue	R	IntegerT32 / (0xFFFFF8300)	sign extended to 32bit Note: Modifiable via CCP.		x
	0x2	UpperValue	R	IntegerT32 / (0x7D00)	Note: Modifiable via CCP.		
	0x3	UnitCode	R	UIntegerT16 / (0d1130)	corresponds to unit kPa by default		
	0x4	Scale	R	IntegerT8 / (0d3)	Note: Modifiable via CCP.		

9.2.8 ISDU - Vendor specific

Table 67: CCP Handling

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x200	0x0	CcpState	R	UIntegerT8 / (0x1)	0x0: CCP invalid 0x1: CCP valid	x	
0x201	0x0	CcpPassword	W	UIntegerT32 / (0xFFFFFFFF)	If password is other than 0xFFFFFFFF, it must be written before access to CCP is possible. Shall not appear in IODD. Note: Modifiable via CCP	x	x

Table 68: HiddenCommand Interpreter

ISDU Index	ISDU Sub-Index	Name	Access	Datatype / (Default Value)	Further Info	IO-Link Operation Mode	
						Bootloader	COM Mode (Active Firmware)
0x300	0x0	Hidden Command	W	OctetStringT5 / n.a.	HiddenCommand of variable length with payload. Shall not appear in IODD. See subsection 9.6 for details		x
0x301	0x0	Hidden Command Response	R	OctetString T129 / (0x0)	HiddenCommandResponse of variable length with Payload. Contains response to latest issued HiddenCommand. Shall not appear in IODD. See subsection 9.6 for details		x

9.3 I2C

ZSSC3286 supports I2C communication in Standard Mode, Fast Mode and Fast Mode+ on I2C SCL and I2C SDA pins. The I2C interface is listening to receive a telegram after system startup and whenever no IO-Link connection has been established.

I2C communication mode is selected and locked after I2C address match was passed and the first 8 bit of telegram data were received.

Table 69: I2C Interface Parameter

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
SlvAddr	I2C slave address	ZSSC3286 delivery default		0x3C		
f_{SCL} Interface	Clock	I2C Mode	0.1		1.0	MHz
D_{I2C} Duty	Cycle		33	–	50	%

Timing and protocol details of the I2C communication in Standard Mode, Fast Mode, and Fast Mode+ are given in I2C-Bus Specification, Rev.6, UM10204. SCL clock stretching is not supported by ZSSC3286.

Note: When using third party tools for configuring the ZSSC3286 via I2C, it is recommended to wait at least 100ms after power up before sending I2C commands to ensure a stable communication.

In I2C Mode, each command request follows the structure shown in Figure 39. Only the number of data bytes needed by the command must be sent. See Table 73 for available commands.

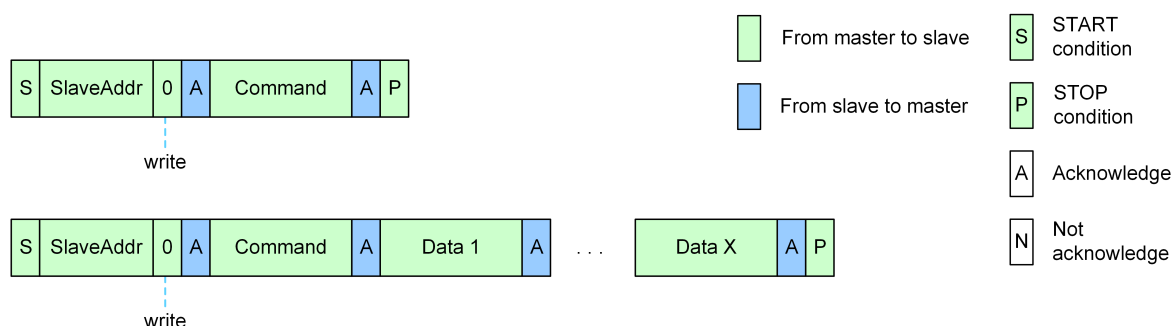


Figure 39: I2C Command Request

Different available options for a response request are shown in Figure 40.

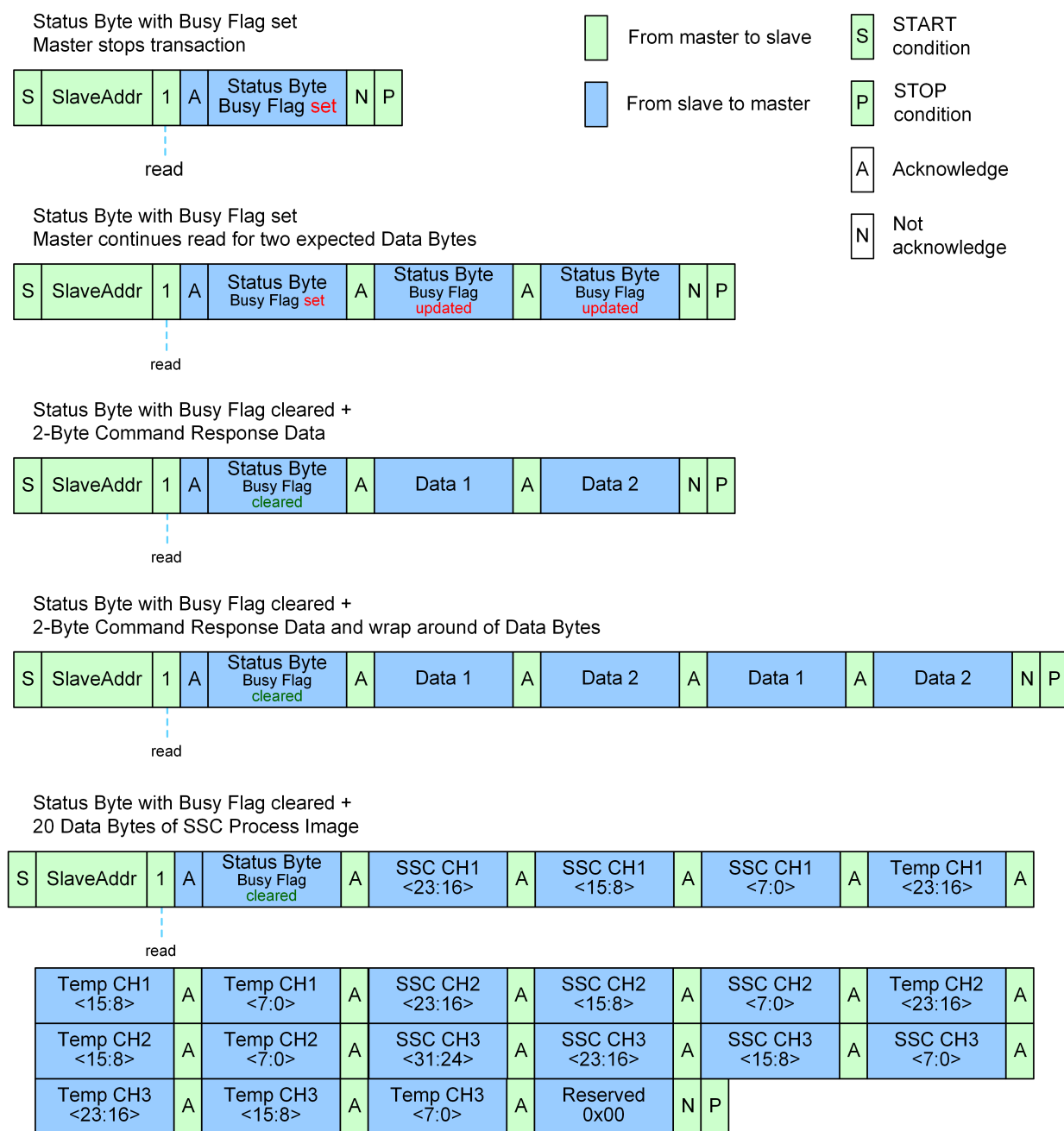


Figure 40: I2C Response Request

9.4 OWI

ZSSC3286 implements an OWI Master Interface solely used for configuring the RH4Z2501 IO-Link PHY. Register values are taken from PhyCfg1 Register. Refer to Memory Layout (section 12) for configuration options of the RH4Z2501. Refer to Application Notes (subsection 13.2 and subsection 13.3) for implementation recommendations.

The RH4Z2501 registers are configured with default values (Reference 3) in the default state of the ZSSC3286. If the IO-Link application requires different register settings for a successful connection, the configuration of the CCP register must be done in advance via I2C. Incorrect configuration may lead to inability to connect via IO-Link.

If the ZSSC3286 starts in bootloader after power up, for example if firmware update fails, the RH4Z2501 registers are not set by ZSSC3286 and contain default values. This may prevent an IO-Link connection if different values are needed. When switching from TFW (active firmware) to bootloader without a power cycle, the RH4Z2501 registers stay configured as set in CCP.

9.5 Command / Response Format

All commands follow the same command request (Table 70) format. Command response format will differ slightly for I2C and IO-Link communication according to (Table 71) and (Table 72). The number of data bytes which need to follow the command byte in the command request are returned after the Status Byte in command response, assuming the command execution was completed, is specific to the command code.

Table 70: Command Request Format

Command	Command Byte								Data Bytes
	7	6	5	4	3	2	1	0	
Valid Command	8-bit command								[Data Bytes]

Table 71: I2C Command Response Format

Command	Command Byte								Data Bytes
	7	6	5	4	3	2	1	0	
Previously received command in execution, response pending, New command not accepted, retry later	Telegram Error Flag	Power Supply OK	Busy Flag	1	SSC Mode 00: Command Mode 01: Cyclic Mode 10: Sleep Mode 11: Boot/Diagnosis Mode	Memory Error	Sensor Connection Fault	Saturation ¹	NONE
Command successfully processed				0					[Data Bytes]

¹ Cleared before each command execution except for 0xA9 (Start Command Mode).

Table 72: IO-Link Command Response Format

Command	Command Byte								Data Bytes
	7	6	5	4	3	2	1	0	
Previously received command in execution, response pending, New command not accepted, retry later	Reserved (always 0)							Saturation (in commands 0xA7; 0xB2) ¹	NONE
Command successfully processed									[Data Bytes]

¹ Cleared before each command execution except for 0xA9 (Start Command Mode).

9.6 Command Interpreter

The availability of commands in Table 73 depends on the active main operating mode (Command or Cyclic Mode) and the current connection mode (I2C or IO-Link COM).

Commands available in IO-Link are called Hidden Commands. Except for commands related to FW Update functionality, the commands are for configuration and calibration purposes and are not required in final product application.

Some commands require an additional argument for successful command execution. If an argument error or missing argument appears, the current command is not executed. For IO-Link, a failure is indicated in the error response. For I2C, no error response is sent.

The commands available using IO-Link are called Hidden Commands. It is required to send commands via ISDU index 0x300 (sub-index 0x0) for writing and index 0x301 (sub-index 0x0) for reading the response. Reading the response requires sending an ISDU write command with the respective command code before sending an ISDU read command, see subsection 9.2.

Table 73: Command List

Command Code (Byte)	Return (after Status Byte)	Description	Command Available in		
			Command Mode	Cyclic Mode	Bootloader
0x82 followed by 0xXX + 0xWW	0xWW × 4 bytes	Read configuration data in burst Reads content of Configuration and Calibration Page (CCP) in burst mode: 0xXX selects the 32-bit word in CCP which is read first 0xWW defines the number of words which is read from output memory Note: Maximum supported 0xWW is 0x20 Note: Before sending this command via IO-Link, set CCP Password must be sent via ISDU 0x201.	I2C IO-Link	IO-Link	
0x83 followed by 0xXXYY + Data bytes (multiple of 4)	1 byte (ACK / NACK)	Send CCP Update Chunk Sends a data chunk during CCP Update 0xXXYY - chunk counter - Data bytes - chunk fixed to size of 128 bytes Note: Before sending this command via IO-Link, set CCP Password must be sent via ISDU 0x201.			I2C
0x84 followed by 0xXX + 0xWW	0xWW × 4 bytes	Read device info data in burst Reads device info data in burst mode : 0xXX selects the word in InfoPage which is read first 0xWW defines the number of words which is read from output memory Note: Maximum supported 0xXX is 0x1F Note: Maximum supported 0xWW is 0x20 Note: If 0xXX + 0xWW is > 0x20, the command fails.	I2C IO-Link	IO-Link	
0x89	4 bytes (CCP version with PID)	Read expected CCP Version	I2C IO-Link	IO-Link	
0x8A	2 bytes	Read chip revision	I2C IO-Link	IO-Link	I2C
0x8B	3 bytes (Bootloader Version)	Read Bootloader Version	I2C		I2C
0x8C	n.a. (Execution jumps directly to the FW update routines)	Start Firmware Update Triggers Firmware update procedure Note: This command is designed exclusively for use with the ZSSC3286 GUI (see section 10)	I2C		
	1 byte (ACK / NACK)	Send Firmware Update Chunk Sends a data chunk during Firmware Update 0xXXYY - chunk counter - Data bytes - chunk fixed to size of 128 bytes			I2C
0x8D	n.a. (Device is immediately restarted)	Restart the Device	I2C		I2C
0x8E	3 bytes (APP Firmware Version)	Read Application Firmware Version	I2C		

Continued on next page

Table 73: Command List (Continued)

Command Code (Byte)	Return (after Status Byte)	Description	Command Available in		
			Command Mode	Cyclic Mode	Bootloader
0xA7 followed by 0xXX + 0xYY	20 bytes (Raw data)	Snapshot calibration all sensors ¹ Returns unconditioned raw sensor and temperature data of all AFE channels that are activated in CCP. Other auxiliary measurement tasks will be excluded within the execution of this command. • 0xXX minimum average count for AFE1 data • 0xYY minimum average count for AFE2 data 0xXX and 0xYY must be in range 1 to 32 (=0x20). "Minimum average count" refers to the minimum number of measurement tasks executed within a single measurement cycle. These typically include single temperature or auto-zero measurement tasks. As a result, primary measurements such as SM+ and SM- can be performed more frequently. The output data format is as follows: • Raw Data Bridge Sensor1 (24 bit) • Raw Data Temperature Channel1 (24 bit) • Raw Data Bridge Sensor2 (24 bit) • Raw Data Temperature Channel2 (24 bit) • 0x00000000 (4 bytes 0x0) (32 bit) • Raw Data Temperature Channel3 (24 bit) • 0x00 (1 byte 0x0) (8 bit)	I2C IO-Link		
0xA9	n.a.	Start Command Mode Exit Cyclic Mode and transition to Command Mode	I2C IO-Link	I2C IO-Link	
0xAB	n.a.	Start Cyclic Mode Enter Cyclic Mode based on configuration in Shadow RAM: continuous measurement cycles, SSC corrections, and automatic, continuous digital and/or analog output updates	I2C IO-Link	IO-Link	
0xB2 followed by data (0x0000 to 0xFFFF)	n.a.	Update diagnosis status Executes all activated sensor and system diagnosis checks	I2C IO-Link		
0xB3 followed by data (0x0000 to 0xFFFF)	n.a.	Direct DAC Stimulus Set the DAC output register with the data in the command and enable/output the respective analog signal through AOUT (according to the AOUT_setup)	I2C		
0xB4 followed by 0x0X + 0xYY	2 bytes	Self-diagnostic measure for AFE1 and AFE2 Parameter 0x0X: • AFE1: 0x00 • AFE2: 0x01 • Parameter 0xYY See description in Table 39	I2C IO-Link		
0xB5 followed by 0xXX 0xYY 0xYY 0xYY	n.a.	Direct linear stimulus of analog output path Stimulates the output path, linear relation between input data and pin output. Parameter 0xXX - Output Selection: • 0: reserved • 1: AOUT • 2: reserved • 3: reserved Parameter 0xYYYYYY – Output Value: • 24bit data value for output, unsigned integer (as SSC value format) • assigned output is static (the output can be switched off by the RESN pin, POR, or a change in the main operating mode) Note: The following workflow for the given command must be ensured: • Start Command Mode (0xA9) • Set Direct linear stimulus of output path (0xB5) • Reset the device	I2C IO-Link		

Continued on next page

Table 73: Command List (Continued)

Command Code (Byte)	Return (after Status Byte)	Description	Command Available in		
			Command Mode	Cyclic Mode	Bootloader
0xB8	12 bytes (diagnostic result data)	Read fault memory Responds with the detailed fault-memory status (see section 7)	I2C IO-Link	IO-Link	
0xB9	n.a.	Reset fault memory Resets the contents of the fault memory to 0x0	I2C IO-Link	IO-Link	
0xC0	n.a.	Store Factory Settings Stores parameters for restoring via System Commands "BackToBox" and "ApplicationReset"	IO-Link	IO-Link	

¹ These commands can be used to conduct a measurement without SSC conditioning, for example during the smart sensor calibration procedure. No digital correction is performed on the measurement result. The setup and configuration for the raw measurement is the content in the shadow registers that is automatically loaded from the Flash during power-on.

10 Firmware Update

ZSSC3286 offers a firmware update function via IO-Link and via I2C interface for Renesas provided code (RCA code). IO-Link uses the BLOB transfer mechanism to download the IOLFW update file to the device.

Figure 41 shows the high-level firmware update flow. After Initiating the firmware update, the device switches to Bootloader Mode. After the data is successfully transferred, the device is restarted.

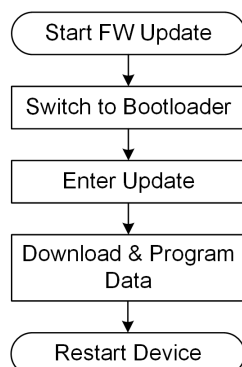


Figure 41: High-level Firmware Update Flow

The Firmware Update access via IO-Link can be protected with the firmware password (FwPassword described in subsection 12.23), as shown in Figure 42. If the FW-Password is other than an empty String, it must be entered via ISDU Index 0x43BD in IO-Link COM Mode before starting Firmware Update. Otherwise, it prevents the device from entering bootloader and an error message is sent.

Note: The Firmware Update mechanism via I2C ignores the FW-Password protection.

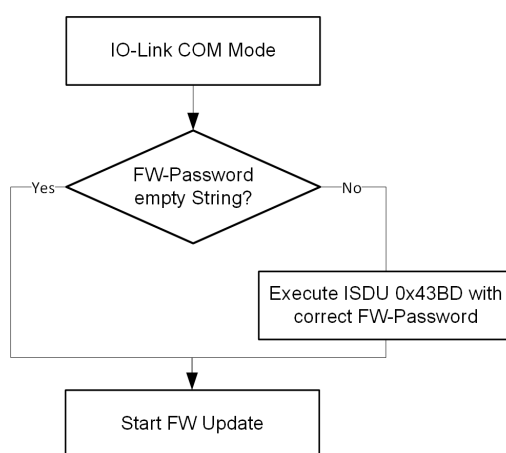


Figure 42: FW-Password Mechanism for Firmware Update

A firmware update is meant to be executed exclusively via the ZSSC3286 GUI and not by third party tools. Since a firmware update technically can be done via third party IO-Link tools, a firmware password should be set to prevent unauthorized firmware updates. It can be initiated at the FW UPDATE tab, where the respective new firmware file can be selected, and the update process can be triggered.

Note: Ensure a stable power supply during update. Power loss during update may cause corruption of the device.

11 CCP Update

ZSSC3286 offers a CCP update function via IO-Link and via I2C interface, triggered by the Write Memory button in the Renesas GUI. It uses similar update mechanisms to the Firmware Update described in section 10.

Figure 43 shows the high-level CCP update flow. After Initiating the CCP update, the device switches to Bootloader Mode. After the data is successfully transferred, the device is restarted.

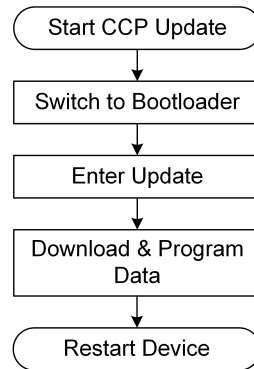


Figure 43: High-level CCP Update Flow

The CCP Update access via IO-Link can be protected with the firmware password (See subsection 12.23 for *Fw-Password* and section 10 for firmware password mechanism) and the CCP password (CcpPassword see subsubsection 12.31.1), as shown in Figure 44.

Note: If the CCP-Password is other than 0xFFFFFFFF, it must be entered via ISDU Index 0x201 in Bootloader before starting CCP update. Otherwise, it prevents the device from updating CCP via BLOB mechanism and an error message is sent.

Enter the passwords in the following order:

1. Enter FW-Password in IO-Link COM Mode
2. Enter Bootloader
3. Enter CCP-Password in Bootloader via IO-Link
4. Start CCP Update data transfer

Note: The CCP update mechanism via I2C ignores both the firmware password and the CCP password protection.

Note: The CCP-Password protects the device from reading CCP via IO-Link. The CCP-Password must be entered via ISDU 0x201 in IO-Link COM Mode prior to executing the Hidden Command 0x82 for CCP read.

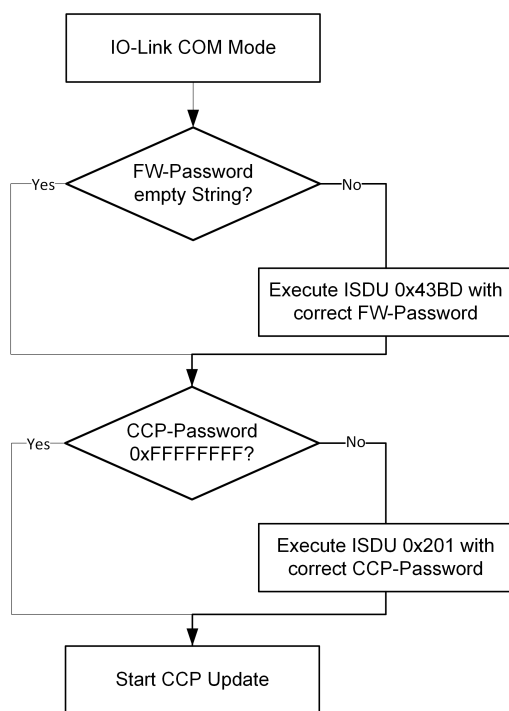


Figure 44: Password Mechanism for CCP Update

Execute the CCP update exclusively via the ZSSC3286 GUI and not by third party tools and set the FW password and CCP password to prevent an unauthorized CCP update.

Note: Ensure a stable power supply during update. Power loss during update may cause corruption of the device.

12 Configuration and Calibration Page (CCP) Memory Map

This section describes the details and usage of single bitfields of CCP memory. The bitfields have two possible access attributes:

- **Reserved:** contains data that is set by Renesas and must not be changed from its default value.
- **Read/Write:** programmable with proper Read/Write access. By default all bitfields can be assumed as read and writable. Thus an empty access information indicates an read and writable bitfield.

12.1 IO-Link Settings

12.1.1 0x01 – PhyCtrl

Address : 0x01		Register Name : PhyCtrl		Default: 0x000000FF
Bits	Access	Default	Field Name	Description
31:8		0x0	Reserved	
7:0		0xFF	PhySel	

12.1.2 0x02 – PhyCfg[0]

The CCP register PhyCfg[0] will contain configuration data for RH4Z2501 that will be transferred after power-on (reset) into the RH4Z2501 registers via OWI interface. For details of the register content refer RH4Z2501 datasheet referred in Table 3.

Address : 0x02		Register Name : PhyCfg[0]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	PhyReg4	Contains register content for <i>alarm</i> register of RH4Z2501.
23:16		0x0	PhyReg3	Contains register content for <i>comCtrl2</i> register of RH4Z2501.
15:8		0x0	PhyReg2	Contains register content for <i>comCtrl1</i> register of RH4Z2501.
7:0		0x0	PhyReg1	Contains register content for <i>comParam</i> register of RH4Z2501.

12.1.3 0x03 – PhyCfg[1]

Address : 0x03		Register Name : PhyCfg[1]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	PhyReg4	Unused
23:16		0x0	PhyReg3	Unused
15:8		0x0	PhyReg2	Unused
7:0		0x0	PhyReg1	Unused

12.1.4 0x04 – IoIMisc

Address : 0x04		Register Name : IoIMisc		Default: 0x00000006
Bits	Access	Default	Field Name	Description
31:13	Reserved	0x0		Reserved
12		0x0	BinOutInversion	Inversion of the Binary Output signal 0x0 : Disabled 0x1 : Enabled
11		0x0	BinOutSwitchingSignalNum	Sets the Sensor Switching Channel of the selected MDC for the Binary Output signal 0x0 : SSC.1 0x1 : SSC.2
10:9		0x0	BinOutSwitchingChNum	Sets the Measurement Data Channel (MDC) for the Binary Output signal 0x0 : MDC1 for SSP 4.1.1 0x1 : Reserved 0x2 : Reserved 0x3 : Reserved
8		0x0	BinOutEn	Activation of the Binary Output signal on GPIO15 0x0 : Disabled 0x1 : Enabled
7	Reserved	0x0		Reserved
6		0x0	AlarmInversion	Inversion of ALARM signal 0x0 : Disabled 0x1 : Enabled
5		0x0	AlarmSwitchingSignalNum	Sets the Sensor Switching Channel of the selected MDC for the ALARM signal 0x0 : SSC.1 0x1 : SSC.2
4:3		0x0	AlarmSwitchingChNum	Sets the Measurement Data Channel (MDC) for the ALARM signal 0x0 : MDC1 for SSP 4.1.1 0x1 : Reserved 0x2 : Reserved 0x3 : Reserved
2		0x1	LocatorEna	IO-Link Locator Function Enable - transmitted in ISDU 0xD Subindex 0x7 0x0 : Disabled 0x1 : Enabled
1		0x1	SspDetectionMode	IO-Link Detection Mode - transmitted in ISDU 0xD Subindex 0x6 0x0 : Object Detection 0x1 : Quantity Detection
0		0x0	SioPdinFlag	ALARM Function in SIO Mode 0x0 : Disabled 0x1 : Enabled

12.2 Basic AFE Setups

12.2.1 0x05 – AfeBaseCfgParam

Address : 0x05		Register Name : AfeBaseCfgParam		Default: 0x00000001
Bits	Access	Default	Field Name	Description
31:24		0x0	AfeSyncStatus	AFE1 / AFE2 Synchronization 0x0 : Asynchronous measurement 0x1 : Synchronized measurement
23:16		0x0	Afe2SmConfig	AFE2 Sequencer Configuration 0x0 : SM- and SM+ 0x1 : SM+ and AUX_AZ 0x2 : SM+ only
15:8		0x0	Afe1SmConfig	AFE1 Sequencer Configuration 0x0 : SM- and SM+ 0x1 : SM+ and AUX_AZ 0x2 : SM+ only
7:0		0x1	AfeActive	AFE Activation configuration 0x0 : None 0x1 : AFE1 only 0x2 : AFE2 only 0x3 : AFE1 and AFE2

12.2.2 0x06 – AfeBaseCfgParam.AfeDsCfg.Reg1

Address : 0x06		Register Name : AfeBaseCfgParam.AfeDsCfg.Reg1		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	ConvCnt	Feature not implemented
23:0		0x0	Thresh1	Feature not implemented

12.2.3 0x07 – AfeBaseCfgParam.AfeDsCfg.Reg2

Address : 0x07		Register Name : AfeBaseCfgParam.AfeDsCfg.Reg2		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	Thresh2	Feature not implemented

12.3 Sensor Bridge

12.3.1 0x08 – Bm1Cfg1

Address : 0x08		Register Name : Bm1Cfg1		Default: 0x04000655						
Bits	Access	Default	Field Name	Description						
31		0x0	BmType	Sensor Type 0x0 : Resistive Bridge 0x1 : Thermopile / Thermocouple						
30	Reserved	0x0	BmTestDac	Reserved						
29	Reserved	0x0	BmTest	Reserved						
28:26		0x1	BmAdcMux	ADC Input MUX Setting 0x1 : ADC input connected to PGA 0x2 : ADC input connected to input (Gain = 1, PGA bypassed)						
25:22		0x0	BmBrdgRtl	Rtl resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω						
21:18		0x0	BmBrdgRth	Rth resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω						
17:16		0x0	BmSetTime	Bridge Settling Time before ADC conversion starts 0x0 : 20μs 0x1 : 40μs 0x2 : 60μs 0x3 : 80μs						
15		0x0	BmBrdgType	Bridge Supply via TOPx, BOTx 0x0 : Voltage Source 0x1 : Resistor or Current Source						
14:12		0x0	BmAdcShift	ADC Shift V _{Shift} / V _{fs} 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875						
11:8		0x6	BmAdcReso	ADC Resolution 0x0 : 10 Bit 0x4 : 14 Bit 0x8 : 18 Bit 0xC : 22 Bit 0x1 : 11 Bit 0x5 : 15 Bit 0x9 : 19 Bit 0xD : 23 Bit 0x2 : 12 Bit 0x6 : 16 Bit 0xA : 20 Bit 0xE : 24 Bit 0x3 : 13 Bit 0x7 : 17 Bit 0xB : 21 Bit						
7		0x0	BmPgaPolarity	PGA Polarity 0x0 : Positive 0x1 : Negative						
6:4		0x5	BmPgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 0x5 : 1.6 0x7 : 1.8						
3:0		0x5	BmPgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275						

12.3.2 0x09 – Bm1Cfg2

Address : 0x09		Register Name : Bm1Cfg2		Default: 0x00000210
Bits	Access	Default	Field Name	Description
31:15	Reserved	0x0		Reserved
14		0x0	BmSetPerm	Enable permanent bridge supply. In this mode bridge supply (TOP1) will not be switched off during AUX measurement tasks 0x0 : Disabled 0x1 : Enabled Note: Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this bitfield to the GUI.
13:12		0x0	BmSetTimeMult	Selects multiplication factor for <i>Bm1Cfg1.BmSetTime</i> bridge settling time 0x0 : use selected bridge settling time (x1) 0x1 : use doubled bridge settling time (x2) 0x2 : use tripled bridge settling time (x3) 0x3 : use quadrupled bridge settling time (x4)
11:10		0x0	BmBias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current
9		0x1	BmAdcEnShift	ADC Shift & Gain ×2 Enable, activates BmAdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled
8:5		0x0	BmBrdglBias	Sensor Supply Current, applicable if BmBrdgType = 1 0x0 : Open/Off 0x4 : 40µA 0x8 : 200µA 0x1 : 5µA 0x5 : 80µA 0x9 : 500µA 0x2 : 10µA 0x6 : 100µA 0x3 : 20µA 0x7 : 160µA
4:0		0x10	BmPgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV

12.3.3 0x0A – Bm2Cfg1

Address : 0x0A		Register Name : Bm2Cfg1		Default: 0x04000656	
Bits	Access	Default	Field Name	Description	
31		0x0	BmType	Sensor Type 0x0 : Resistive Bridge 0x1 : Thermopile / Thermocouple	
30	Reserved	0x0	BmTestDac	Reserved	
29	Reserved	0x0	BmTest	Reserved	
28:26		0x1	BmAdcMux	ADC Input MUX Setting 0x1 : ADC input connected to PGA 0x2 : ADC input connected to input (Gain = 1, PGA bypassed)	
25:22		0x0	BmBrdgRtl	Rtl resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω	
21:18		0x0	BmBrdgRth	Rth resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω	
17:16		0x0	BmSetTime	Bridge Settling Time before ADC conversion starts 0x0 : 20μs 0x1 : 40μs 0x2 : 60μs 0x3 : 80μs	
15		0x0	BmBrdgType	Bridge Supply via TOPx, BOTx 0x0 : Voltage Source 0x1 : Resistor or Current Source	
14:12		0x0	BmAdcShift	ADC Shift $V_{\text{Shift}} / V_{\text{fs}}$ 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875	
11:8		0x6	BmAdcReso	ADC Resolution 0x0 : 10 Bit 0x4 : 14 Bit 0x8 : 18 Bit 0xC : 22 Bit 0x1 : 11 Bit 0x5 : 15 Bit 0x9 : 19 Bit 0xD : 23 Bit 0x2 : 12 Bit 0x6 : 16 Bit 0xA : 20 Bit 0xE : 24 Bit 0x3 : 13 Bit 0x7 : 17 Bit 0xB : 21 Bit	
7		0x0	BmPgaPolarity	PGA Polarity 0x0 : Positive 0x1 : Negative	
6:4		0x5	BmPgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 0x5 : 1.6 0x7 : 1.8	
3:0		0x6	BmPgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275	

12.3.4 0x0B – Bm2Cfg2

Address : 0x0B		Register Name : Bm2Cfg2		Default: 0x00000210
Bits	Access	Default	Field Name	Description
31:15	Reserved	0x0		Reserved
14		0x0	BmSetPerm	Enable permanent bridge supply. In this mode bridge supply (TOP2) will not be switched off during AUX measurement tasks 0x0 : Disabled 0x1 : Enabled Note: Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this bitfield to the GUI.
13:12		0x0	BmSetTimeMult	Selects multiplication factor for <i>Bm2Cfg1.BmSetTime</i> bridge settling time 0x0 : use selected bridge settling time (x1) 0x1 : use doubled bridge settling time (x2) 0x2 : use tripled bridge settling time (x3) 0x3 : use quadrupled bridge settling time (x4)
11:10		0x0	BmBias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current
9		0x1	BmAdcEnShift	ADC Shift & Gain ×2 Enable, activates BmAdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled
8:5		0x0	BmBrdglBias	Sensor Supply Current, applicable if BmBrdgType = 1 0x0 : Open/Off 0x4 : 40μA 0x8 : 200μA 0x1 : 5μA 0x5 : 80μA 0x9 : 500μA 0x2 : 10μA 0x6 : 100μA 0x3 : 20μA 0x7 : 160μA
4:0		0x10	BmPgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV

12.4 External Temperature Sensor

12.4.1 0x0C – ExtTemp1Cfg1

Address : 0x0C		Register Name : ExtTemp1Cfg1		Default: 0x0011C5F1				
Bits	Access	Default	Field Name	Description				
31:28	Reserved	0x0		Reserved				
27:24		0x0	ExtTempBrdgRtl	Rtl resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω				
23:20		0x1	ExtTempBrdgRth	Rth resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω				
19		0x0	ExtTempInput	External Temperature Sensor Input MUX 0x0 : Input connected to PGA 0x1 : Input connected to ADC				
18:15		0x3	ExtTempType	External Temperature Type 0x0 : Reserved 0x1 : Diode/NTC/PTC sink mode, internal bias 0x2 : Diode/NTC/PTC, external bias 0x3 : Diode/NTC/PTC source mode, internal bias 0x4 : Reserved 0x5 : Bridge single ended, internal bias 0x6 : Bridge single ended, external bias 0x7 : Bridge differential				
14:12		0x4	ExtTempAdcShift	ADC Shift $V_{\text{Shift}} / V_{\text{fs}}$ 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875				
11:8		0x5	ExtTempAdcReso	ADC Resolution 0x0 : 10 Bit 0x2 : 12 Bit 0x4 : 14 Bit 0x1 : 11 Bit 0x3 : 13 Bit 0x5 : 15 Bit				
7		0x1	ExtTempPgaPolarity	PGA Polarity 0x0 : Positive 0x1 : Negative				
6:4		0x7	ExtTempPgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 0x5 : 1.6 0x7 : 1.8				
3:0		0x1	ExtTempPgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275				

12.4.2 0x0D – ExtTemp1Cfg2

Address : 0x0D		Register Name : ExtTemp1Cfg2		Default: 0x00000210	
Bits	Access	Default	Field Name	Description	
31:14	Reserved	0x0		Reserved	
13:12		0x0	ExtTempSetTime	T1 Input Settling Time before ADC conversion starts 0x0 : 20μs 0x1 : 40μs 0x2 : 60μs 0x3 : 80μs	
11:10		0x0	ExtTempBias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current	
9		0x1	ExtTempAdcEnShift	ADC Shift & Gain ×2 Enable, activates BmAdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled	
8:5		0x0	ExtTempBrdglBias	Sensor Supply Current, applicable if BmBrdgType = 1 0x0 : Open/Off 0x4 : 40μA 0x8 : 200μA 0x1 : 5μA 0x5 : 80μA 0x9 : 500μA 0x2 : 10μA 0x6 : 100μA 0x3 : 20μA 0x7 : 160μA	
4:0		0x10	ExtTempPgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV	

12.4.3 0x0E – ExtTemp2Cfg1

Address : 0x0E		Register Name : ExtTemp2Cfg1		Default: 0x00118502					
Bits	Access	Default	Field Name	Description					
31:28	Reserved	0x0		Reserved					
27:24		0x0	ExtTempBrdgRtl	Rtl resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω					
23:20		0x1	ExtTempBrdgRth	Rth resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω					
19		0x0	ExtTempInput	External Temperature Sensor Input MUX 0x0 : Input connected to PGA 0x1 : Input connected to ADC					
18:15		0x3	ExtTempType	External Temperature Type 0x0 : Reserved 0x1 : Diode/NTC/PTC sink mode, internal bias 0x2 : Diode/NTC/PTC, external bias 0x3 : Diode/NTC/PTC source mode, internal bias 0x4 : Reserved 0x5 : Bridge single ended, internal bias 0x6 : Bridge single ended, external bias 0x7 : Bridge differential					
14:12		0x0	ExtTempAdcShift	ADC Shift $V_{\text{Shift}} / V_{\text{fs}}$ 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875					
11:8		0x5	ExtTempAdcReso	ADC Resolution 0x0 : 10 Bit 0x2 : 12 Bit 0x4 : 14 Bit 0x1 : 11 Bit 0x3 : 13 Bit 0x5 : 15 Bit					
7		0x0	ExtTempPgaPolarity	PGA Polarity 0x0 : Positive 0x1 : Negative					
6:4		0x0	ExtTempPgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 0x5 : 1.6 0x7 : 1.8					
3:0		0x2	ExtTempPgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275					

12.4.4 0x0F – ExtTemp2Cfg2

Address : 0x0F		Register Name : ExtTemp2Cfg2		Default: 0x00000010	
Bits	Access	Default	Field Name	Description	
31:14	Reserved	0x0		Reserved	
13:12		0x0	ExtTempSetTime	T1 Input Settling Time before ADC conversion starts 0x0 : 20μs 0x1 : 40μs 0x2 : 60μs 0x3 : 80μs	
11:10		0x0	ExtTempBias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current	
9		0x0	ExtTempAdcEnShift	ADC Shift & Gain ×2 Enable, activates BmAdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled	
8:5		0x0	ExtTempBrdglBias	Sensor Supply Current, applicable if BmBrdgType = 1 0x0 : Open/Off 0x4 : 40μA 0x8 : 200μA 0x1 : 5μA 0x5 : 80μA 0x9 : 500μA 0x2 : 10μA 0x6 : 100μA 0x3 : 20μA 0x7 : 160μA	
4:0		0x10	ExtTempPgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV	

12.4.5 0x10 – ExtTemp3Cfg1

Address : 0x10		Register Name : ExtTemp3Cfg1		Default: 0x00118502					
Bits	Access	Default	Field Name	Description					
31:28	Reserved	0x0		Reserved					
27:24		0x0	ExtTempBrdgRtl	Rtl resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω					
23:20		0x1	ExtTempBrdgRth	Rth resistor, applicable if BmBrdgType = 1 0x0 : Open 0x4 : 8000Ω 0x8 : 20000Ω 0x1 : 1333Ω 0x5 : 10000Ω 0x9 : 24000Ω 0x2 : 2000Ω 0x6 : 14000Ω 0xA : 28000Ω 0x3 : 4000Ω 0x7 : 18000Ω 0xB : 40000Ω					
19		0x0	ExtTempInput	External Temperature Sensor Input MUX 0x0 : Input connected to PGA 0x1 : Input connected to ADC					
18:15		0x3	ExtTempType	External Temperature Type 0x0 : Reserved 0x1 : Diode/NTC/PTC sink mode, internal bias 0x2 : Diode/NTC/PTC, external bias 0x3 : Diode/NTC/PTC source mode, internal bias 0x4 : Reserved 0x5 : Bridge single ended, internal bias 0x6 : Bridge single ended, external bias 0x7 : Bridge differential					
14:12		0x0	ExtTempAdcShift	ADC Shift V_{Shift} / V_{fs} 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875					
11:8		0x5	ExtTempAdcReso	ADC Resolution 0x0 : 10 Bit 0x2 : 12 Bit 0x4 : 14 Bit 0x1 : 11 Bit 0x3 : 13 Bit 0x5 : 15 Bit					
7		0x0	ExtTempPgaPolarity	PGA Polarity 0x0 : Positive 0x1 : Negative					
6:4		0x0	ExtTempPgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 0x5 : 1.6 0x7 : 1.8					
3:0		0x2	ExtTempPgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275					

12.4.6 0x11 – ExtTemp3Cfg2

Address : 0x11		Register Name : ExtTemp3Cfg2		Default: 0x00000010	
Bits	Access	Default	Field Name	Description	
31:14	Reserved	0x0		Reserved	
13:12		0x0	ExtTempSetTime	T1 Input Settling Time before ADC conversion starts 0x0 : 20μs 0x1 : 40μs 0x2 : 60μs 0x3 : 80μs	
11:10		0x0	ExtTempBias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current	
9		0x0	ExtTempAdcEnShift	ADC Shift & Gain ×2 Enable, activates BmAdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled	
8:5		0x0	ExtTempBrdglBias	Sensor Supply Current, applicable if BmBrdgType = 1 0x0 : Open/Off 0x4 : 40μA 0x8 : 200μA 0x1 : 5μA 0x5 : 80μA 0x9 : 500μA 0x2 : 10μA 0x6 : 100μA 0x3 : 20μA 0x7 : 160μA	
4:0		0x10	ExtTempPgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV	

12.4.7 0x12 – AfeRegsAna.CmConfig[0]

Address : 0x12		Register Name : AfeRegsAna.CmConfig[0]		Default: 0x00000000	
Bits	Access	Default	Field Name	Description	
31:0		0x0	CmConfig[0]		

12.4.8 0x13 – AfeRegsAna.CmConfig[1]

Address : 0x13		Register Name : AfeRegsAna.CmConfig[1]		Default: 0x00000000	
Bits	Access	Default	Field Name	Description	
31:0		0x0	CmConfig[1]		

12.4.9 0x14 – AfeRegsAna.CmConfig[2]

Address : 0x14		Register Name : AfeRegsAna.CmConfig[2]		Default: 0x00000000	
Bits	Access	Default	Field Name	Description	
31:0		0x0	CmConfig[2]		

12.5 PTAT Sensor

12.5.1 0x15 – PtatCfg1

Address : 0x15		Register Name : PtatCfg1		Default: 0x0000F533				
Bits	Access	Default	Field Name	Description				
31:18	Reserved	0x0		Reserved				
17:15		0x1	AdcMux	ADC Input MUX Setting 0x1 : ADC input connected to PGA ¹				
14:12		0x7	AdcShift	ADC Shift V _{Shift} / V _{fs} 0x0 : 0 0x2 : 0.250 0x4 : 0.500 0x6 : 0.750 0x1 : 0.125 0x3 : 0.375 0x5 : 0.625 0x7 : 0.875 ¹				
11:8		0x5	AdcReso	ADC Resolution 0x0 : 10 Bit 0x2 : 12 Bit 0x4 : 14 Bit 0x1 : 11 Bit 0x3 : 13 Bit 0x5 : 15 Bit				
7		0x0	PgaPolarity	PGA Polarity 0x0 : Positive ¹ 0x1 : Negative				
6:4		0x3	PgaGain2	PGA2 Gain 0x0 : 1.1 0x2 : 1.3 0x4 : 1.5 0x6 : 1.7 0x1 : 1.2 0x3 : 1.4 ¹ 0x5 : 1.6 0x7 : 1.8				
3:0		0x3	PgaGain1	PGA1 Gain 0x0 : 1.2 0x3 : 5.97 ¹ 0x6 : 29.6 0x9 : 76.6 0xC : 187 0x1 : 2 0x4 : 11.9 0x7 : 39.2 0xA : 112 0xD : 223 0x2 : 4 0x5 : 19.8 0x8 : 58.1 0xB : 143 0xE : 275				

¹ Renesas recommended

12.5.2 0x16 – PtatCfg2

Address : 0x16		Register Name : PtatCfg2		Default: 0x00000030	
Bits	Access	Default	Field Name	Description	
31:8	Reserved	0x0		Reserved	
7:6		0x0	Bias	AFE Bias Current Setting 0x0 : normal operation 0x3 : reduced AFE bias current	
5		0x1	AdcEnShift	ADC Shift & Gain ×2 Enable, activates AdcShift setting 0x0 : ADC Gain ×1, ADC Shift disabled 0x3 : ADC Gain ×2, ADC Shift enabled ¹	
4:0		0x10	PgaOffset	PGA Offset Shift 0x1 : -1.9mV 0x10 : 0mV ¹ 0x2 : -3.8mV 0x11 : 1.9mV 0x3 : -5.6mV 0x12 : 3.8mV 0x4 : -7.5mV 0x13 : 5.6mV 0x5 : -9.4mV 0x14 : 7.5mV 0x6 : -11.3mV 0x15 : 9.4mV 0x7 : -13.1mV 0x16 : 11.3mV 0x8 : -15.0mV 0x17 : 13.1mV 0x9 : -16.9mV 0x18 : 15.0mV 0xA : -18.8mV 0x19 : 16.9mV 0xB : -20.6mV 0x1A : 18.8mV 0xC : -22.5mV 0x1B : 20.6mV 0xD : -24.4mV 0x1C : 22.5mV 0xE : -26.2mV 0x1D : 24.4mV 0xF : -28.1mV 0x1E : 26.2mV 0x1F : 28.1mV	

¹ Renesas recommended

12.6 AFE Sequencer

12.6.1 0x17 – Afe1MeasCfg1

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x17		Register Name : Afe1MeasCfg1		Default: 0x01020036
Bits	Access	Default	Field Name	Description
31		0x0	BurstModeSlot8	AFE DMA Burst Mode Data Transfer after Slot_x 0x0 : Disabled 0x1 : Enabled
30		0x0	BurstModeSlot7	
29		0x0	BurstModeSlot6	
28		0x0	BurstModeSlot5	
27		0x0	BurstModeSlot4	
26		0x0	BurstModeSlot3	
25		0x0	BurstModeSlot2	
24		0x1	BurstModeSlot1	
23		0x0	EocIrqSlot8	End of Conversion Interrupt after Slot_x 0x0 : Disabled 0x1 : Enabled
22		0x0	EocIrqSlot7	
21		0x0	EocIrqSlot6	
20		0x0	EocIrqSlot5	
19		0x0	EocIrqSlot4	
18		0x0	EocIrqSlot3	
17		0x1	EocIrqSlot2	
16		0x0	EocIrqSlot1	
15:14		0x0	MeasTypeSlot8	AFE Measurement Type for Slot_x 0x0 : None 0x1 : SM- 0x2 : SM+ 0x3 : AUX _i
13:12		0x0	MeasTypeSlot7	
11:10		0x0	MeasTypeSlot6	
9:8		0x0	MeasTypeSlot5	
7:6		0x0	MeasTypeSlot4	
5:4		0x3	MeasTypeSlot3	
3:2		0x1	MeasTypeSlot2	
1:0		0x2	MeasTypeSlot1	

12.6.2 0x18 – Afe1MeasCfg2

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x18		Register Name : Afe1MeasCfg2		Default: 0x00000013
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:8		0x0	AuxMaxTime	Maximum lenght of AUX _i measurement slots within a sequence 0x0000 ... 0xFFFF AFE clock cycles The parameter is calculated based on the relevant timing setups of all active AUX _i measurements to secure all AUX _i measurements have the same duration. This is mainly required for synchronized AFE operation.
7:6		0x0	AuxInsertRate	Insertion Rate of an AUX _i measurement in „Accelerated main measurement“ setup 0x0 : Disabled 0x1 : Every 2nd 0x2 : Every 4th 0x3 : Every 8th
5:4		0x1	CyclicMode	Sequencer Run Mode 0x0 : Single measurement 0x1 : Continuous cyclic measurement 0x2 : Discontinuous cyclic measurement, started by trigger
3:0		0x3	NrOfSlots	Number of active measurement slots 0x0 ... 0x8 selectable

12.6.3 0x19 – Afe1MeasCfg3

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x19			Register Name : Afe1MeasCfg3		Default: 0x00000018
Bits	Access	Default	Field Name	Description	
31	Reserved	0x0	AuxMeasEnable0Aux32	Activation of Auxiliary measurements Bit 0 : Auto-zero (AZ) measurement on Sensor Bridge Bit 1 : PTAT Sensor S- Bit 2 : PTAT Sensor S+ Bit 3 : T1 Sensor S- Bit 4 : T1 Sensor S+ Bit 5 : T1 Sensor, check short to top Bit 6 : T1 Sensor, check short to bottom Bit 7 : T1 Sensor, check open Bit 8 : T2 Sensor S- Bit 9 : T2 Sensor S+ Bit 10 : T2 Sensor, check short to top Bit 11 : T2 Sensor, check short to bottom Bit 12 : T2 Sensor, check open Bit 13 : T3 Sensor S- Bit 14 : T3 Sensor S+ Bit 15 : T3 Sensor, check short to top Bit 16 : T3 Sensor, check short to bottom Bit 17 : T3 Sensor, check open Bit 27 : Bridge Sensor connection check, INP or INN open Bit 28 : Bridge Sensor connection check, INP and INN shorted All other bits reserved Bit Value Meaning 0 : Aux measurement Skipped 1 : Aux measurement Executed	
30	Reserved	0x0	AuxMeasEnable0Aux31		
29	Reserved	0x0	AuxMeasEnable0Aux30		
28	Reserved	0x0	AuxMeasEnable0Aux29		
27		0x0	AuxMeasEnable0Aux28		
26		0x0	AuxMeasEnable0Aux27		
25	Reserved	0x0	AuxMeasEnable0Aux26		
24	Reserved	0x0	AuxMeasEnable0Aux25		
23	Reserved	0x0	AuxMeasEnable0Aux24		
22	Reserved	0x0	AuxMeasEnable0Aux23		
21		0x0	AuxMeasEnable0Aux22		
20	Reserved	0x0	AuxMeasEnable0Aux21		
19	Reserved	0x0	AuxMeasEnable0Aux20		
18		0x0	AuxMeasEnable0Aux19		
17		0x0	AuxMeasEnable0Aux18		
16		0x0	AuxMeasEnable0Aux17		
15		0x0	AuxMeasEnable0Aux16		
14		0x0	AuxMeasEnable0Aux15		
13		0x0	AuxMeasEnable0Aux14		
12		0x0	AuxMeasEnable0Aux13		
11		0x0	AuxMeasEnable0Aux12		
10		0x0	AuxMeasEnable0Aux11		
9		0x0	AuxMeasEnable0Aux10		
8		0x0	AuxMeasEnable0Aux9		
7		0x0	AuxMeasEnable0Aux8		
6		0x0	AuxMeasEnable0Aux7		
5		0x0	AuxMeasEnable0Aux6		
4		0x1	AuxMeasEnable0Aux5		
3		0x1	AuxMeasEnable0Aux4		
2		0x0	AuxMeasEnable0Aux3		
1		0x0	AuxMeasEnable0Aux2		
0		0x0	AuxMeasEnable0Aux1		

12.6.4 0x1A – Afe1MeasCfg4

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x1A		Register Name : Afe1MeasCfg4		Default: 0x00400000
Bits	Access	Default	Field Name	Description
31:25	Reserved	0x0		Reserved
24		0x0	SensBufDepth	Bridge Sensor data buffer depth in SRAM 0x0 : data buffer depth 1 0x1 : data buffer depth 8
23		0x0	IrqEnableEoauxaz	End of AZ Measurement 0x0 : IRQ disabled 0x1 : IRQ enabled
22		0x1	IrqEnableEoauxseq	End of Aux Sequence 0x0 : IRQ disabled 0x1 : IRQ enabled
21		0x0	IrqEnableEoauxins	End of Inserted AUX Measurement 0x0 : IRQ disabled 0x1 : IRQ enabled
20:5		0x0	IdleTime	In continuous cyclic measurement mode idle times up to 10ms can be asserted between two sequences. IdleTime represents a number of AFE clocks – 4MHz by default
4	Reserved	0x0	AuxMeasEnable1Aux37	Reserved
3	Reserved	0x0	AuxMeasEnable1Aux36	Reserved
2	Reserved	0x0	AuxMeasEnable1Aux35	Reserved
1	Reserved	0x0	AuxMeasEnable1Aux34	Reserved
0	Reserved	0x0	AuxMeasEnable1Aux33	Reserved

12.6.5 0x1B – Afe2MeasCfg1

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x1B		Register Name : Afe2MeasCfg1		Default: 0x01020036
Bits	Access	Default	Field Name	Description
31		0x0	BurstModeSlot8	AFE DMA Burst Mode Data Transfer after Slot_x 0x0 : Disabled 0x1 : Enabled
30		0x0	BurstModeSlot7	
29		0x0	BurstModeSlot6	
28		0x0	BurstModeSlot5	
27		0x0	BurstModeSlot4	
26		0x0	BurstModeSlot3	
25		0x0	BurstModeSlot2	
24		0x1	BurstModeSlot1	
23		0x0	EocIrqSlot8	End of Conversion Interrupt after Slot_x 0x0 : Disabled 0x1 : Enabled
22		0x0	EocIrqSlot7	
21		0x0	EocIrqSlot6	
20		0x0	EocIrqSlot5	
19		0x0	EocIrqSlot4	
18		0x0	EocIrqSlot3	
17		0x1	EocIrqSlot2	
16		0x0	EocIrqSlot1	
15:14		0x0	MeasTypeSlot8	AFE Measurement Type for Slot_x 0x0 : None 0x1 : SM- 0x2 : SM+ 0x3 : AUX _i
13:12		0x0	MeasTypeSlot7	
11:10		0x0	MeasTypeSlot6	
9:8		0x0	MeasTypeSlot5	
7:6		0x0	MeasTypeSlot4	
5:4		0x3	MeasTypeSlot3	
3:2		0x1	MeasTypeSlot2	
1:0		0x2	MeasTypeSlot1	

12.6.6 0x1C – Afe2MeasCfg2

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x1C		Register Name : Afe2MeasCfg2		Default: 0x00000013
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:8		0x0	AuxMaxTime	Maximum lenght of AUX _i measurement slots within a sequence 0x0000 ... 0xFFFF AFE clock cycles The parameter is calculated based on the relevant timing setups of all active AUX _i measurements to secure all AUX _i measurements have the same duration. This is mainly required for synchronized AFE operation.
7:6		0x0	AuxInsertRate	Insertion Rate of an AUX _i measurement in „Accelerated main measurement“ setup 0x0 : Disabled 0x1 : Every 2nd 0x2 : Every 4th 0x3 : Every 8th
5:4		0x1	CyclicMode	Sequencer Run Mode 0x0 : Single measurement 0x1 : Continuous cyclic measurement 0x2 : Discontinuous cyclic measurement, started by trigger
3:0		0x3	NrOfSlots	Number of active measurement slots 0x0 ... 0x8 selectable

12.6.7 0x1D – Afe2MeasCfg3

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x1D			Register Name : Afe2MeasCfg3		Default: 0x00000000
Bits	Access	Default	Field Name	Description	
31	Reserved	0x0	AuxMeasEnable0Aux32	Activation of Auxiliary measurements Bit 0 : Auto-zero (AZ) measurement on Sensor Bridge Bit 1 : PTAT Sensor S- Bit 2 : PTAT Sensor S+ Bit 3 : T1 Sensor S- Bit 4 : T1 Sensor S+ Bit 5 : T1 Sensor, check short to top Bit 6 : T1 Sensor, check short to bottom Bit 7 : T1 Sensor, check open Bit 8 : T2 Sensor S- Bit 9 : T2 Sensor S+ Bit 10 : T2 Sensor, check short to top Bit 11 : T2 Sensor, check short to bottom Bit 12 : T2 Sensor, check open Bit 13 : T3 Sensor S- Bit 14 : T3 Sensor S+ Bit 15 : T3 Sensor, check short to top Bit 16 : T3 Sensor, check short to bottom Bit 17 : T3 Sensor, check open Bit 27 : Bridge Sensor connection check, INP or INN open Bit 28 : Bridge Sensor connection check, INP and INN shorted All other bits reserved Bit Value Meaning 0 : Aux measurement Skipped 1 : Aux measurement Executed	
30	Reserved	0x0	AuxMeasEnable0Aux31		
29	Reserved	0x0	AuxMeasEnable0Aux30		
28	Reserved	0x0	AuxMeasEnable0Aux29		
27		0x0	AuxMeasEnable0Aux28		
26		0x0	AuxMeasEnable0Aux27		
25	Reserved	0x0	AuxMeasEnable0Aux26		
24	Reserved	0x0	AuxMeasEnable0Aux25		
23	Reserved	0x0	AuxMeasEnable0Aux24		
22	Reserved	0x0	AuxMeasEnable0Aux23		
21		0x0	AuxMeasEnable0Aux22		
20	Reserved	0x0	AuxMeasEnable0Aux21		
19	Reserved	0x0	AuxMeasEnable0Aux20		
18		0x0	AuxMeasEnable0Aux19		
17		0x0	AuxMeasEnable0Aux18		
16		0x0	AuxMeasEnable0Aux17		
15		0x0	AuxMeasEnable0Aux16		
14		0x0	AuxMeasEnable0Aux15		
13		0x0	AuxMeasEnable0Aux14		
12		0x0	AuxMeasEnable0Aux13		
11		0x0	AuxMeasEnable0Aux12		
10		0x0	AuxMeasEnable0Aux11		
9		0x0	AuxMeasEnable0Aux10		
8		0x0	AuxMeasEnable0Aux9		
7		0x0	AuxMeasEnable0Aux8		
6		0x0	AuxMeasEnable0Aux7		
5		0x0	AuxMeasEnable0Aux6		
4		0x0	AuxMeasEnable0Aux5		
3		0x0	AuxMeasEnable0Aux4		
2		0x0	AuxMeasEnable0Aux3		
1		0x0	AuxMeasEnable0Aux2		
0		0x0	AuxMeasEnable0Aux1		

12.6.8 0x1E – Afe2MeasCfg4

Wrong setting of this parameter can corrupt firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x1E		Register Name : Afe2MeasCfg4		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:25	Reserved	0x0		Reserved
24		0x0	SensBufDepth	Bridge Sensor data buffer depth in SRAM 0x0 : data buffer depth 1 0x1 : data buffer depth 8
23		0x0	IrqEnableEoauxaz	End of AZ Measurement 0x0 : IRQ disabled 0x1 : IRQ enabled
22		0x0	IrqEnableEoauxseq	End of Aux Sequence 0x0 : IRQ disabled 0x1 : IRQ enabled
21		0x0	IrqEnableEoauxins	End of Inserted AUX Measurement 0x0 : IRQ disabled 0x1 : IRQ enabled
20:5		0x0	IdleTime	In continuous cyclic measurement mode idle times up to 10ms can be asserted between two sequences. IdleTime represents a number of AFE clocks – 4MHz by default
4	Reserved	0x0	AuxMeasEnable1Aux37	Reserved
3	Reserved	0x0	AuxMeasEnable1Aux36	Reserved
2	Reserved	0x0	AuxMeasEnable1Aux35	Reserved
1	Reserved	0x0	AuxMeasEnable1Aux34	Reserved
0	Reserved	0x0	AuxMeasEnable1Aux33	Reserved

12.7 Diagnosis

12.7.1 0x1F – DiagSen.DiagCfg

Address : 0x1F		Register Name : DiagSen.DiagCfg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:17	Reserved	0x0		Reserved
16:15		0x0	Extt3Range	Reference for Temp Sensor open check on T3 0x0 : 2MΩ 0x1 : 0.5MΩ 0x3 : 0.1MΩ
14		0x0	Extt3Pt100	Reference for temperature sensor short measurement on T3 0x0 : RT_SHORT < 500Ω 0x1 : RT_SHORT < 10Ω
13	Reserved	0x0		Reserved
12:11		0x0	Extt2Range	Reference for Temp Sensor open check on T2 0x0 : 2MΩ 0x1 : 0.5MΩ 0x3 : 0.1MΩ
10		0x0	Extt2Pt100	Reference for temperature sensor short measurement on T2 0x0 : RT_SHORT < 500Ω 0x1 : RT_SHORT < 10Ω
9	Reserved	0x0		Reserved
8:7		0x0	Extt1Range	Reference for Temp Sensor open check on T1 0x0 : 2MΩ 0x1 : 0.5MΩ 0x3 : 0.1MΩ
6		0x0	Extt1Pt100	Reference for temperature sensor short measurement on T1 0x0 : RT_SHORT < 500Ω 0x1 : RT_SHORT < 10Ω
5:4	Reserved	0x0	Afe2GainChkResDacVal	Reserved
3	Reserved	0x0	Afe2GainChkResDacEn	Reserved
2:1	Reserved	0x0	Afe1GainChkResDacVal	Reserved
0	Reserved	0x0	Afe1GainChkResDacEn	Reserved

12.7.2 0x20 – DiagSen.Range[0].Inp

Address : 0x20		Register Name : DiagSen.Range[0].Inp		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16		0x0	Max	
15:0		0x0	Min	

12.7.3 0x21 – DiagSen.Range[0].Inn

Address : 0x21		Register Name : DiagSen.Range[0].Inn		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16		0x0	Max	
15:0		0x0	Min	

12.7.4 0x22 – DiagSen.Range[1].Inp

Address : 0x22		Register Name : DiagSen.Range[1].Inp		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16		0x0	Max	
15:0		0x0	Min	

12.7.5 0x23 – DiagSen.Range[1].Inn

Address : 0x23		Register Name : DiagSen.Range[1].Inn		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16		0x0	Max	
15:0		0x0	Min	

12.7.6 0x24 – DiagSen.GainChk[0]

Address : 0x24		Register Name : DiagSen.GainChk[0]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16	Reserved	0x0	TolVal	Reserved
15:0	Reserved	0x0	RefVal	Reserved

12.7.7 0x25 – DiagSen.GainChk[1]

Address : 0x25		Register Name : DiagSen.GainChk[1]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16	Reserved	0x0	TolVal	Reserved
15:0	Reserved	0x0	RefVal	Reserved

12.7.8 0x26 – DiagSen.OfstChk[0]

Address : 0x26		Register Name : DiagSen.OfstChk[0]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16	Reserved	0x0	TolVal	Reserved
15:0	Reserved	0x0	RefVal	Reserved

12.7.9 0x27 – DiagSen.OfstChk[1]

Address : 0x27		Register Name : DiagSen.OfstChk[1]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16	Reserved	0x0	TolVal	Reserved
15:0	Reserved	0x0	RefVal	Reserved

12.8 Temperature Channel Mapping

12.8.1 0x28 – TempMapChId

Wrong setting of this parameter hinders firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0x28		Register Name : TempMapChId		Default: 0x00000002
Bits	Access	Default	Field Name	Description
31:9	Reserved	0x0		Reserved
8:6		0x0	Tch3	Temperature Sensor Source for Temperature Channels 1, 2, 3 0x0 : None 0x1 : PTAT 0x2 : T1 0x3 : T2 0x4 : T3
5:3		0x0	Tch2	
2:0		0x2	Tch1	

12.9 SSC Algorithm Selection

12.9.1 0x29 – MathSbrAlgoSel

Address : 0x29		Register Name : MathSbrAlgoSel		Default: 0x00000011
Bits	Access	Default	Field Name	Description
31:12	Reserved	0x0		Reserved
11		0x0	TlcChOrder	Third Logic Channel Operand Order 0x0 : CH1 op CH2 0x1 : CH2 op CH1
10:8		0x0	TlcOp	Third Logic Channel Operation 0x0 : Subtraction 0x1 : Division 0x2 : Ratio
7:4		0x1	Sensor2	SSC Algorithm for Bridge Sensors 1 & 2 0x0 : None 0x1 : SOT Parabolic 0x2 : SOT S-Shaped
3:0		0x1	Sensor1	

12.10 Analog Output (AOUT)

12.10.1 0x2A – AoutSelParam

Address : 0x2A		Register Name : AoutSelParam		Default: 0x00000001
Bits	Access	Default	Field Name	Description
31:7	Reserved	0x0		Reserved
6:3		0x0	AoutModSel	Analog Output Driver Mode 0x0 : Disabled 0x1 : Absolute Voltage Output 0-10V 0x2 : Absolute Voltage Output 0-5V 0x3 : Absolute Voltage Output 0-1V 0x6 : 3-Wire Current Loop 0x8 : Absolute Voltage Output 0-3V
2:0		0x1	SelAfeForDac	Source Signal for Analog Output 0x0 : None 0x1 : Bridge Sensor Channel 1 0x2 : Bridge Sensor Channel 2 0x3 : Third Logic Channel 0x4 : Temperature Channel 1 0x5 : Temperature Channel 2 0x6 : Temperature Channel 3

12.10.2 0x2B – AoutRegCtrl

Address : 0x2B		Register Name : AoutRegCtrl		Default: 0x0000001A
Bits	Access	Default	Field Name	Description
31:13	Reserved	0x0		Reserved
12:11		0x0	Aout5vRdacRefSel	Selection for RDAC reference voltage 0x0 : VDD 0x1 : internal 3.1V regulator voltage
10:9		0x0	AoutVddnLoad	VDDN Charge Pump Load Current 0x0 : 0.5mA 0x2 : 3mA 0x1 : 1mA 0x3 : 5mA
8		0x0	AoutVddnEn	VDDN Charge Pump for Negative Supply 0x0 : Disabled 0x1 : Enabled
7		0x0	AoutOffsetCompOff	Analog Output Offset Compensation 0x0 : Disabled 0x1 : Enabled
6:5		0x0	AoutCurrLim	Analog Driver Output Current Limitation 0x0 : 6mA 0x2 : 18mA 0x1 : 12mA 0x3 : 25mA
4		0x1	AoutFeedBackEn	Analog Driver Feedback 0x0 : External 0x1 : Internal
3		0x1	AoutHighPowEn	Analog Driver Output Power 0x0 : Low Power 0x1 : High Power
2:1		0x1	AoutMode	Analog Output Mode 0x0 : Reserved 0x1 : VOUT 5V 0x2 : VOUT 1V 0x3 : Reserved
0		0x0	AoutEn	Analog Output Activation 0x0 : Disabled 0x1 : Enabled

12.10.3 0x2C – AoutRegDiag

Address : 0x2C		Register Name : AoutRegDiag		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:4	Reserved	0x0		Reserved
3	Reserved	0x0	AoutDiagVddaEn	Reserved
2:1	Reserved	0x0	AoutDiagOutValue	Reserved
0	Reserved	0x0	AoutDiagOutEn	Reserved

12.10.4 0x2D – AoutCl3Coeff

Address : 0x2D		Register Name : AoutCl3Coeff		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:16		0x0	ClDelta	3-Wire Current Loop Calibration Coefficient CL3_Delta 16-bit Value
15:0		0x0	ClOffset	3-Wire Current Loop Calibration Coefficient CL3_Offset 16-bit Value

12.11 System Startup

12.11.1 0x2E – StartupParamCfg

Address : 0x2E		Register Name : StartupParamCfg		Default: 0x00000001
Bits	Access	Default	Field Name	Description
31:1	Reserved	0x0		Reserved
0		0x1	StartupMode	System Startup Mode 0x0 : Cyclic Mode 0x1 : Command Mode

12.12 IIR Filter

12.12.1 0x2F – IirFiltCoeffReg

Address : 0x2F		Register Name : IirFiltCoeffReg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:30	Reserved	0x0		Reserved
29:27		0x0	FiltTemp3Diff	IIR Diff Value Temperature Channel 3
26:24		0x0	FiltTemp3Avg	IIR Avg Value Temperature Channel 3
23:21		0x0	FiltTemp2Diff	IIR Diff Value Temperature Channel 2
20:18		0x0	FiltTemp2Avg	IIR Avg Value Temperature Channel 2
17:15		0x0	FiltTemp1Diff	IIR Diff Value Temperature Channel 1
14:12		0x0	FiltTemp1Avg	IIR Avg Value Temperature Channel 1
11:9		0x0	FiltSbr2Diff	IIR Diff Value Sensor Bridge 2
8:6		0x0	FiltSbr2Avg	IIR Avg Value Sensor Bridge 2
5:3		0x0	FiltSbr1Diff	IIR Diff Value Sensor Bridge 1
2:0		0x0	FiltSbr1Avg	IIR Avg Value Sensor Bridge 1

12.13 General AFE Configuration

12.13.1 0x30 – AfeConfig

Address : 0x30		Register Name : AfeConfig		Default: 0x20000000
Bits	Access	Default	Field Name	Description
31	Reserved	0x0	CLMode	Reserved
30:26	Reserved	0x8	AfeMisc	Reserved
25	Reserved	0x0	Afe2LowSpeed	Reserved
24	Reserved	0x0	CM2En	Reserved
23	Reserved	0x0	CM1En	Reserved
22	Reserved	0x0	Vdda3Brownout	Reserved
21	Reserved	0x0	Vdda2Brownout	Reserved
20	Reserved	0x0	Vdda1Brownout	Reserved
19	Reserved	0x0	CMDitheringEnable	Reserved
18	Reserved	0x0	CMNoiseInt1	Reserved
17	Reserved	0x0	TNoiseInt1	Reserved
16	Reserved	0x0	ExtTemp3NoiseInt1	Reserved
15	Reserved	0x0	ExtTemp2NoiseInt1	Reserved
14	Reserved	0x0	ExtTemp1NoiseInt1	Reserved
13	Reserved	0x0	BM2NoiseInt1	Reserved
12	Reserved	0x0	BM1NoiseInt1	Reserved
11:10	Reserved	0x0	TChpMode	Reserved
9:8	Reserved	0x0	ExtTemp3ChpMode	Reserved
7:6	Reserved	0x0	ExtTemp2ChpMode	Reserved
5:4	Reserved	0x0	ExtTemp1ChpMode	Reserved
3:2	Reserved	0x0	BM2ChpMode	Reserved
1:0	Reserved	0x0	BM1ChpMode	Reserved

12.14 Output Clipping, Diagnostic Range Assignment

12.14.1 0x31 – DiagClipOutCfg.SysDiagCfg

Address : 0x31		Register Name : DiagClipOutCfg.SysDiagCfg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:28	Reserved	0x0		Reserved
27:24	Reserved	0x0	WatchdogTimeout	Reserved
23:16	Reserved	0x0	WatchdogDisableKey	Reserved
15:2	Reserved	0x0		Reserved
1		0x0	ClipOutEn	Two-Sided Clipping to Upper and Lower Diagnostic Limit 0x0 : Disabled 0x1 : Enabled Note: Enabling this feature requires enabling ClipOutEn. Note: DiagOutEn sets the AOUT to either 0% (LDR) or 100% (UDR) Note: UDR will have higher priority than LDR if configuration mixes both failure output signalization states. Failure signalization of saturation requires enabling of any additional AFE or sensor diagnosis functions.
0		0x0	DiagOutEn	Output Signalization of Diagnostic State at AOUT 0x0 : Disabled 0x1 : Enabled Note: Clipping limits are defined in DiagClipOutCfg.ClipOutLvl register.

12.14.2 0x32 – DiagClipOutCfg.DiagOutLvl[0]

Address : 0x32		Register Name : DiagClipOutCfg.DiagOutLvl[0]		Default: 0x00007FFE
Bits	Access	Default	Field Name	Description
31:0		0x7FFE	DiagOutLvl[0]	UDR / LDR assignment of diagnostic checks Bit 1 : Br1InpOrInnOpen Bit 2 : Br1InpAndInnShorted Bit 7 : Br2InpOrInnOpen Bit 8 : Br2InpAndInnShorted Bit 16 : T1CheckOpen Bit 17 : T1CheckShortToTop Bit 18 : T1CheckShortToBottom Bit 19 : T2CheckOpen Bit 20 : T2CheckShortToTop Bit 21 : T2CheckShortToBottom Bit 22 : T3CheckOpen Bit 23 : T3CheckShortToTop Bit 24 : T3CheckShortToBottom All other bits reserved Bit Value Meaning 0 : LDR Selection 1 : UDR Selection

12.14.3 0x33 – DiagClipOutCfg.DiagOutLvl[1]

Address : 0x33		Register Name : DiagClipOutCfg.DiagOutLvl[1]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0	Reserved	0x0	DiagOutLvl[1]	Second select register for UDR / LDR assignment of diagnostic checks

12.14.4 0x34 – DiagClipOutCfg.DiagOutLvl[2]

Address : 0x34		Register Name : DiagClipOutCfg.DiagOutLvl[2]		Default: 0x0000003F
Bits	Access	Default	Field Name	Description
31:0	Reserved	0x3F	DiagOutLvl[2]	Third select register for UDR / LDR assignment of diagnostic checks

12.14.5 0x35 – DiagClipOutCfg.ClipOutLvl

Address : 0x35		Register Name : DiagClipOutCfg.ClipOutLvl		Default: 0xF3330CCC
Bits	Access	Default	Field Name	Description
31:16		0xF333	ClipOutHigh	Upper Clipping Limit 0xF333 : 95% Full Scale
15:0		0xCCC	ClipOutLow	Lower Clipping Limit 0x0CCC : 5% Full Scale

12.15 SSC Coefficients

12.15.1 0x36 – Bs1Coeff.SOffset

Address : 0x36		Register Name : Bs1Coeff.SOffset		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SOffset	Sensor offset term <i>Offset_S</i>

12.15.2 0x37 – Bs1Coeff.SGain

Address : 0x37		Register Name : Bs1Coeff.SGain		Default: 0x00200000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x200000	SGain	Sensor gain term <i>Gain_S</i>

12.15.3 0x38 – Bs1Coeff.SSot

Address : 0x38		Register Name : Bs1Coeff.SSot		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSot	Second-order term for sensor non-linearity <i>SOT_sens</i>

12.15.4 0x39 – Bs1Coeff.SShift

Address : 0x39		Register Name : Bs1Coeff.SShift		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SShift	Post-calibration term <i>SENS_shift</i>

12.15.5 0x3A – Bs1Coeff.STco

Address : 0x3A		Register Name : Bs1Coeff.STco		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	STco	Temperature coefficient offset term <i>Tco</i>

12.15.6 0x3B – Bs1Coeff.SSotTco

Address : 0x3B		Register Name : Bs1Coeff.SSotTco		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSotTco	Second-order term for Tco nonlinearity <i>SOT_tco</i>

12.15.7 0x3C – Bs1Coeff.STcg

Address : 0x3C		Register Name : Bs1Coeff.STcg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	STcg	Temperature coefficient gain term <i>Tcg</i>

12.15.8 0x3D – Bs1Coeff.SSotTcg

Address : 0x3D		Register Name : Bs1Coeff.SSotTcg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSotTcg	Second-order term for Tcg non-linearity <i>SOT_tcg</i>

12.15.9 0x3E – Bs1Coeff.OutScaleGain

Address : 0x3E		Register Name : Bs1Coeff.OutScaleGain		Default: 0x00100000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x100000	OutScaleGain	Post SSC Output Scaling Gain

12.15.10 0x3F – Bs1Coeff.OutScaleOfst

Address : 0x3F		Register Name : Bs1Coeff.OutScaleOfst		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	OutScaleOfst	Post SSC Output Scaling Offset

12.15.11 0x40 – Bs2Coeff.SOffset

Address : 0x40		Register Name : Bs2Coeff.SOffset		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SOffset	Sensor offset term <i>Offset_S</i>

12.15.12 0x41 – Bs2Coeff.SGain

Address : 0x41		Register Name : Bs2Coeff.SGain		Default: 0x00200000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x200000	SGain	Sensor gain term <i>Gain_S</i>

12.15.13 0x42 – Bs2Coeff.SSot

Address : 0x42		Register Name : Bs2Coeff.SSot		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSot	Second-order term for sensor non-linearity <i>SOT_sens</i>

12.15.14 0x43 – Bs2Coeff.SShift

Address : 0x43		Register Name : Bs2Coeff.SShift		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SShift	Post-calibration term <i>SENS_shift</i>

12.15.15 0x44 – Bs2Coeff.STco

Address : 0x44		Register Name : Bs2Coeff.STco		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	STco	Temperature coefficient offset term <i>Tco</i>

12.15.16 0x45 – Bs2Coeff.SSotTco

Address : 0x45		Register Name : Bs2Coeff.SSotTco		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSotTco	Second-order term for Tco nonlinearity <i>SOT_tco</i>

12.15.17 0x46 – Bs2Coeff.STcg

Address : 0x46		Register Name : Bs2Coeff.STcg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	STcg	Temperature coefficient gain term <i>Tcg</i>

12.15.18 0x47 – Bs2Coeff.SSotTcg

Address : 0x47		Register Name : Bs2Coeff.SSotTcg		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	SSotTcg	Second-order term for Tcg non-linearity <i>SOT_tcg</i>

12.15.19 0x48 – Bs2Coeff.OutScaleGain

Address : 0x48		Register Name : Bs2Coeff.OutScaleGain		Default: 0x00100000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x100000	OutScaleGain	Post SSC Output Scaling Gain

12.15.20 0x49 – Bs2Coeff.OutScaleOfst

Address : 0x49		Register Name : Bs2Coeff.OutScaleOfst		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	OutScaleOfst	Post SSC Output Scaling Offset

12.15.21 0x4A – Tch1Coeff.TOffset

Address : 0x4A		Register Name : Tch1Coeff.TOffset		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TOffset	Offset coefficient for temperature <i>Offset_T</i>

12.15.22 0x4B – Tch1Coeff.TGain

Address : 0x4B		Register Name : Tch1Coeff.TGain		Default: 0x00200000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x200000	TGain	Gain coefficient for temperature <i>Gain_T</i>

12.15.23 0x4C – Tch1Coeff.TSot

Address : 0x4C		Register Name : Tch1Coeff.TSot		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TSot	Second-order term for temperature source <i>SOT_T</i>

12.15.24 0x4D – Tch1Coeff.TShift

Address : 0x4D		Register Name : Tch1Coeff.TShift		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TShift	Shift for post-calibration/post-assembly offset compensation <i>T_Shift</i>

12.15.25 0x4E – Tch2Coeff.TOffset

Address : 0x4E		Register Name : Tch2Coeff.TOffset		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TOffset	Offset coefficient for temperature <i>Offset_T</i>

12.15.26 0x4F – Tch2Coeff.TGain

Address : 0x4F		Register Name : Tch2Coeff.TGain		Default: 0x00200000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x200000	TGain	Gain coefficient for temperature <i>Gain_T</i>

12.15.27 0x50 – Tch2Coeff.TSot

Address : 0x50		Register Name : Tch2Coeff.TSot		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TSot	Second-order term for temperature source <i>SOT_T</i>

12.15.28 0x51 – Tch2Coeff.TShift

Address : 0x51		Register Name : Tch2Coeff.TShift		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TShift	Shift for post-calibration/post-assembly offset compensation <i>T_Shift</i>

12.15.29 0x52 – Tch3Coeff.TOffset

Address : 0x52		Register Name : Tch3Coeff.TOffset		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TOffset	Offset coefficient for temperature <i>Offset_T</i>

12.15.30 0x53 – Tch3Coeff.TGain

Address : 0x53		Register Name : Tch3Coeff.TGain		Default: 0x00200000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x200000	TGain	Gain coefficient for temperature <i>Gain_T</i>

12.15.31 0x54 – Tch3Coeff.TSot

Address : 0x54		Register Name : Tch3Coeff.TSot		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TSot	Second-order term for temperature source <i>SOT_T</i>

12.15.32 0x55 – Tch3Coeff.TShift

Address : 0x55		Register Name : Tch3Coeff.TShift		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24	Reserved	0x0		Reserved
23:0		0x0	TShift	Shift for post-calibration/post-assembly offset compensation <i>T_Shift</i>

12.16 CCP CRC**12.16.1 0x7F – CrcCcp0**

Address : 0x7F		Register Name : CrcCcp0		Default: 0xBF24211B
Bits	Access	Default	Field Name	Description
31:0		0xBF24211B	CrcCcp0	

12.17 IO-Link – SI Scaling**12.17.1 0xA0 – SiScaling.Coeff[0].Offset**

Address : 0xA0		Register Name : SiScaling.Coeff[0].Offset		Default: 0xFFFF8300
Bits	Access	Default	Field Name	Description
31:0		0xFFFF8300	Offset	SI Scaling Offset for MDC1

12.17.2 0xA1 – SiScaling.Coeff[0].Gain

Address : 0xA1		Register Name : SiScaling.Coeff[0].Gain		Default: 0x0000FA0
Bits	Access	Default	Field Name	Description
31:0		0xFA0	Gain	SI Scaling Gain for MDC1

12.17.3 0xA2 – SiScaling.Coeff[1].Offset

Address : 0xA2		Register Name : SiScaling.Coeff[1].Offset		Default: 0xFFFF8000
Bits	Access	Default	Field Name	Description
31:0		0xFFFF8000	Offset	SI Scaling Offset for MDC2 (n.a. for SSP 4.1.1)

12.17.4 0xA3 – SiScaling.Coeff[1].Gain

Address : 0xA3		Register Name : SiScaling.Coeff[1].Gain		Default: 0x00001000
Bits	Access	Default	Field Name	Description
31:0		0x1000	Gain	SI Scaling Gain for MDC2 (n.a. for SSP 4.1.1)

12.17.5 0xA4 – SiScaling.Coeff[2].Offset

Address : 0xA4		Register Name : SiScaling.Coeff[2].Offset		Default: 0xFFFF8000
Bits	Access	Default	Field Name	Description
31:0		0xFFFF8000	Offset	SI Scaling Offset for MDC3 (n.a. for SSP 4.1.1)

12.17.6 0xA5 – SiScaling.Coeff[2].Gain

Address : 0xA5		Register Name : SiScaling.Coeff[2].Gain		Default: 0x00001000
Bits	Access	Default	Field Name	Description
31:0		0x1000	Gain	SI Scaling Gain for MDC3 (n.a. for SSP 4.1.1)

12.17.7 0xA6 – SiScaling.Coeff[3].Offset

Address : 0xA6		Register Name : SiScaling.Coeff[3].Offset		Default: 0xFFFF8000
Bits	Access	Default	Field Name	Description
31:0		0xFFFF8000	Offset	SI Scaling Offset for MDC4 (n.a. for SSP 4.1.1)

12.17.8 0xA7 – SiScaling.Coeff[3].Gain

Address : 0xA7		Register Name : SiScaling.Coeff[3].Gain		Default: 0x00001000
Bits	Access	Default	Field Name	Description
31:0		0x1000	Gain	SI Scaling Gain for MDC4 (n.a. for SSP 4.1.1)

12.17.9 0xA8 – SiScaling.OffsetScaler

Address : 0xA8		Register Name : SiScaling.OffsetScaler		Default: 0x01010101
Bits	Access	Default	Field Name	Description
31:24		0x1	Ch4	SI Scaling Offset Scaler for MDC4 (n.a. for SSP 4.1.1)
23:16		0x1	Ch3	SI Scaling Offset Scaler for MDC3 (n.a. for SSP 4.1.1)
15:8		0x1	Ch2	SI Scaling Offset Scaler for MDC2 (n.a. for SSP 4.1.1)
7:0		0x1	Ch1	SI Scaling Offset Scaler for MDC1 (n.a. for SSP 4.1.1)

12.18 IO-Link – Measurement Data Channel (MDC) Description

12.18.1 0xA9 – MdcDescr[0].LowerValue

Address : 0xA9		Register Name : MdcDescr[0].LowerValue		Default: 0xFFFF8300
Bits	Access	Default	Field Name	Description
31:0		0xFFFF8300	LowerValue	Lower value of measurement range for MDC1 - transmitted in ISDU 0x4080 Subindex 0x1

12.18.2 0xAA – MdcDescr[0].UpperValue

Address : 0xAA		Register Name : MdcDescr[0].UpperValue		Default: 0x00007D00
Bits	Access	Default	Field Name	Description
31:0		0x7D00	UpperValue	Upper value of measurement range for MDC1 - transmitted in ISDU 0x4080 Subindex 0x2

12.18.3 0xAB – MdcDescr[0].Reg1

Address : 0xAB		Register Name : MdcDescr[0].Reg1		Default: 0x0003046A
Bits	Access	Default	Field Name	Description
31:24		0x0	Unused	Unused
23:16		0x3	Scale	Range shifting (10scale) for MDC1 - transmitted in ISDU 0x4080 Subindex 0x4
15:0		0x46A	UnitCode	Unit Code (SI unit) for MDC1 - transmitted in ISDU 0x4080 Subindex 0x3

12.18.4 0xAC – MdcDescr[1].LowerValue

Address : 0xAC		Register Name : MdcDescr[1].LowerValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	LowerValue	Lower value of measurement range for MDC2 (n.a. for SSP 4.1.1)

12.18.5 0xAD – MdcDescr[1].UpperValue

Address : 0xAD		Register Name : MdcDescr[1].UpperValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	UpperValue	Upper value of measurement range for MDC2 (n.a. for SSP 4.1.1)

12.18.6 0xAE – MdcDescr[1].Reg1

Address : 0xAE		Register Name : MdcDescr[1].Reg1		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	Unused	Unused (n.a. for SSP 4.1.1)
23:16		0x0	Scale	Range shifting (10scale) for MDC2 (n.a. for SSP 4.1.1)
15:0		0x0	UnitCode	Unit Code (SI unit) for MDC2 (n.a. for SSP 4.1.1)

12.18.7 0xAF – MdcDescr[2].LowerValue

Address : 0xAF		Register Name : MdcDescr[2].LowerValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	LowerValue	Lower value of measurement range for MDC3 (n.a. for SSP 4.1.1)

12.18.8 0xB0 – MdcDescr[2].UpperValue

Address : 0xB0		Register Name : MdcDescr[2].UpperValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	UpperValue	Upper value of measurement range for MDC3 (n.a. for SSP 4.1.1)

12.18.9 0xB1 – MdcDescr[2].Reg1

Address : 0xB1		Register Name : MdcDescr[2].Reg1		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	Unused	Unused (n.a. for SSP 4.1.1)
23:16		0x0	Scale	Range shifting (10scale) for MDC3 (n.a. for SSP 4.1.1)
15:0		0x0	UnitCode	Unit Code (SI unit) for MDC3 (n.a. for SSP 4.1.1)

12.18.10 0xB2 – MdcDescr[3].LowerValue

Address : 0xB2		Register Name : MdcDescr[3].LowerValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	LowerValue	Lower value of measurement range for MDC4 (n.a. for SSP 4.1.1)

12.18.11 0xB3 – MdcDescr[3].UpperValue

Address : 0xB3		Register Name : MdcDescr[3].UpperValue		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	UpperValue	Upper value of measurement range for MDC4 (n.a. for SSP 4.1.1)

12.18.12 0xB4 – MdcDescr[3].Reg1

Address : 0xB4		Register Name : MdcDescr[3].Reg1		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:24		0x0	Unused	Unused (n.a. for SSP 4.1.1)
23:16		0x0	Scale	Range shifting (10scale) for MDC4 (n.a. for SSP 4.1.1)
15:0		0x0	UnitCode	Unit Code (SI unit) for MDC4 (n.a. for SSP 4.1.1)

12.19 IO-Link – SSP Channel Mapping**12.19.1 0xB5 – SspChMap**

Address : 0xB5		Register Name : SspChMap		Default: 0x00006660
Bits	Access	Default	Field Name	Description
31:16	Reserved	0x0		Reserved
15:12		0x6	Ch4	Mapped Data Channel for MDC4 (n.a. for SSP 4.1.1)
11:8		0x6	Ch3	Mapped Data Channel for MDC3 (n.a. for SSP 4.1.1)
7:4		0x6	Ch2	Mapped Data Channel for MDC2 (n.a. for SSP 4.1.1)
3:0		0x0	Ch1	Mapped Data Channel for MDC1 0x0 : Sensor Channel 1 0x1 : Sensor Channel 2 0x2 : Third Logic Channel 3 0x3 : Temperature Channel 1 0x4 : Temperature Channel 2 0x5 : Temperature Channel 3

12.20 IO-Link – Vendor Text**12.20.1 0xB6 – VendorText[0]**

Address : 0xB6		Register Name : VendorText[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	VendorText[0]	Vendor Name - transmitted in ISDU 0x11 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.20.2 0xB7 – VendorText[1]

Address : 0xB7		Register Name : VendorText[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	VendorText[1]	Vendor Name - transmitted in ISDU 0x11 - characters 7, 6, 5, 4

12.20.3 0xB8 – VendorText[2]

Address : 0xB8		Register Name : VendorText[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	VendorText[2]	Vendor Name - transmitted in ISDU 0x11 - characters 11, 10, 9, 8

12.20.4 0xB9 – VendorText[3]

Address : 0xB9		Register Name : VendorText[3]		Default: 0x20796220
Bits	Access	Default	Field Name	Description
31:0		0x20796220	VendorText[3]	Vendor Name - transmitted in ISDU 0x11 - characters 15, 14, 13, 12

12.20.5 0xBA – VendorText[4]

Address : 0xBA		Register Name : VendorText[4]		Default: 0x656E6552
Bits	Access	Default	Field Name	Description
31:0		0x656E6552	VendorText[4]	Vendor Name - transmitted in ISDU 0x11 - characters 19, 18, 17, 16

12.20.6 0xBB – VendorText[5]

Address : 0xBB		Register Name : VendorText[5]		Default: 0x20736173
Bits	Access	Default	Field Name	Description
31:0		0x20736173	VendorText[5]	Vendor Name - transmitted in ISDU 0x11 - characters 23, 22, 21, 20

12.20.7 0xBC – VendorText[6]

Address : 0xBC		Register Name : VendorText[6]		Default: 0x74737563
Bits	Access	Default	Field Name	Description
31:0		0x74737563	VendorText[6]	Vendor Name - transmitted in ISDU 0x11 - characters 27, 26, 25, 24

12.20.8 0xBD – VendorText[7]

Address : 0xBD		Register Name : VendorText[7]		Default: 0x72656D6F
Bits	Access	Default	Field Name	Description
31:0		0x72656D6F	VendorText[7]	Vendor Name - transmitted in ISDU 0x11 - characters 31, 30, 29, 28

12.20.9 0xBE – VendorText[8]

Address : 0xBE		Register Name : VendorText[8]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorText[8]	Vendor Name - transmitted in ISDU 0x11 - characters 35, 34, 33, 32

12.20.10 0xBF – VendorText[9]

Address : 0xBF		Register Name : VendorText[9]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorText[9]	Vendor Name - transmitted in ISDU 0x11 - characters 39, 38, 37, 36

12.20.11 0xC0 – VendorText[10]

Address : 0xC0		Register Name : VendorText[10]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorText[10]	Vendor Name - transmitted in ISDU 0x11 - characters 43, 42, 41, 40

12.20.12 0xC1 – VendorText[11]

Address : 0xC1		Register Name : VendorText[11]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorText[11]	Vendor Name - transmitted in ISDU 0x11 - characters 47, 46, 45, 44

12.21 IO-Link – Product Text**12.21.1 0xC2 – ProductText[0]**

Address : 0xC2		Register Name : ProductText[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	ProductText[0]	Product Text - transmitted in ISDU 0x14 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.21.2 0xC3 – ProductText[1]

Address : 0xC3		Register Name : ProductText[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	ProductText[1]	Product Text - transmitted in ISDU 0x14 - characters 7, 6, 5, 4

12.21.3 0xC4 – ProductText[2]

Address : 0xC4		Register Name : ProductText[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	ProductText[2]	Product Text - transmitted in ISDU 0x14 - characters 11, 10, 9, 8

12.21.4 0xC5 – ProductText[3]

Address : 0xC5		Register Name : ProductText[3]		Default: 0x20796220
Bits	Access	Default	Field Name	Description
31:0		0x20796220	ProductText[3]	Product Text - transmitted in ISDU 0x14 - characters 15, 14, 13, 12

12.21.5 0xC6 – ProductText[4]

Address : 0xC6		Register Name : ProductText[4]		Default: 0x656E6552
Bits	Access	Default	Field Name	Description
31:0		0x656E6552	ProductText[4]	Product Text - transmitted in ISDU 0x14 - characters 19, 18, 17, 16

12.21.6 0xC7 – ProductText[5]

Address : 0xC7		Register Name : ProductText[5]		Default: 0x20736173
Bits	Access	Default	Field Name	Description
31:0		0x20736173	ProductText[5]	Product Text - transmitted in ISDU 0x14 - characters 23, 22, 21, 20

12.21.7 0xC8 – ProductText[6]

Address : 0xC8		Register Name : ProductText[6]		Default: 0x74737563
Bits	Access	Default	Field Name	Description
31:0		0x74737563	ProductText[6]	Product Text - transmitted in ISDU 0x14 - characters 27, 26, 25, 24

12.21.8 0xC9 – ProductText[7]

Address : 0xC9		Register Name : ProductText[7]		Default: 0x72656D6F
Bits	Access	Default	Field Name	Description
31:0		0x72656D6F	ProductText[7]	Product Text - transmitted in ISDU 0x14 - characters 31, 30, 29, 28

12.21.9 0xCA – ProductText[8]

Address : 0xCA		Register Name : ProductText[8]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductText[8]	Product Text - transmitted in ISDU 0x14 - characters 35, 34, 33, 32

12.21.10 0xCB – ProductText[9]

Address : 0xCB		Register Name : ProductText[9]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductText[9]	Product Text - transmitted in ISDU 0x14 - characters 39, 38, 37, 36

12.21.11 0xCC – ProductText[10]

Address : 0xCC		Register Name : ProductText[10]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductText[10]	Product Text - transmitted in ISDU 0x14 - characters 43, 42, 41, 40

12.21.12 0xCD – ProductText[11]

Address : 0xCD		Register Name : ProductText[11]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductText[11]	Product Text - transmitted in ISDU 0x14 - characters 47, 46, 45, 44

12.22 IO-Link – Serial Number**12.22.1 0xCE – SerialNumber[0]**

Address : 0xCE		Register Name : SerialNumber[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	SerialNumber[0]	Serial Number - transmitted in ISDU 0x15 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.22.2 0xCF – SerialNumber[1]

Address : 0xCF		Register Name : SerialNumber[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	SerialNumber[1]	Serial Number - transmitted in ISDU 0x15 - characters 7, 6, 5, 4

12.22.3 0xD0 – SerialNumber[2]

Address : 0xD0		Register Name : SerialNumber[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	SerialNumber[2]	Serial Number - transmitted in ISDU 0x15 - characters 11, 10, 9, 8

12.22.4 0xD1 – SerialNumber[3]

Address : 0xD1		Register Name : SerialNumber[3]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	SerialNumber[3]	Serial Number - transmitted in ISDU 0x15 - characters 15, 14, 13, 12

12.23 IO-Link – Firmware Password

12.23.1 0xD2 – FwPassword[0]

If FW Password is other than empty String, the FW password function becomes effective.

Address : 0xD2		Register Name : FwPassword[0]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	FwPassword[0]	Firmware Password - transmitted in ISDU 0x43BD - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 character 0

12.23.2 0xD3 – FwPassword[1]

Address : 0xD3		Register Name : FwPassword[1]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	FwPassword[1]	Firmware Password - transmitted in ISDU 0x43BD - characters 11, 10, 9, 8

12.23.3 0xD4 – FwPassword[2]

Address : 0xD4		Register Name : FwPassword[2]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	FwPassword[2]	Firmware Password - transmitted in ISDU 0x43BD - characters 15, 14, 13, 12

12.23.4 0xD5 – FwPassword[3]

Address : 0xD5		Register Name : FwPassword[3]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	FwPassword[3]	Firmware Password - transmitted in ISDU 0x43BD - characters 19, 18, 17, 16

12.24 IO-Link – Device IDs

12.24.1 0xD6 – Deviceld

Value 0x0 not allowed.

Address : 0xD6		Register Name : Deviceld		Default: 0x00000001
Bits	Access	Default	Field Name	Description
31:0		0x1	Deviceld	Device ID in active Firmware - transmitted in ISDU 0xA, 0xB, 0xC - LSB aligned

12.24.2 0xD7 – BootloaderDeviceld

Value 0x0 not allowed.

Address : 0xD7		Register Name : BootloaderDeviceld		Default: 0x00000002
Bits	Access	Default	Field Name	Description
31:0		0x2	BootloaderDeviceld	Device ID in Bootloader - transmitted in ISDU 0xA, 0xB, 0xC - LSB aligned

12.25 IO-Link – Vendor ID

12.25.1 0xD8 – VendorId

Address : 0xD8		Register Name : VendorId		Default: 0x000018C
Bits	Access	Default	Field Name	Description
31:0		0x18C	VendorId	Vendor ID - transmitted in ISDU 0x8 and 0x9 - LSB aligned

12.26 IO-Link – Vendor Name

12.26.1 0xD9 – VendorName[0]

Address : 0xD9		Register Name : VendorName[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	VendorName[0]	Vendor Name - transmitted in ISDU 0x10 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.26.2 0xDA – VendorName[1]

Address : 0xDA		Register Name : VendorName[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	VendorName[1]	Vendor Name - transmitted in ISDU 0x10 - characters 7, 6, 5, 4

12.26.3 0xDB – VendorName[2]

Address : 0xDB		Register Name : VendorName[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	VendorName[2]	Vendor Name - transmitted in ISDU 0x10 - characters 11, 10, 9, 8

12.26.4 0xDC – VendorName[3]

Address : 0xDC		Register Name : VendorName[3]		Default: 0x20796220
Bits	Access	Default	Field Name	Description
31:0		0x20796220	VendorName[3]	Vendor Name - transmitted in ISDU 0x10 - characters 15, 14, 13, 12

12.26.5 0xDD – VendorName[4]

Address : 0xDD		Register Name : VendorName[4]		Default: 0x656E6552
Bits	Access	Default	Field Name	Description
31:0		0x656E6552	VendorName[4]	Vendor Name - transmitted in ISDU 0x10 - characters 19, 18, 17, 16

12.26.6 0xDE – VendorName[5]

Address : 0xDE		Register Name : VendorName[5]		Default: 0x20736173
Bits	Access	Default	Field Name	Description
31:0		0x20736173	VendorName[5]	Vendor Name - transmitted in ISDU 0x10 - characters 23, 22, 21, 20

12.26.7 0xDF – VendorName[6]

Address : 0xDF		Register Name : VendorName[6]		Default: 0x74737563
Bits	Access	Default	Field Name	Description
31:0		0x74737563	VendorName[6]	Vendor Name - transmitted in ISDU 0x10 - characters 27, 26, 25, 24

12.26.8 0xE0 – VendorName[7]

Address : 0xE0		Register Name : VendorName[7]		Default: 0x72656D6F
Bits	Access	Default	Field Name	Description
31:0		0x72656D6F	VendorName[7]	Vendor Name - transmitted in ISDU 0x10 - characters 31, 30, 29, 28

12.26.9 0xE1 – VendorName[8]

Address : 0xE1		Register Name : VendorName[8]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorName[8]	Vendor Name - transmitted in ISDU 0x10 - characters 35, 34, 33, 32

12.26.10 0xE2 – VendorName[9]

Address : 0xE2		Register Name : VendorName[9]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorName[9]	Vendor Name - transmitted in ISDU 0x10 - characters 39, 38, 37, 36

12.26.11 0xE3 – VendorName[10]

Address : 0xE3		Register Name : VendorName[10]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorName[10]	Vendor Name - transmitted in ISDU 0x10 - characters 43, 42, 41, 40

12.26.12 0xE4 – VendorName[11]

Address : 0xE4		Register Name : VendorName[11]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	VendorName[11]	Vendor Name - transmitted in ISDU 0x10 - characters 47, 46, 45, 44

12.27 IO-Link – Hardware ID Key**12.27.1 0xE5 – HwldKey[0]**

Address : 0xE5		Register Name : HwldKey[0]		Default: 0x425F4F54
Bits	Access	Default	Field Name	Description
31:0		0x425F4F54	HwldKey[0]	Hardware ID Key - transmitted in ISDU 0x43BE - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:1 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.27.2 0xE6 – HwldKey[1]

Address : 0xE6		Register Name : HwldKey[1]		Default: 0x49465F45
Bits	Access	Default	Field Name	Description
31:0		0x49465F45	HwldKey[1]	Hardware ID Key - transmitted in ISDU 0x43BE - characters 7, 6, 5, 4

12.27.3 0xE7 – HwldKey[2]

Address : 0xE7		Register Name : HwldKey[2]		Default: 0x44454C4C
Bits	Access	Default	Field Name	Description
31:0		0x44454C4C	HwldKey[2]	Hardware ID Key - transmitted in ISDU 0x43BE - characters 11, 10, 9, 8

12.27.4 0xE8 – HwldKey[3]

Address : 0xE8		Register Name : HwldKey[3]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	HwldKey[3]	Hardware ID Key - transmitted in ISDU 0x43BE - characters 15, 14, 13, 12

12.28 IO-Link – Hardware Revision**12.28.1 0xE9 – HardwareRevision[0]**

Address : 0xE9		Register Name : HardwareRevision[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	HardwareRevision[0]	Hardware Revision - transmitted in ISDU 0x16 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

12.28.2 0xEA – HardwareRevision[1]

Address : 0xEA		Register Name : HardwareRevision[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	HardwareRevision[1]	Hardware Revision - transmitted in ISDU 0x16 - characters 7, 6, 5, 4

12.28.3 0xEB – HardwareRevision[2]

Address : 0xEB		Register Name : HardwareRevision[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	HardwareRevision[2]	Hardware Revision - transmitted in ISDU 0x16 - characters 11, 10, 9, 8

12.28.4 0xEC – HardwareRevision[3]

Address : 0xEC		Register Name : HardwareRevision[3]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	HardwareRevision[3]	Hardware Revision - transmitted in ISDU 0x16 - characters 15, 14, 13, 12

12.29 IO-Link – Product Name**12.29.1 0xED – ProductName**

Address : 0xED		Register Name : ProductName[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	ProductName[0]	Product Name - transmitted in ISDU 0x12 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 : character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

Address : 0xEE		Register Name : ProductName[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	ProductName[1]	Product Name - transmitted in ISDU 0x12 - characters 7, 6, 5, 4

Address : 0xEF		Register Name : ProductName[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	ProductName[2]	Product Name - transmitted in ISDU 0x12 - characters 11, 10, 9, 8

Address : 0xF0		Register Name : ProductName[3]		Default: 0x20796220
Bits	Access	Default	Field Name	Description
31:0		0x20796220	ProductName[3]	Product Name - transmitted in ISDU 0x12 - characters 15, 14, 13, 12

Address : 0xF1		Register Name : ProductName[4]		Default: 0x656E6552
Bits	Access	Default	Field Name	Description
31:0		0x656E6552	ProductName[4]	Product Name - transmitted in ISDU 0x12 - characters 19, 18, 17, 16

Address : 0xF2		Register Name : ProductName[5]		Default: 0x20736173
Bits	Access	Default	Field Name	Description
31:0		0x20736173	ProductName[5]	Product Name - transmitted in ISDU 0x12 - characters 23, 22, 21, 20

Address : 0xF3		Register Name : ProductName[6]		Default: 0x74737563
Bits	Access	Default	Field Name	Description
31:0		0x74737563	ProductName[6]	Product Name - transmitted in ISDU 0x12 - characters 27, 26, 25, 24

Address : 0xF4		Register Name : ProductName[7]		Default: 0x72656D6F
Bits	Access	Default	Field Name	Description
31:0		0x72656D6F	ProductName[7]	Product Name - transmitted in ISDU 0x12 - characters 31, 30, 29, 28

12.30 IO-Link – Product ID

12.30.1 0xF5 – ProductId

Address : 0xF5		Register Name : ProductId[0]		Default: 0x62206F54
Bits	Access	Default	Field Name	Description
31:0		0x62206F54	ProductId[0]	Product ID - transmitted in ISDU 0x13 - characters 3, 2, 1, 0 Bits 31:24 : character 3 Bits 23:16 character 2 Bits 15:8 : character 1 Bits 7:0 : character 0

Address : 0xF6		Register Name : ProductId[1]		Default: 0x69662065
Bits	Access	Default	Field Name	Description
31:0		0x69662065	ProductId[1]	Product ID - transmitted in ISDU 0x13 - characters 7, 6, 5, 4

Address : 0xF7		Register Name : ProductId[2]		Default: 0x64656C6C
Bits	Access	Default	Field Name	Description
31:0		0x64656C6C	ProductId[2]	Product ID - transmitted in ISDU 0x13 - characters 11, 10, 9, 8

Address : 0xF8		Register Name : ProductId[3]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductId[3]	Product ID - transmitted in ISDU 0x13 - characters 15, 14, 13, 12

Address : 0xF9		Register Name : ProductId[4]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductId[4]	Product ID - transmitted in ISDU 0x13 - characters 19, 18, 17, 16

Address : 0xFA		Register Name : ProductId[5]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductId[5]	Product ID - transmitted in ISDU 0x13 - characters 23, 22, 21, 20

Address : 0xFB		Register Name : ProductId[6]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductId[6]	Product ID - transmitted in ISDU 0x13 - characters 27, 26, 25, 24

Address : 0xFC		Register Name : ProductId[7]		Default: 0x00000000
Bits	Access	Default	Field Name	Description
31:0		0x0	ProductId[7]	Product ID - transmitted in ISDU 0x13 - characters 31, 30, 29, 28

12.31 CCP Password, Version and CRC

12.31.1 0xFD – CcpPassword

If CCP Password is different from 0xFFFFFFFF, CCP Password protection becomes effective.

Address : 0xFD		Register Name : CcpPassword		Default: 0xFFFFFFFF
Bits	Access	Default	Field Name	Description
31:0		0xFFFFFFFF	CcpPassword	CCP Password to protect CCP read/write actions via IO-Link - transmitted in ISDU 0x201

12.31.2 0xFE – CcpVersion

Address : 0xFE		Register Name : CcpVersion		Default: 0x86020001
Bits	Access	Default	Field Name	Description
31:24		0x86	Pid	Product specific CCP ID
23:16		0x2	PatchVer	Patch Version of CCP
15:8		0x0	MinorVer	Minor Version of CCP
7:0		0x1	MajorVer	Major Version of CCP

12.31.3 0xFF – CrcCcp1

Wrong setting of this parameter hinders firmware execution. Leave the computation of necessary setup for this register to the GUI.

Address : 0xFF		Register Name : CrcCcp1		Default: 0xD7418B6B
Bits	Access	Default	Field Name	Description
31:0		0xD7418B6B	CrcCcp1	CRC of CCP Page 1

13 Application Information

13.1 2-Bridge Application 1.8V to 5.5V Supply

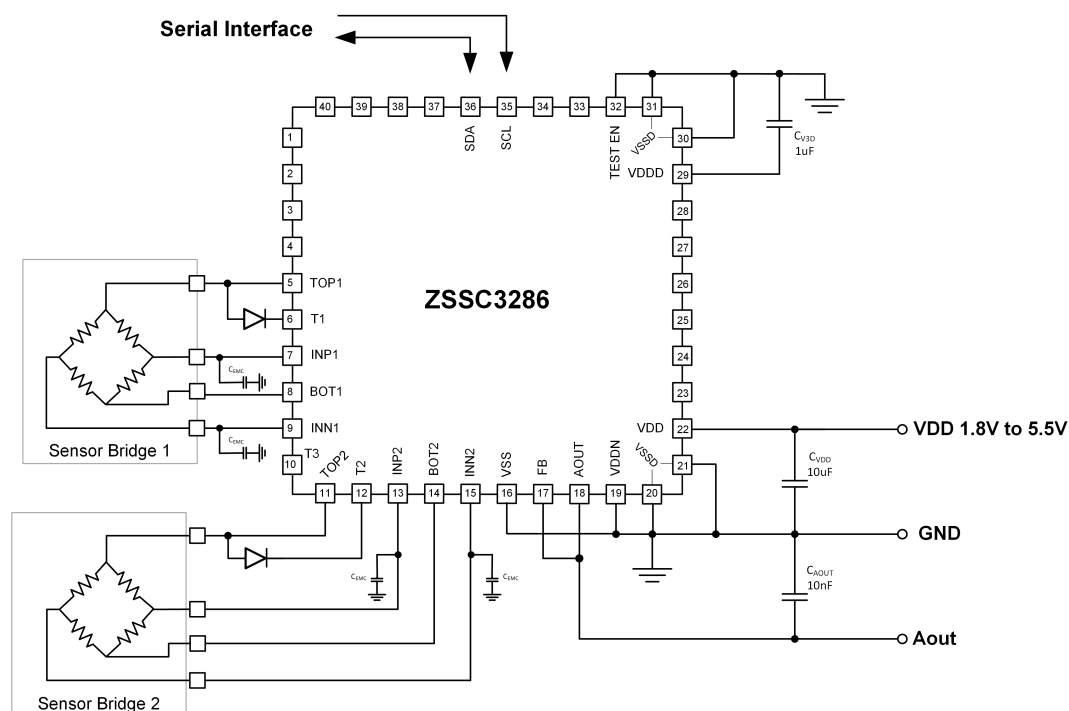


Figure 45: 2-Bridge Application 1.8V to 5.5V Supply

13.2 Single Bridge Application with IO-Link

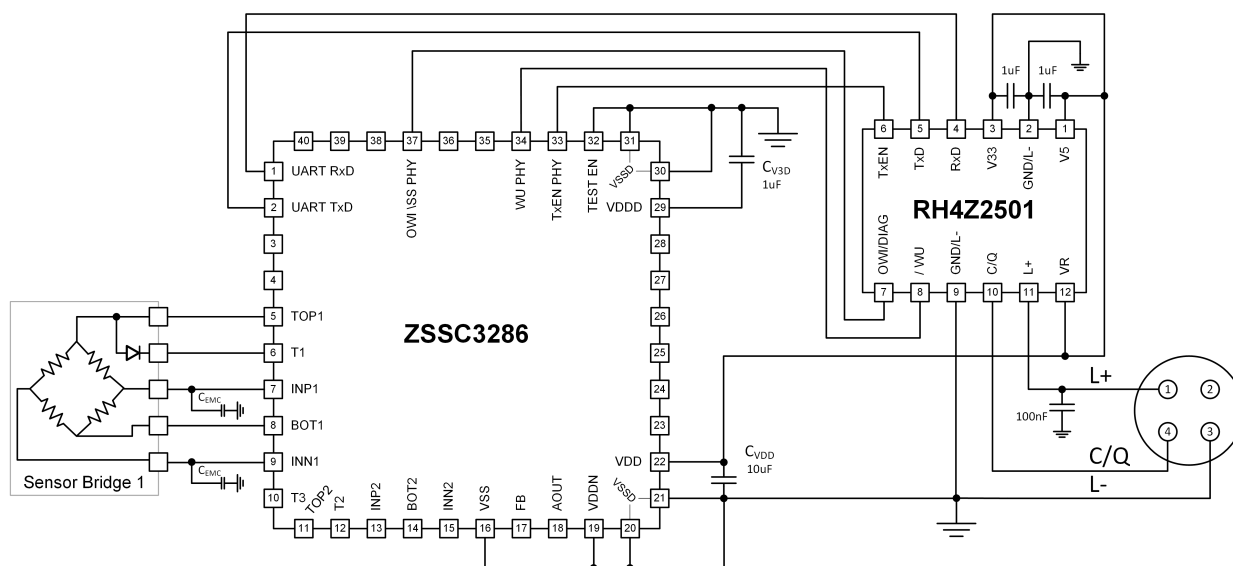


Figure 46: Single Bridge Application with IO-Link

13.3 Single Bridge Application with IO-Link and Current Loop Output

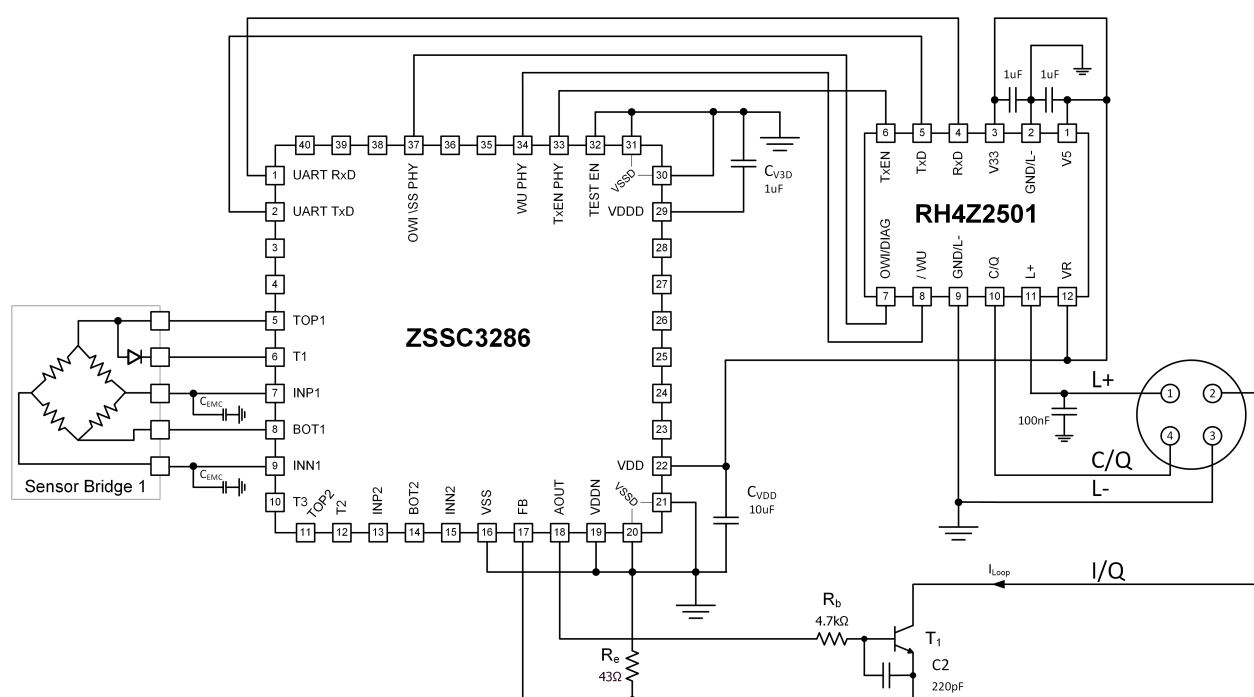


Figure 47: Single Bridge Application with IO-Link and Current Loop Output

14 Package Information

14.1 Package Outline Drawings

The package outline drawings are accessible from the link below. The package information is the most current data available.

QFN40: [Package Outline Drawing Code: NDG40S1 40-VFQFPN 5.0 x 5.0 x 0.9 mm Body, 0.4 mm Pitch \(renesas.com\)](#)

WLCSP: [Package Outline Drawing Code: AWG48D1 48-DSBGA 3.61 x 3.24 x 0.6 mm Body, 0.4 mm Pitch \(renesas.com\)](#)

Bare Die: on request

14.2 QFN40 Marking Diagram

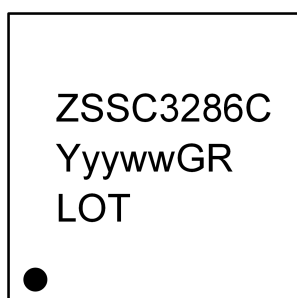


Figure 48: QFN40 Marking Diagram

1. "ZSSC3286" C is the truncated part number.
2. "YyywwGR" where "Y" and "GR" are fixed and "yyww" represents the last digits of the year and week that the part was assembled.
3. "LOT" is the complete lot number of the part.

14.3 WLCSP Marking Diagram

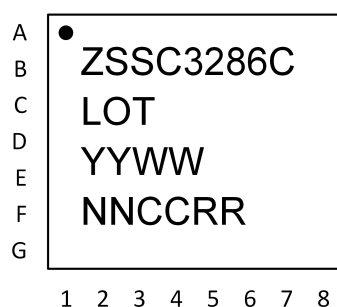


Figure 49: WLCSP Marking Diagram

1. "ZSSC3286C" is the truncated part number.
2. "LOT" is the complete lot number of the part.
3. "YYWW" represents the last digits of the year and week that the part was assembled.
4. "NNCCRR" contains the wafer position information:
 - "NN": Scribe Number
 - "CC": Column of die location
 - "RR": Row of die location

15 Glossary, References and History

15.1 Glossary

Term	Description
ADC	Analog to Digital Converter
AFE	Analog Front End
ARM	Provider of microcontroller core
AUX	Auxiliary measurement, in addition to main sensor bridge measurement
AZ	Auto-zero
BINO	Binary Output Signal
BLOB	Binary Large Object
BOT	Bottom
CCP	Configuration and Calibration Page
DAC	Digital to Analog Converter
EMI	Electromagnetic Interference
ESD	Electrostatic Discharge
FB	Feedback input for analog output buffer
FS	Full Scale
FW	Firmware
GPIO	General Purpose Input Output
GUI	Graphical User Interface
HF	High Frequency
HW	Hardware
I2C	Inter Integrated Circuit communication protocol
ID	Identification
IIR	Infinite Impulse Response
ISDU	Indexed Service Data Unit
LDR	Lower Diagnostic Range
LF	Low Frequency
LSB	Least Significant Bit
MISO	Master-In Slave-Out
MOSI	Master-Out Slave-In
MSB	Most Significant Bit
NC	Not Connected
OWI	One Wire Interface
PGA	Programmable Gain Amplifier
PHY	Physical Layer
POR	Power-On-Reset
PTAT	Proportional to absolute temperature current source
R	Read
RAM	Random Access Memory
RCA	Renesas Code Area
RDAC	Resistive Digital to Analog Converter
RTD	Temperature dependent resistor
RW	Read/Write
SM-	Main Sensor Measurement, inverted signal polarity
SM+	Main Sensor Measurement, standard (non-inverted) signal polarity
SOT	Second Order Term
SPI	Serial Peripheral Interface
SS	Slave Select

Continued on next page

Term	Description
SSC	Sensor Signal Conditioner
SSP	Smart Sensor Profile
TFW	Fechnology Firmware
TLC	Third Logic Channel
UART	Universal Asynchronous Receiver / Transmitter
UDR	Upper Diagnostic Range
W	Write
WURQ	Wake-Up Request

15.2 References

Reference Number	Title
1	IO-Link Interface and System. Specification. Version 1.1.4. June 2024
2	IO-Link Common Profile. Specification. Version 1.2. January 2024
3	RH4Z2501 https://www.renesas.com/RH4Z2501

15.3 Firmware Revision History

Revision	Date	Description
1.0.0	July 31, 2024	Initial release
1.2.0	April 24, 2025	Initial release for revision C

15.4 Document Revision History

Revision	Date	Description
1.0	September 18, 2024	Initial release
2.0	July 10, 2025	Initial release for revision C

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